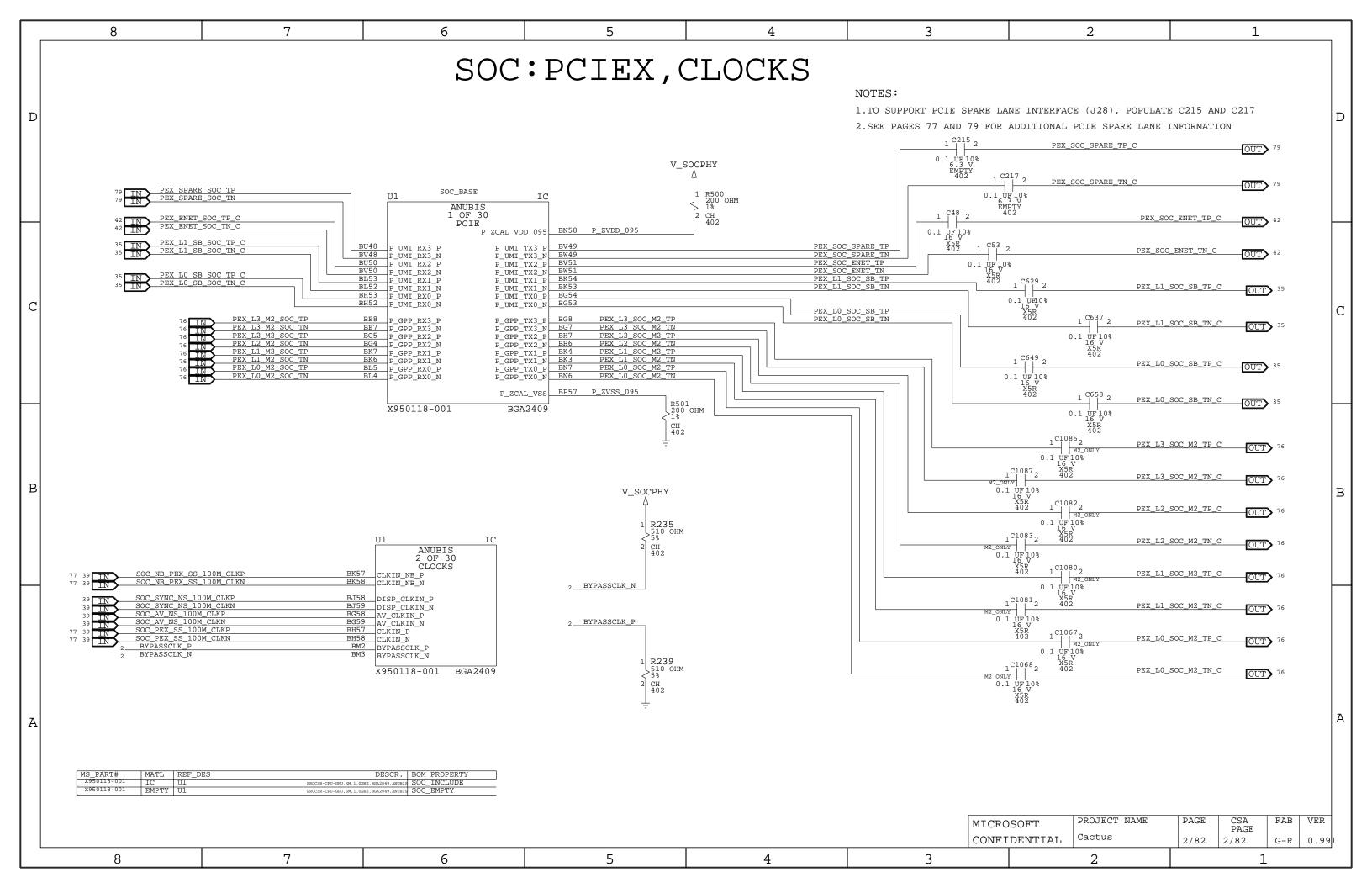
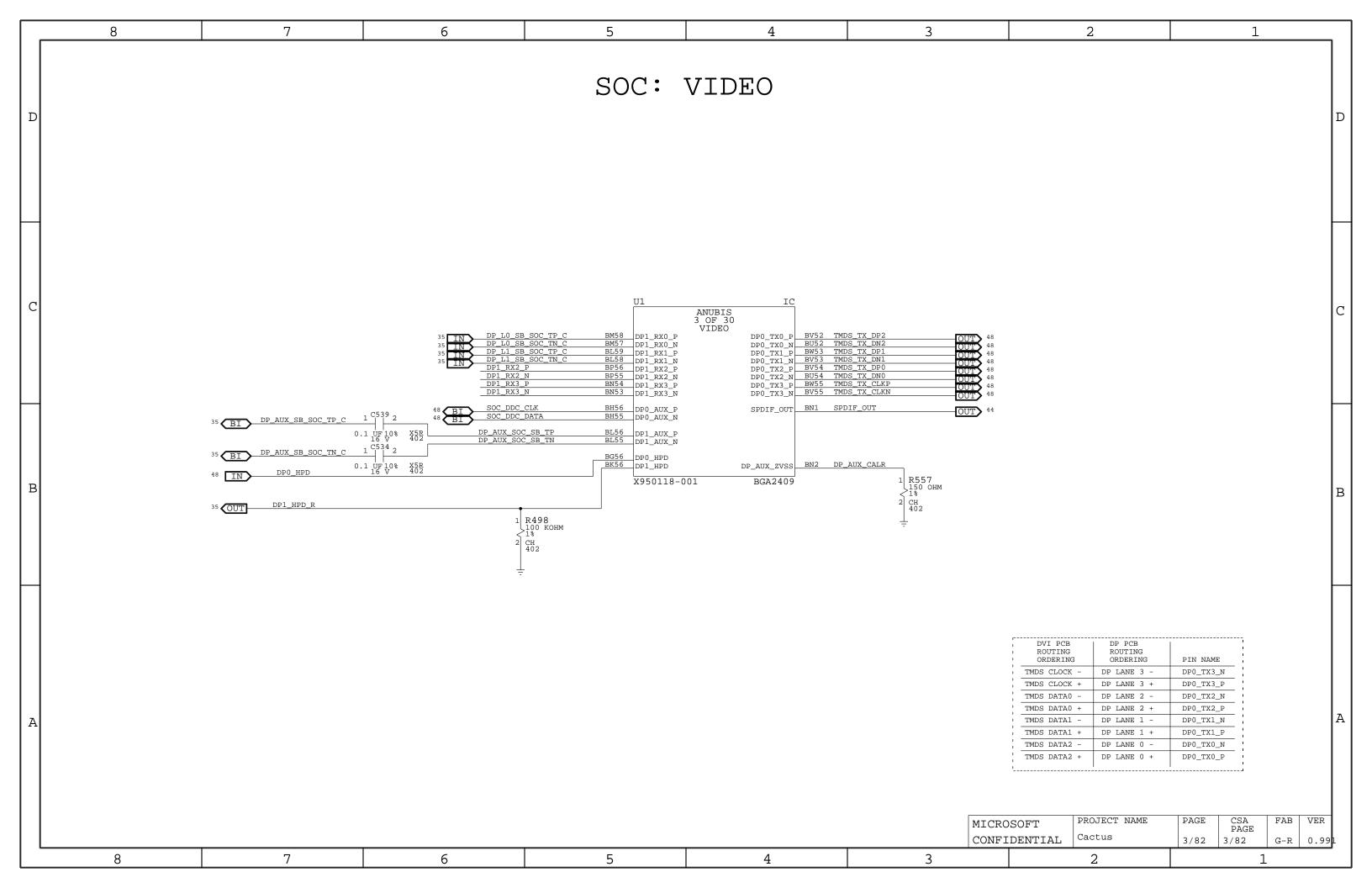
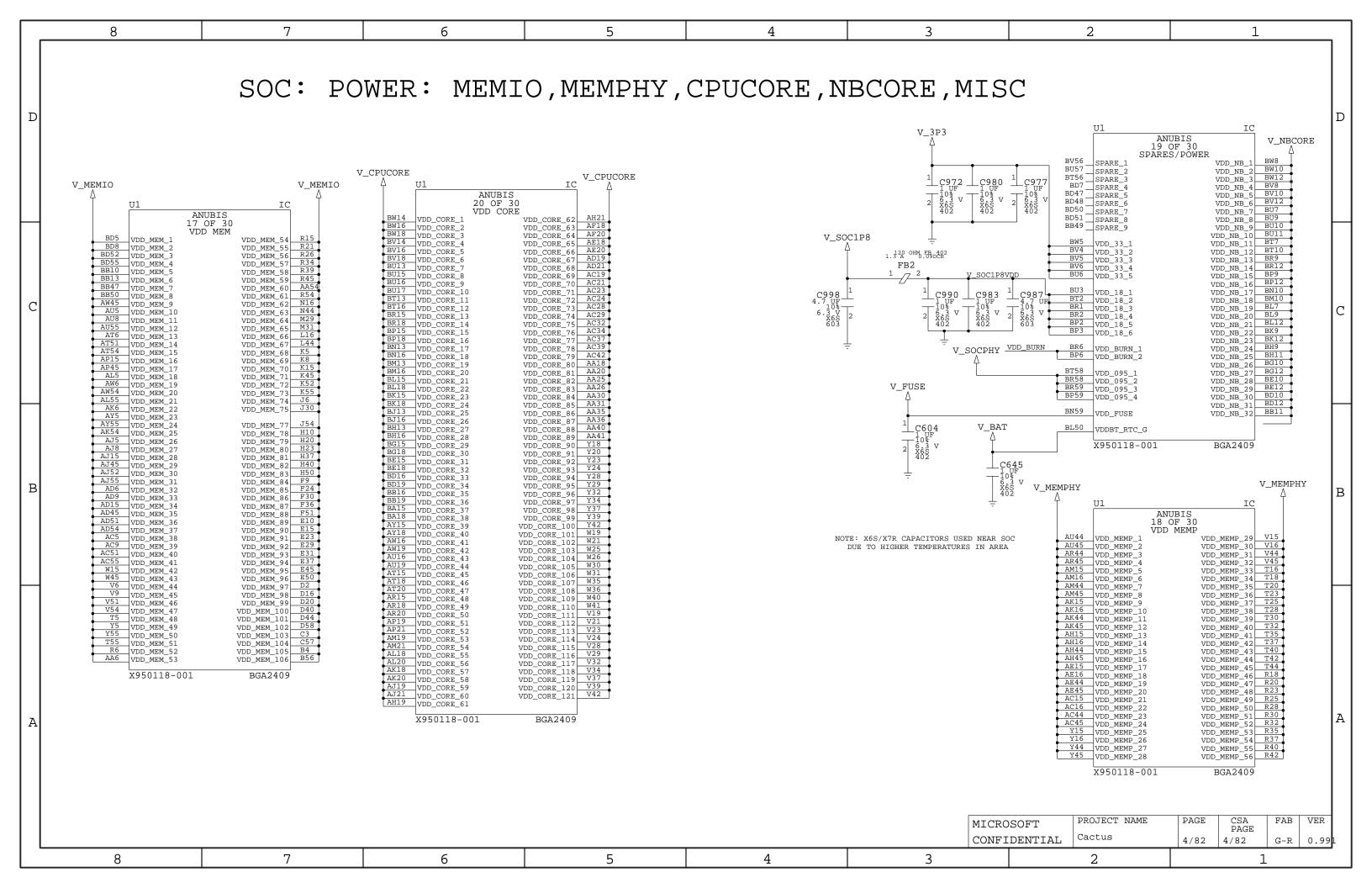
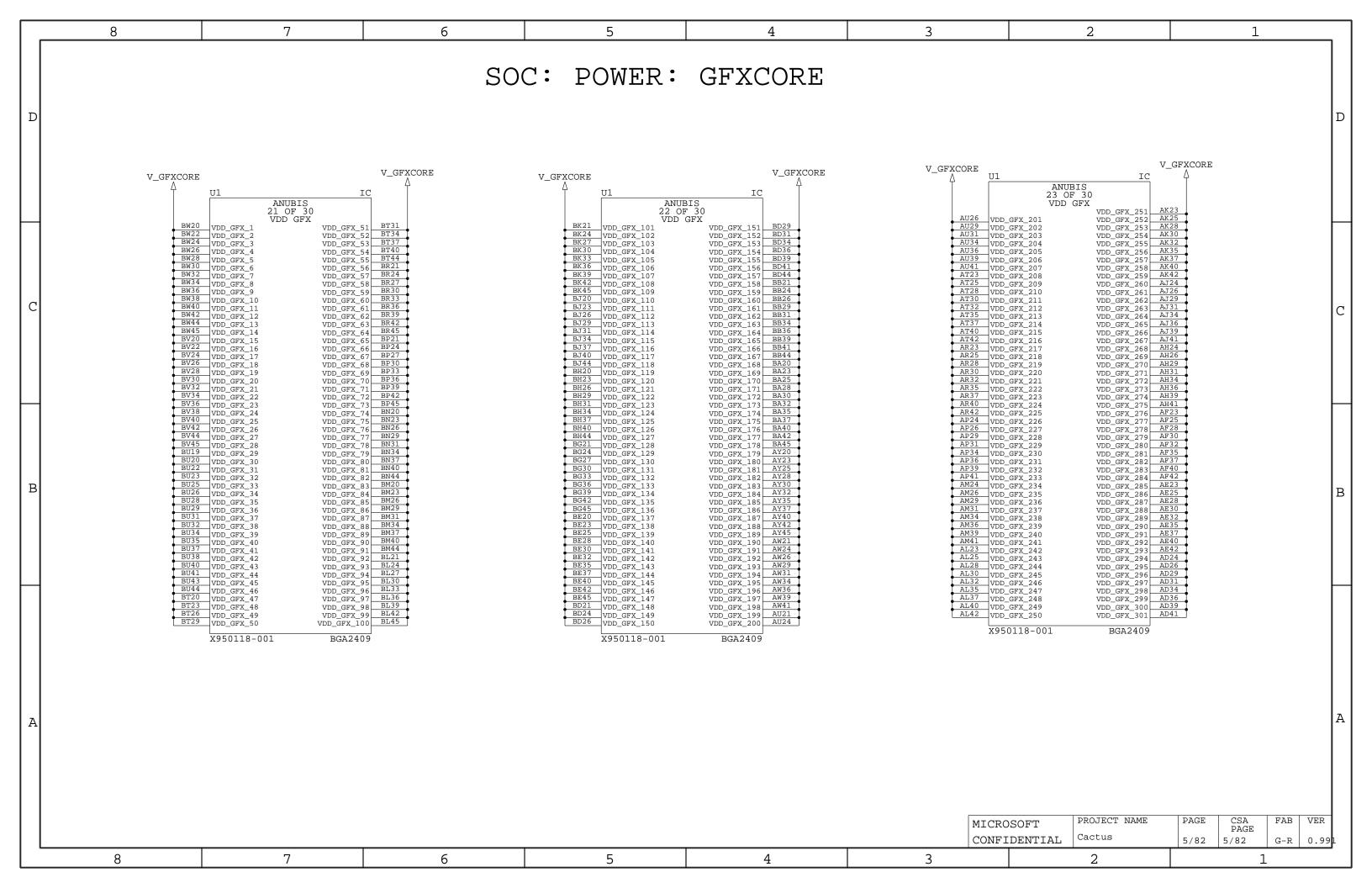
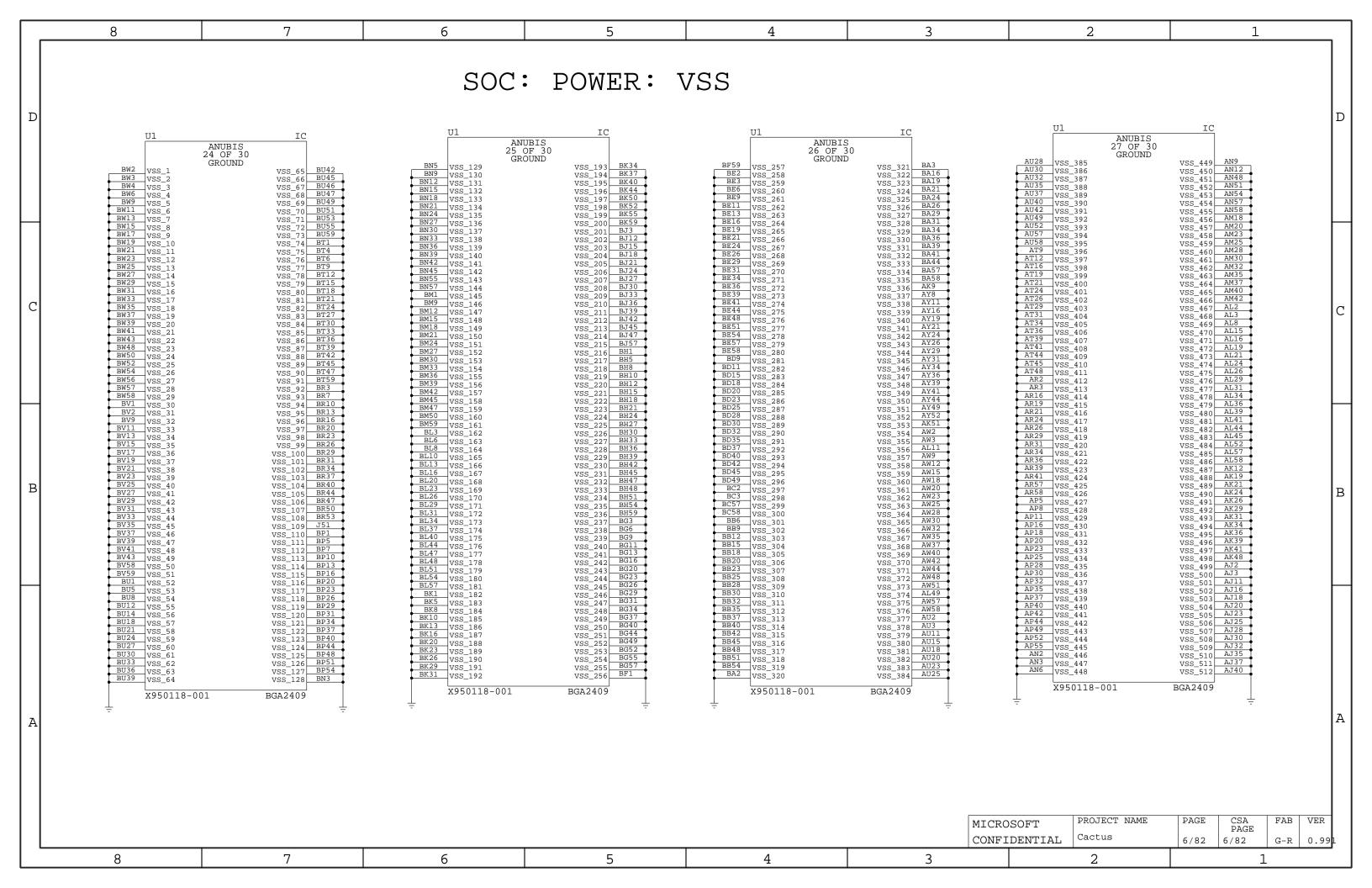
	8	7	6	5		4	3		2	1		
	PAGE CO	ONTENTS										
	[1] COVER PAGE			[48]	COMM	UDMT OUT			$C \lambda C T$	ידדכי		
	[2] SOC: PCIEX, CLOCKS			[49]					= CACTUS			
		: VIDEO		[50]		ODD & HDD				0 00	_	
		: POWER: MEMIO, CPUCORE, NE	SCORE MISC	[51]		FRONT PANEL, FAN,	ΔΙΙΠΤΟ		REV	0.99		
	[5] SOC: POWER: V_GFXCORE			[52]	CONN:		110010					
		: POWER: VSS		[53]		INPUT FILTERS			FAB G	RETAI	rt. I	
		: POWER: VSS		[54]		CPUCORE & GFXCOR	 RE			1411 1211		
	[8] SOC:	: MEMORY PARTITION F1 & F	70	[55]	VREGS:	GFXCORE OUTPUT F	PHASE 1 & 2					
	[9] SOC: MEMORY PARTITION E1 & E0			[56]	VREGS:	GFXCORE OUTPUT F	PHASE 3 & 4					
H	[10] SOC:	MEMORY PARTITION D1 & D	00	[57]	VREGS:	CPUCORE OUTPUT F	PHASE				-	
	[11] SOC: MEMORY PARTITION C1 & C0			[58]	VREGS:	MEMIO & MEMPHY						
	[12] SOC: MEMORY PARTITION B1 & B0			[59]	VREGS:	MEMPHY OUTPUT						
	[13] SOC:	MEMORY PARTITION A1 & A	70	[60]	VREGS:	MEMIO OUTPUT						
		DEBUG, SB SIGNALS, V_BA	T	[61]		NBCORE						
C	[15] SOC: DECOUPLING			[62]	VREGS: V5P0							
		DECOUPLING		[63]		V3P3, VSOC1P8						
		DECOUPLING		[64]		VSOCPHY/VFUSE						
		[18] MEMORY: CHANNEL AO		[65]	VREGS: V_SB1P8, V_SB1P1							
		DRY: CHANNEL A1		[66]		V3P3 STANDBY	DO CELLIDAL					
		DRY: CHANNEL BO		[67]		V1P1 STANDBY, V1	P8 STANDBY					
П		DRY: CHANNEL B1	r M C	[68]		Y GATES						
	[22] MEMORY: CHANNEL A/B DECOUPLING [23] MEMORY: CHANNEL CO [24] MEMORY: CHANNEL C1 [25] MEMORY: CHANNEL DO [26] MEMORY: CHANNEL D1 [27] MEMORY: CHANNEL C/D DECOUPLING		<u>[69]</u> [70]	IR BLA	1EK							
			[71]		I2C MARGIN: SOCPHY, SOC1P8, MEMIO, NBCORE MONITOR: VSOC1P8, VSOCPHY, V12P0 CONN: FACET BOARD							
			[72]									
_			[73]									
B			$\frac{[74]}{[74]}$	CONN: SWITCHES								
		ORY: CHANNEL E0			CONN:							
		ORY: CHANNEL E1		[76]	CONN:							
	[30] MEMORY: CHANNEL FO		$-\frac{[77]}{[77]}$		CLOCK BUFFER							
		DRY: CHANNEL F1		[78]		M SPEAKER (SE/LE)						
Ш		DRY: CHANNEL E/F DECOUPLI	ING	[79]		VR HEADERS, TEST		TORS				
	[33] MEMO	ORY: ADDITIONAL DECOUPLIN	1G	[80]	LABELS	AND MOUNTING						
	[34] KIC:	USB		[81]	FRONT	PANEL USB - NESTE	D PCB					
	[35] KIC:	PCIEX, SATA, VIDEO		[82]	BOM DE	FINITIONS						
	[36] KIC:	SMC										
	[37] KIC:	FACET										
	[38] KIC:	POWER										
		CLOCKS, STRAPPING, POR										
7		POWER		RULES: 1. MSB'	(APPLIED TO LSB IS	WHEN POSSIBLE) TOP TO BOTTOM						
^	[41] KIC: DECOUPLING [42] ETHERNET CONTROLLER		2. WHEN 3. ORDE	(APPLIED WHEN POSSIBLE) TO LSB IS TOP TO BOTTOM POSSIBLE: INPUTS ON LEFT, OUTPUTS ON RIGHT R OF PAGES=CHIP INTERFACES, TERMINATION, POWER, DECOUPLING D USING OFF PAGE CONNECTORS FOR ON PAGE CONNECTIONS D SIGNALS ARE GROUPED ON SYMBOLS SIMITTER NAME USED AS PREFIX WITH RX AND TX CONNECTIONS IX V IS USED FOR VOLTAGE RAIL SIGNAL NAMES IX DP AND DN ARE USED FOR DIFFERIENTAL PAIRS AMED NETS ARE NAMED WITH /2 TEXT SIZE IX N FOR ACTIVE LOW OR N JUNCTION IX P FOR P JUNCTION IX P FOR ENABLE ' FOR CLOCKS, 'RST' FOR RESETS D FOR POWER GOOD AND FAB ARE SET USING CUSTOM VARIABLES S>OPTIONS>VARIABLES CONFIDENTS		DECOUPLING						
			4. AVOI 5. LANE			ONS						
	[43] EMMC MEMORY [44] CONN: RJ45,TOSLINK [45] CONN: USB (FRONT & REAR)			6. TRAN	SIMITTER NAME ÚSÉD AS PREFIX WITH RX AND TX CONNECTIONS IX V IS USED FOR VOLTAGE RAIL SIGNAL NAMES IX DP AND DN ARE USED FOR DIFFERIENTAL PAIRS AMED NETS ARE NAMED WITH /2 TEXT SIZE			CTTONS				
				8. SUFF							_DRAWING_	
				10.SUFF 12.SUFF	IX _N FOR IX _P FOR	ACTIVE LOW OR N JUNC P JUNCTION	LI TOIN		Th	nu Apr 20 16:1		
		N: WIFI N: HDMI IN		13.SUFF. 14.'CLK	TA EN FOR FOR CLO	K ENABLE CKS, 'RST' FOR RESETS		MICROSOFT	PROJECT NAME	PAGE CSA	FAB VER	
	[1] COINI	N - TITN:IT TIN		16.REV TOOT	AND FAB A	ARE SET USING CUSTOM	VARIABLES	CONFIDENTIAL	~ .	PAGE 1/82 1/82	G-R 0.991	
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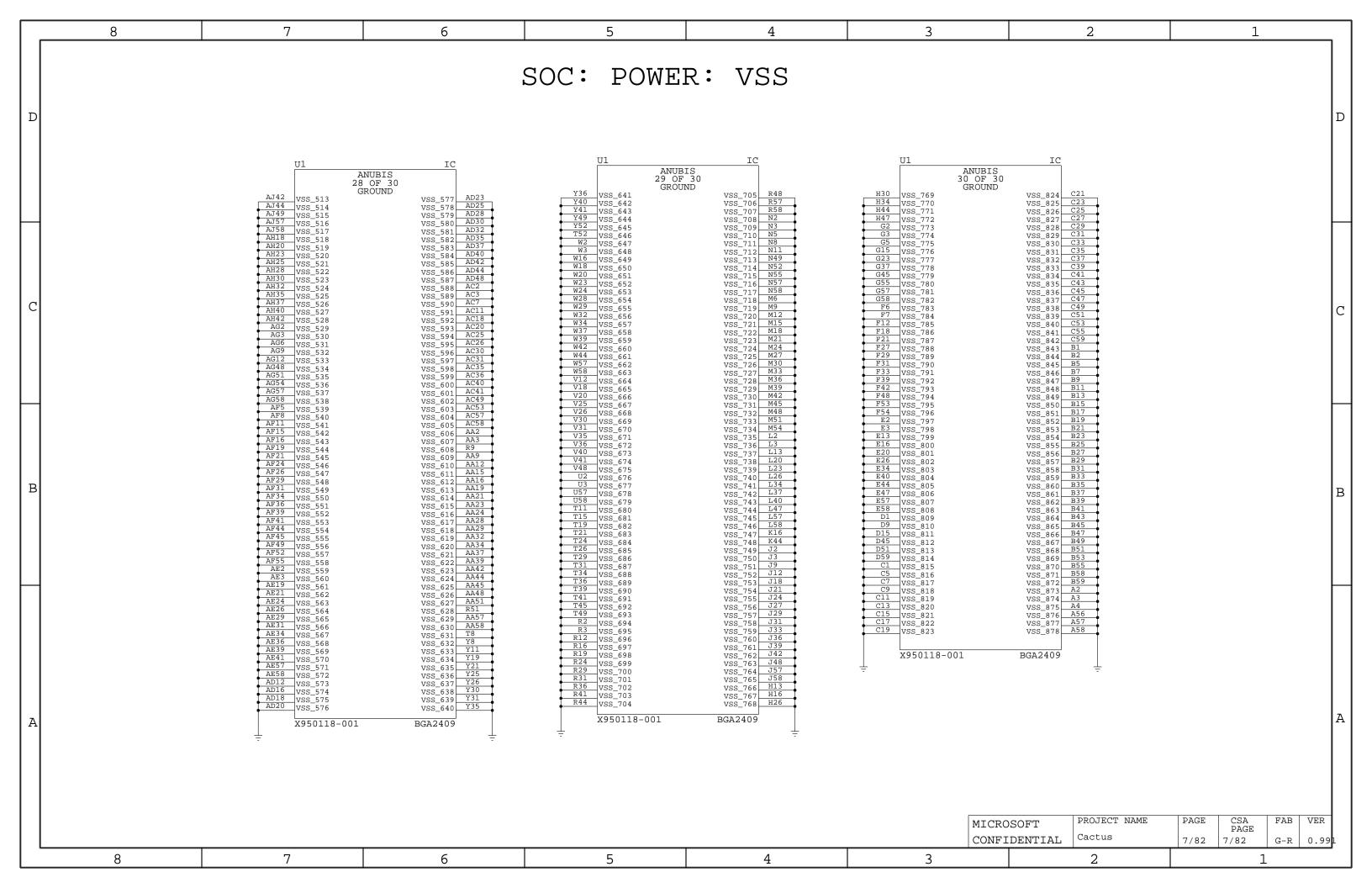


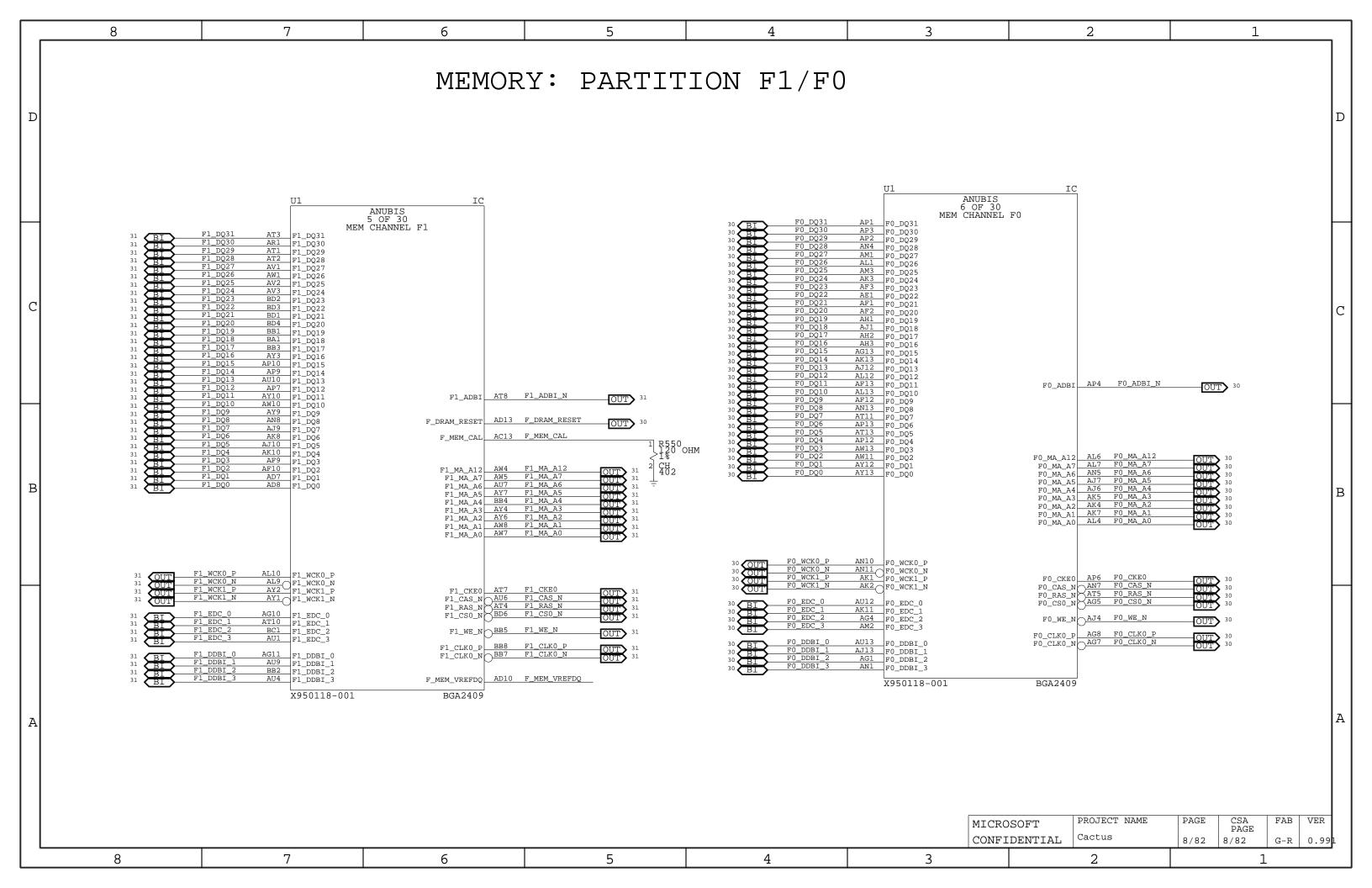


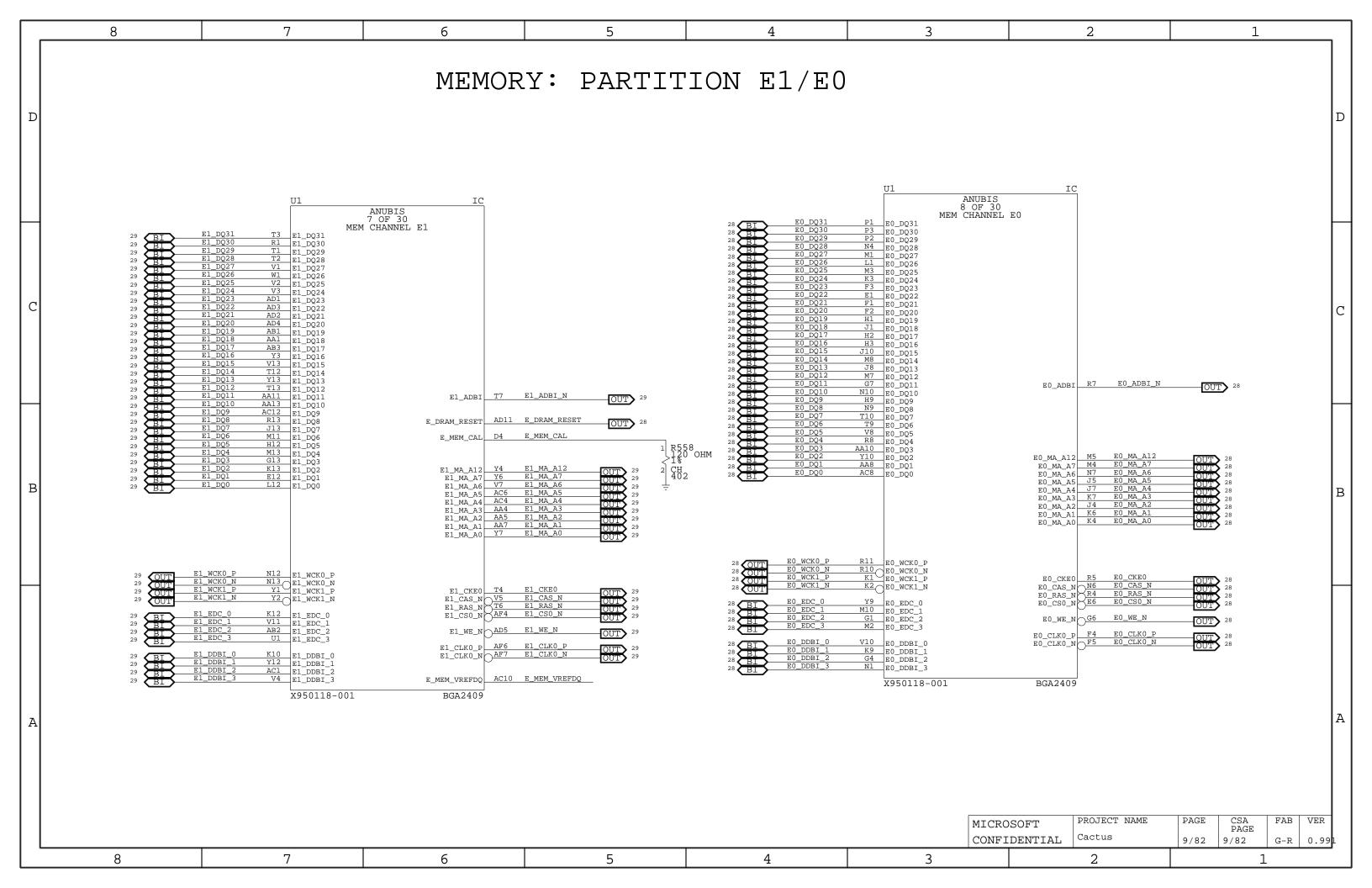


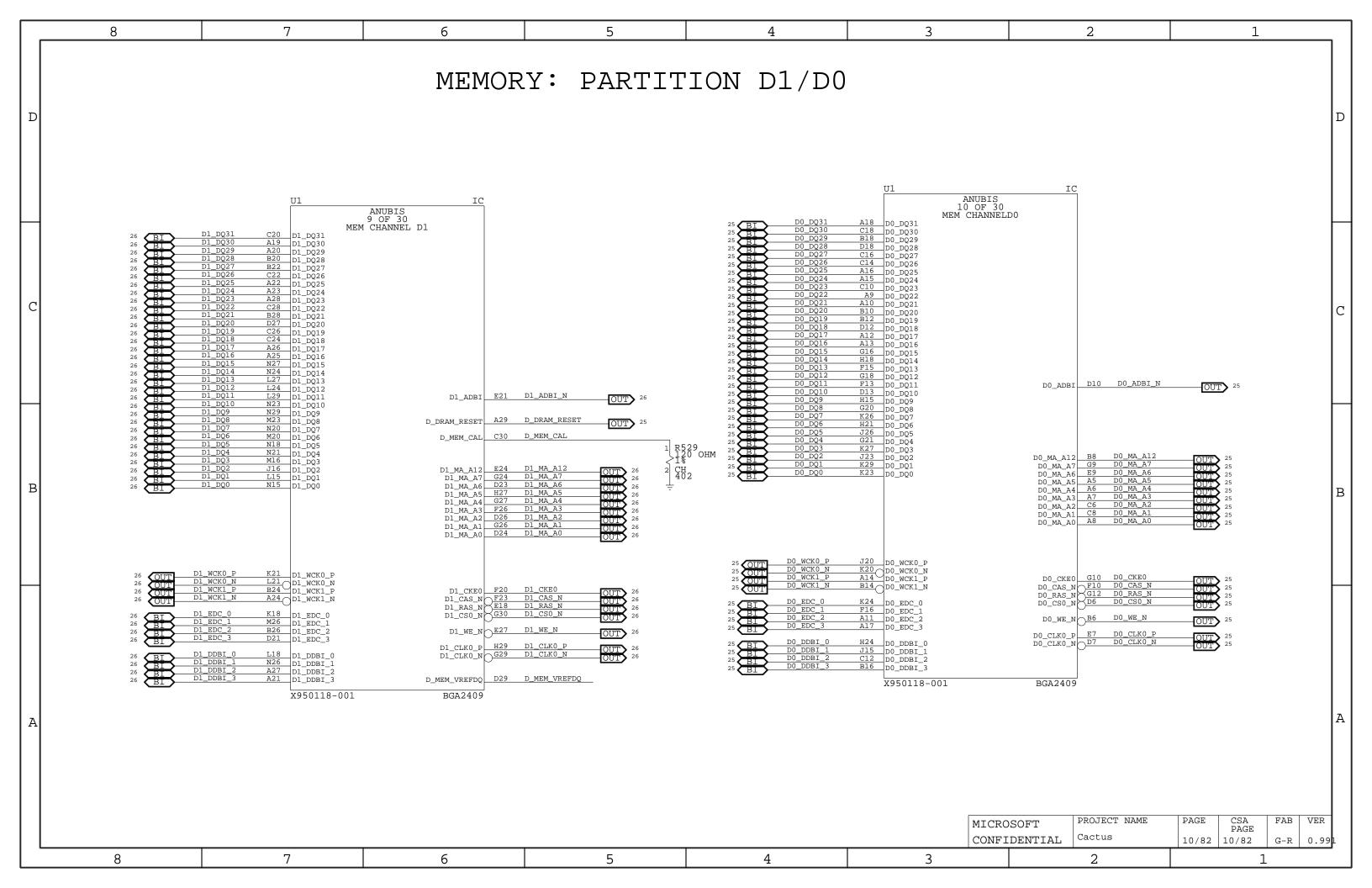


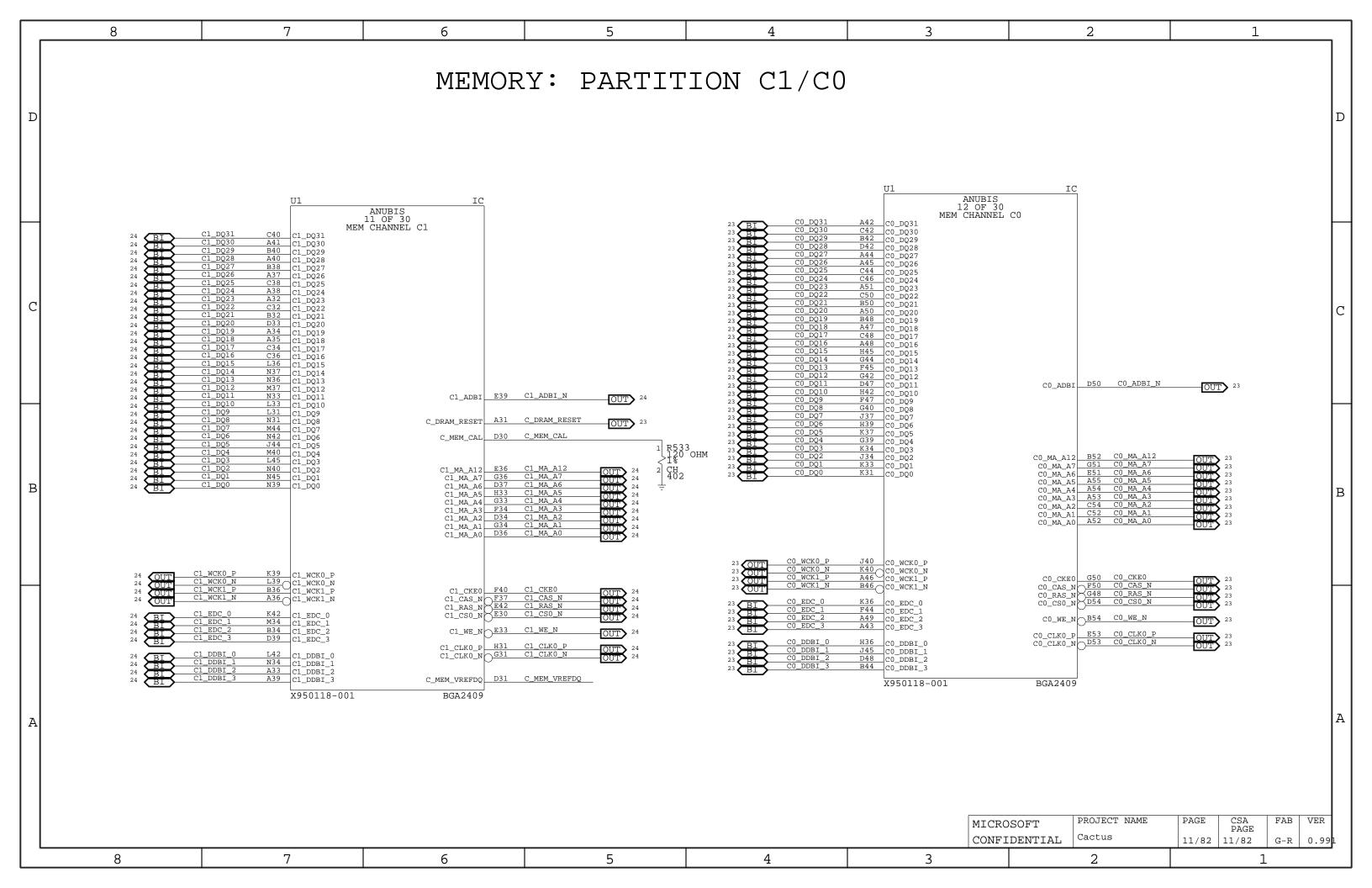


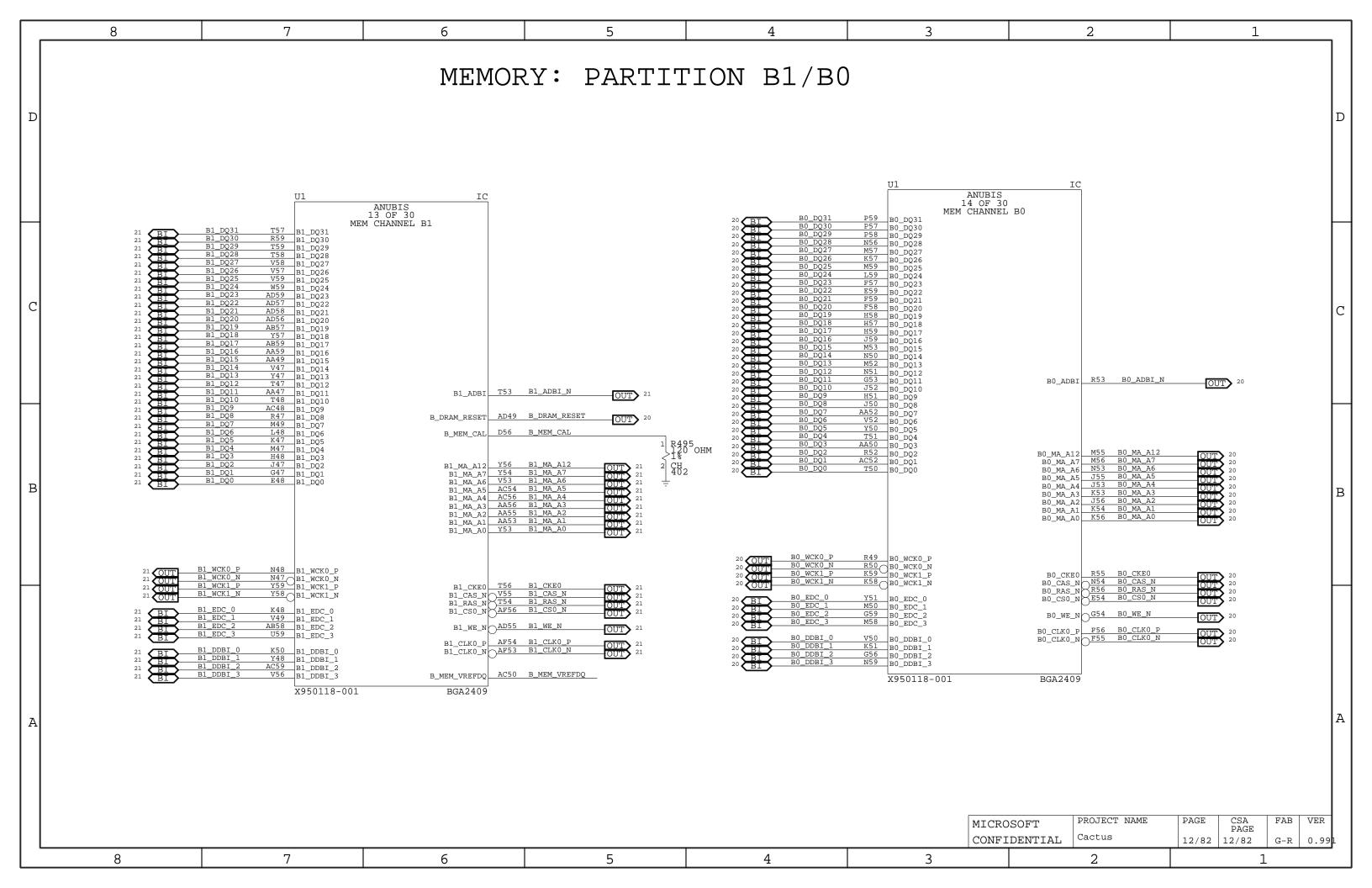


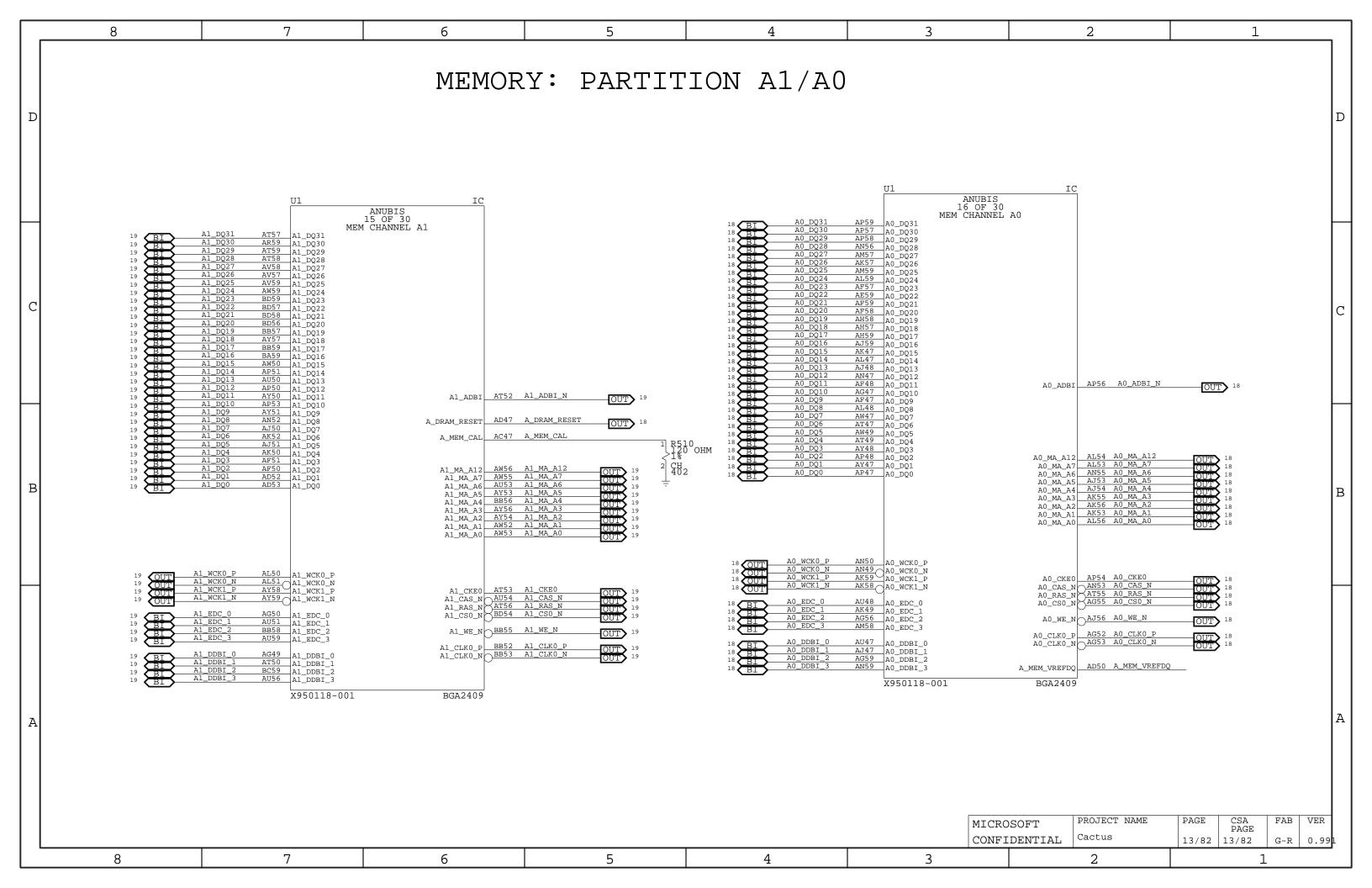


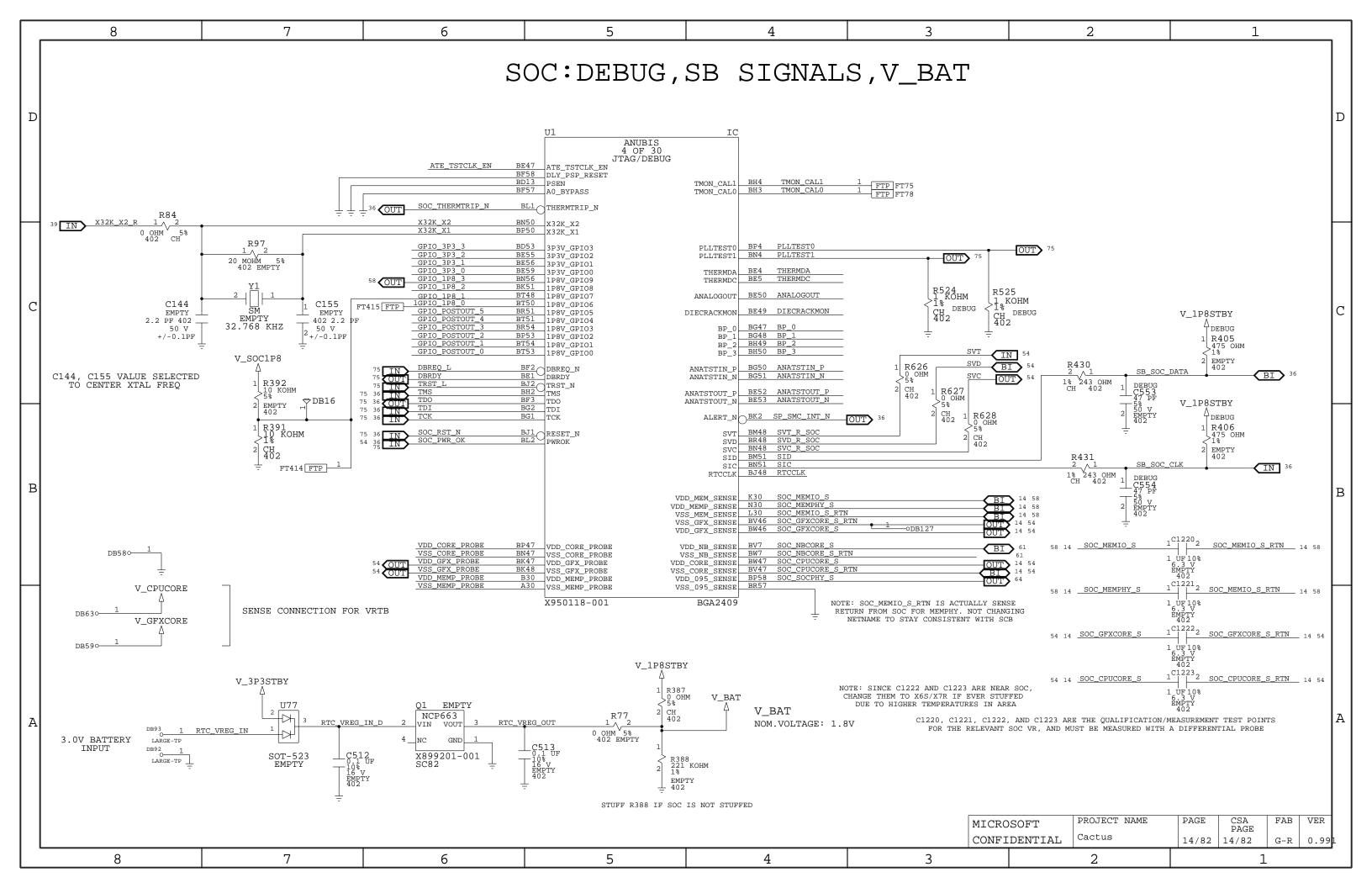


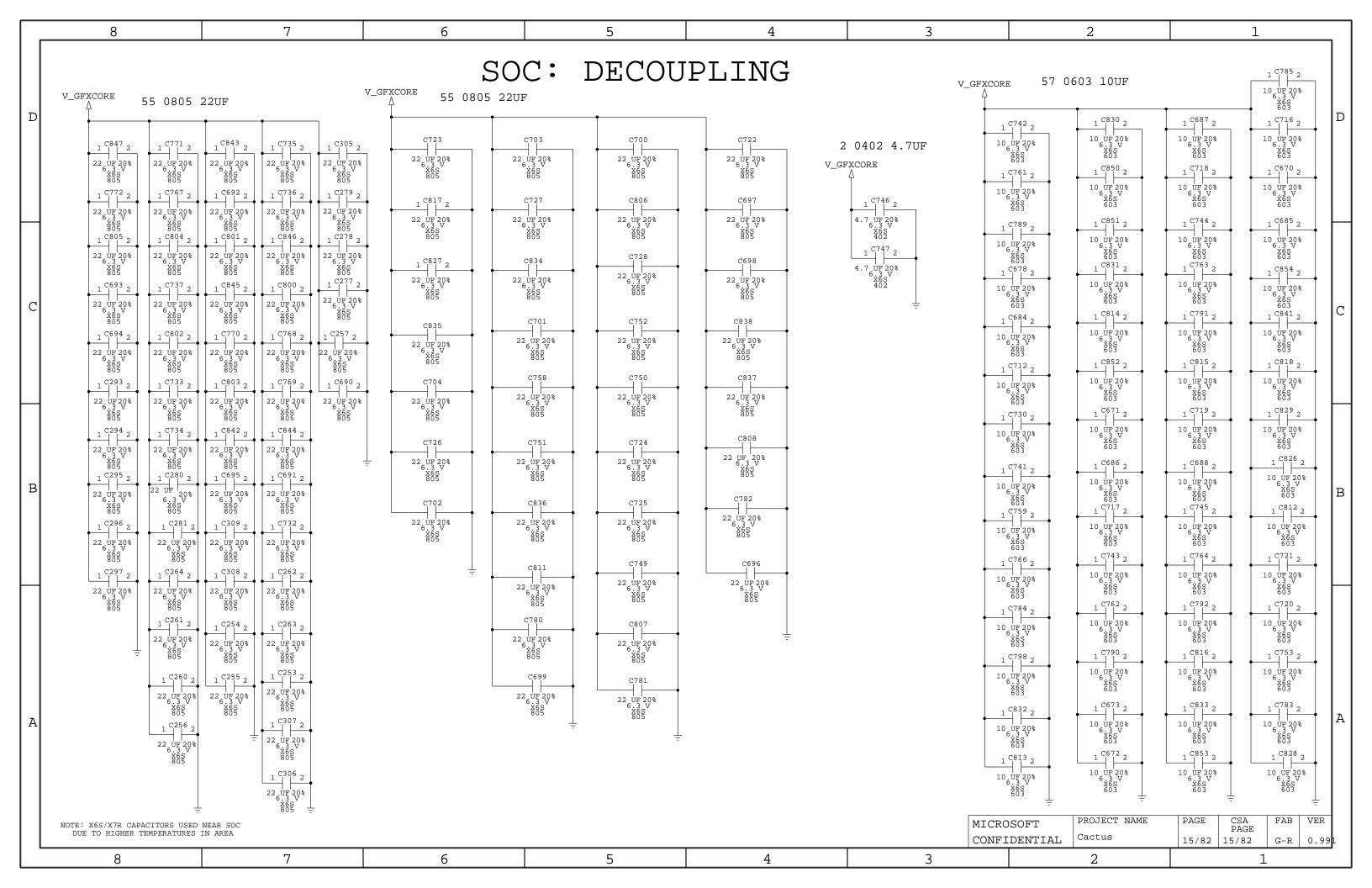


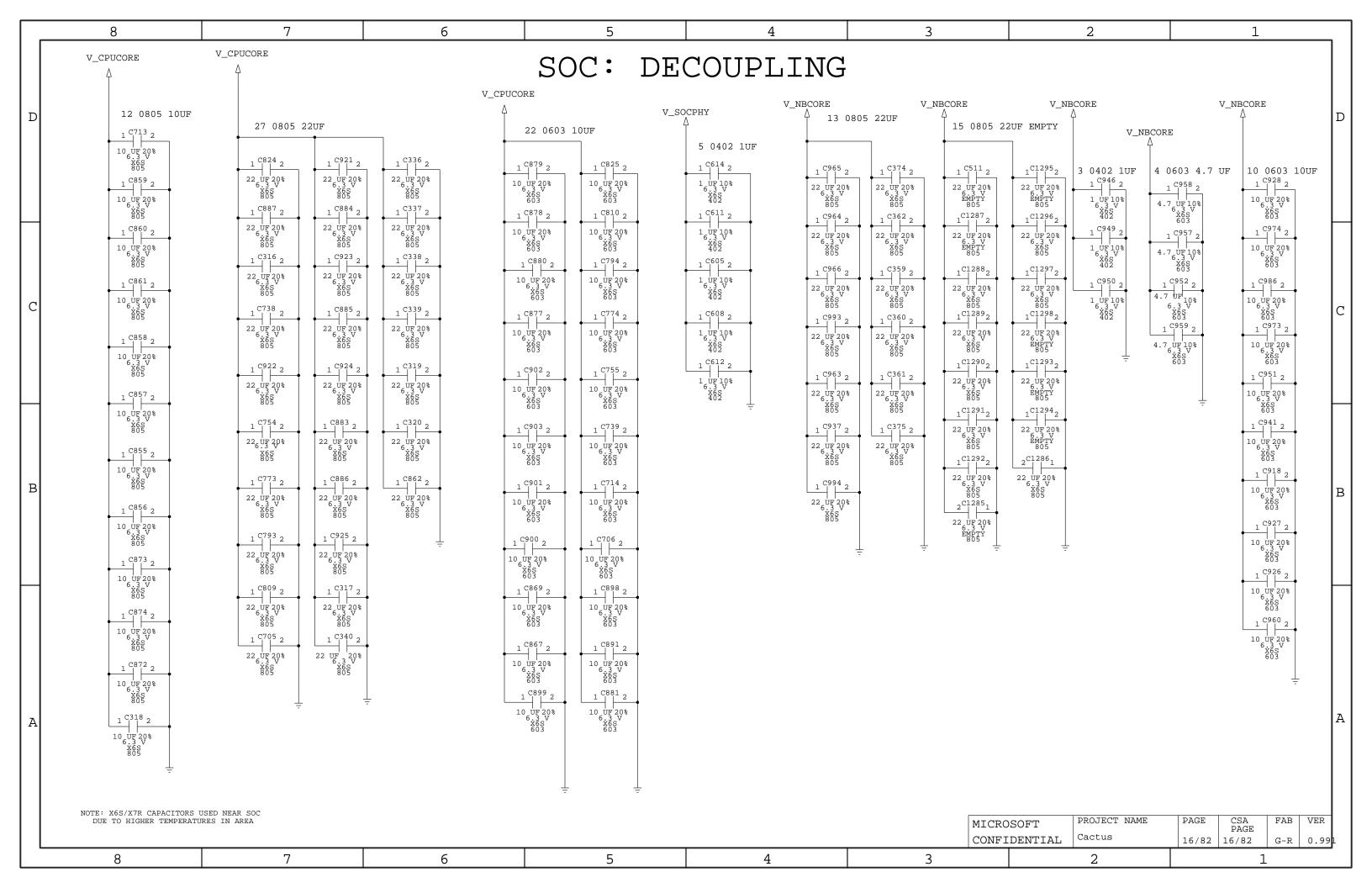


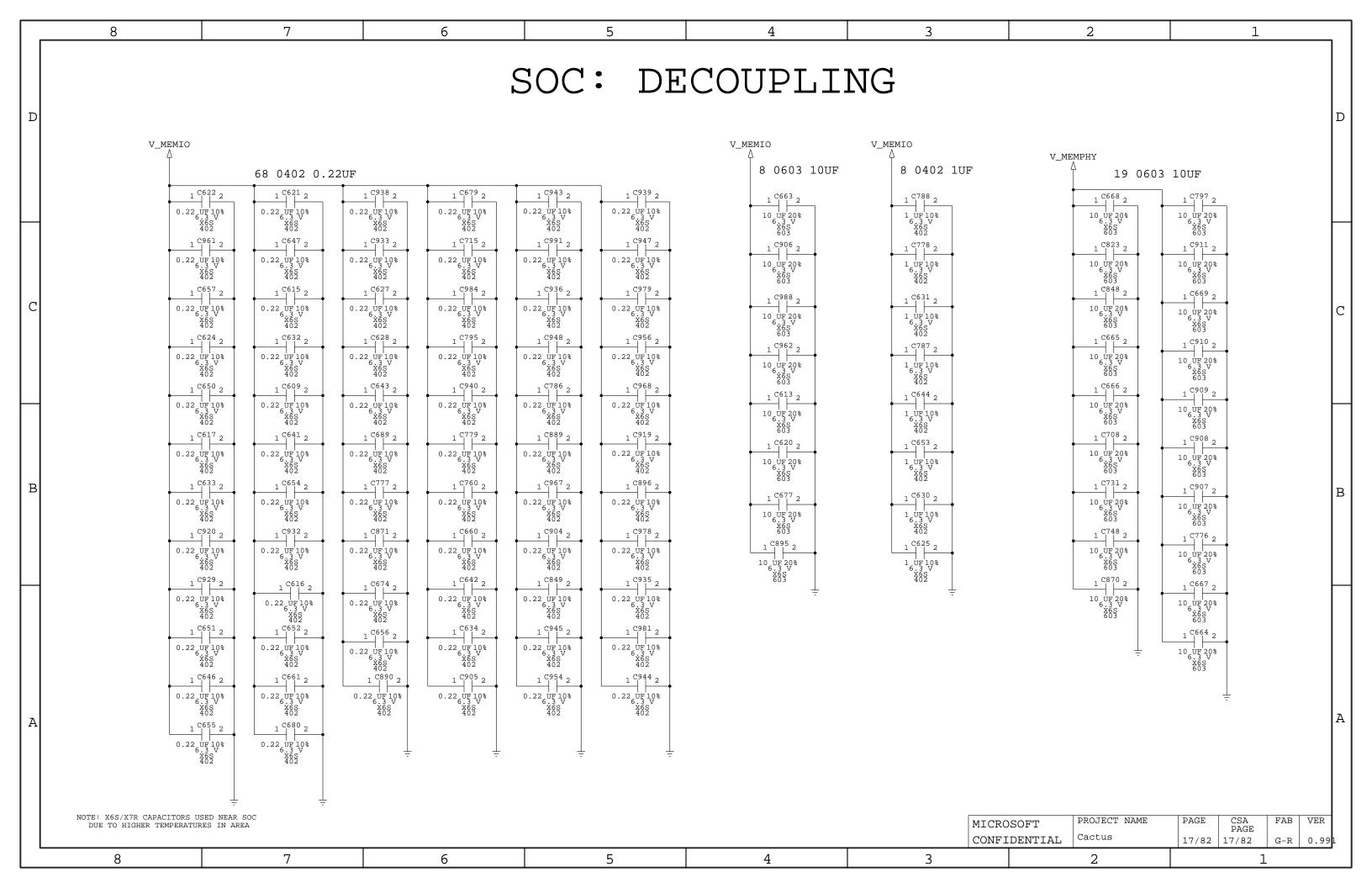


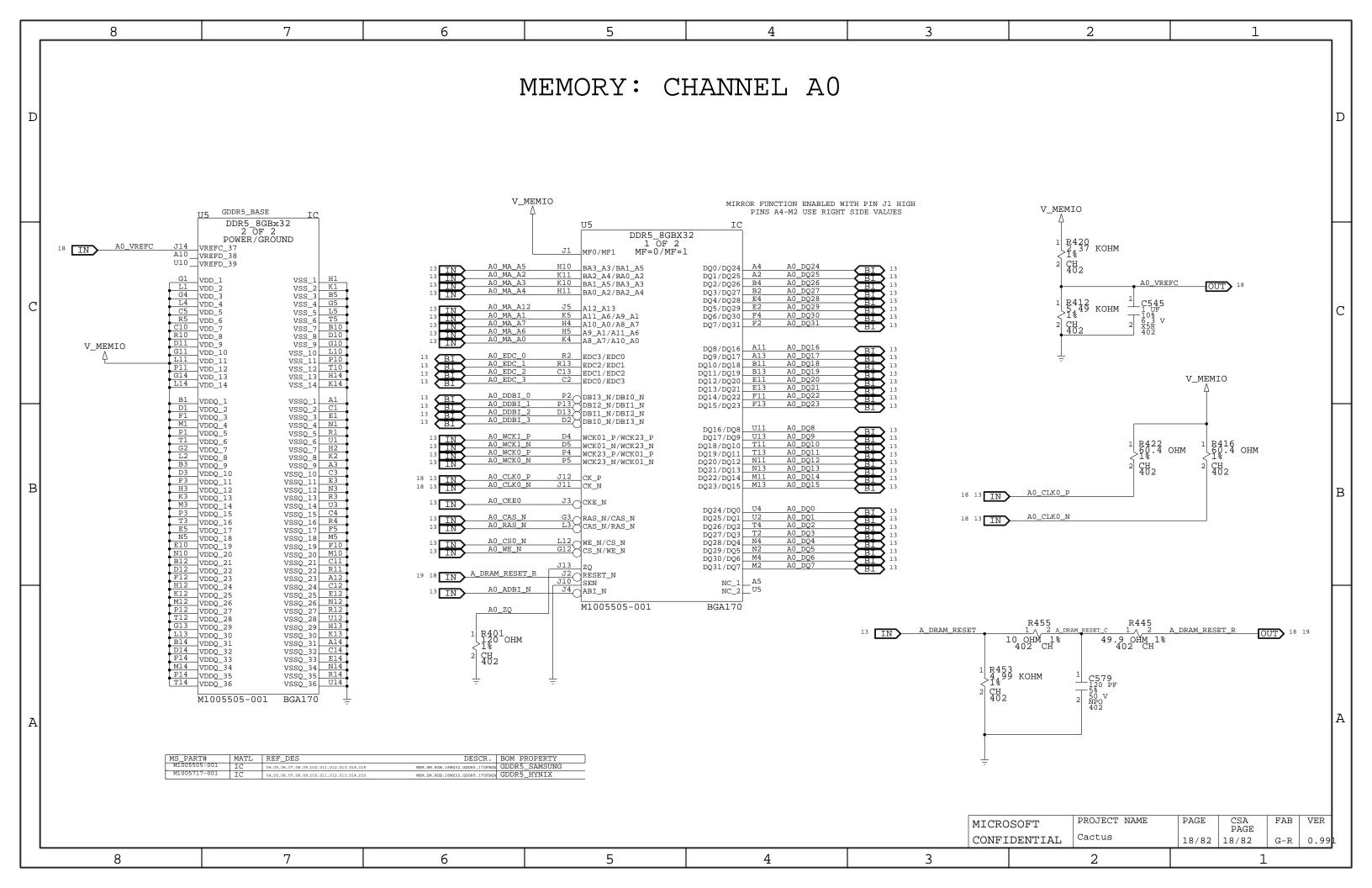


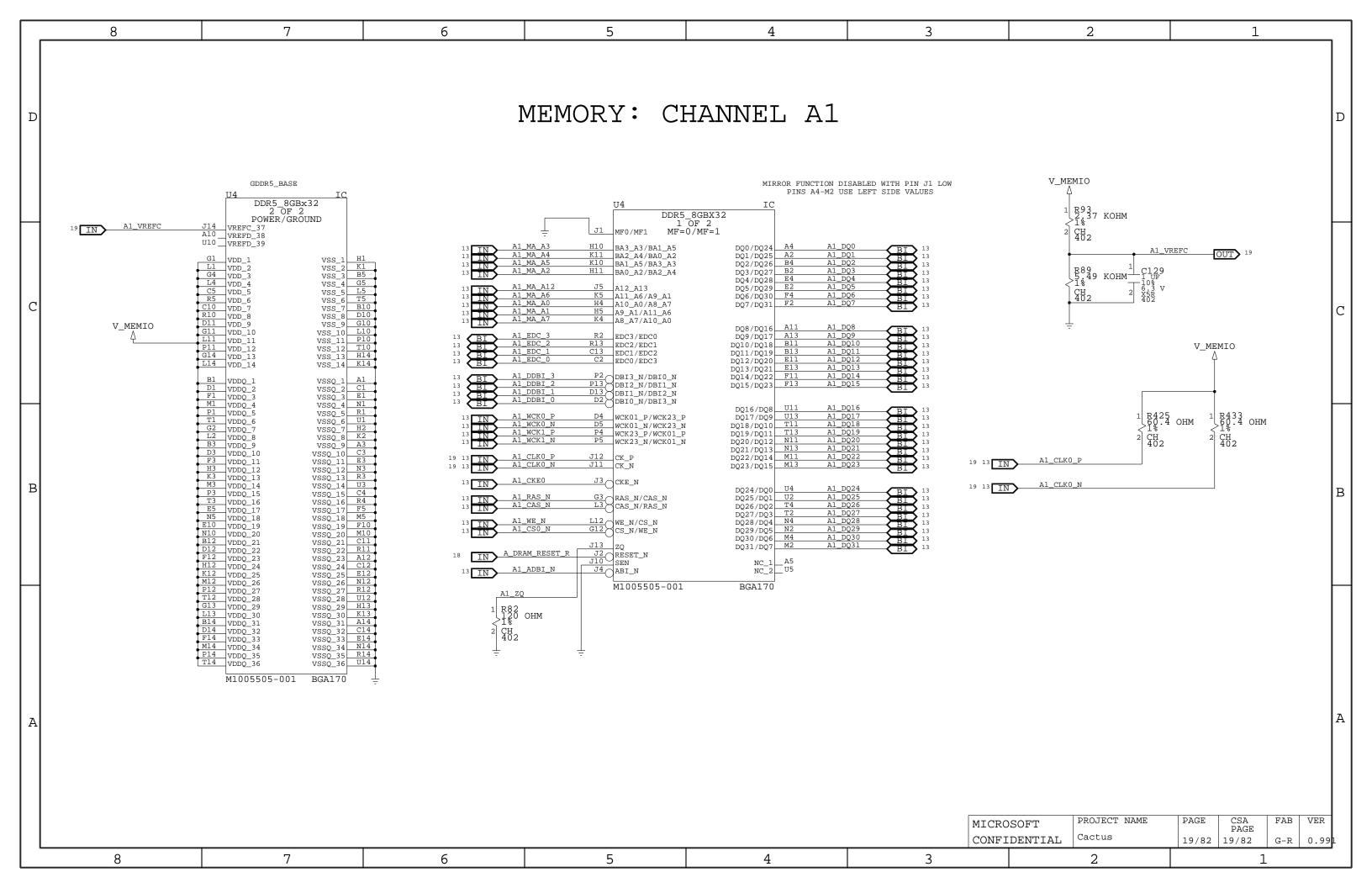


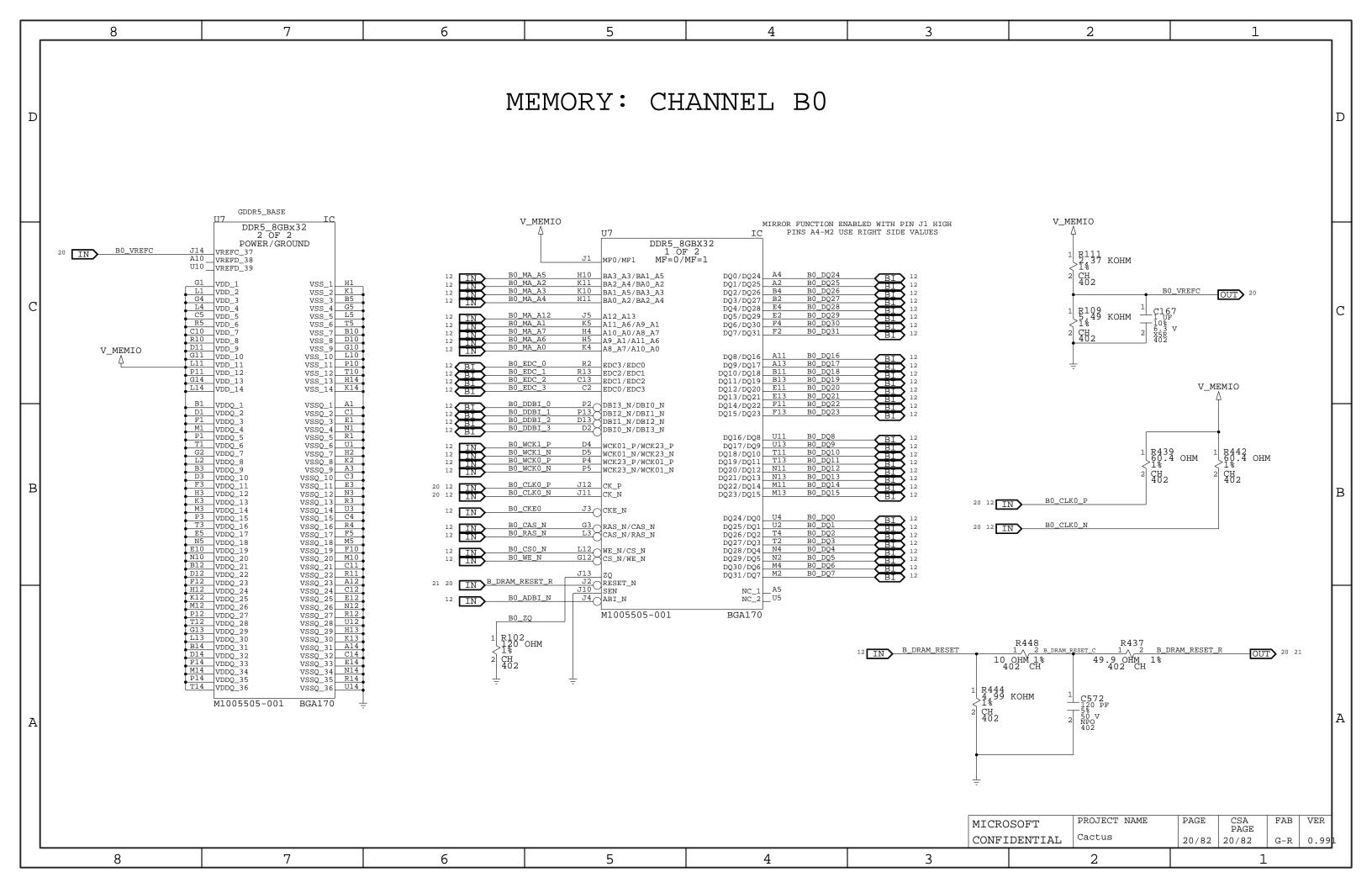


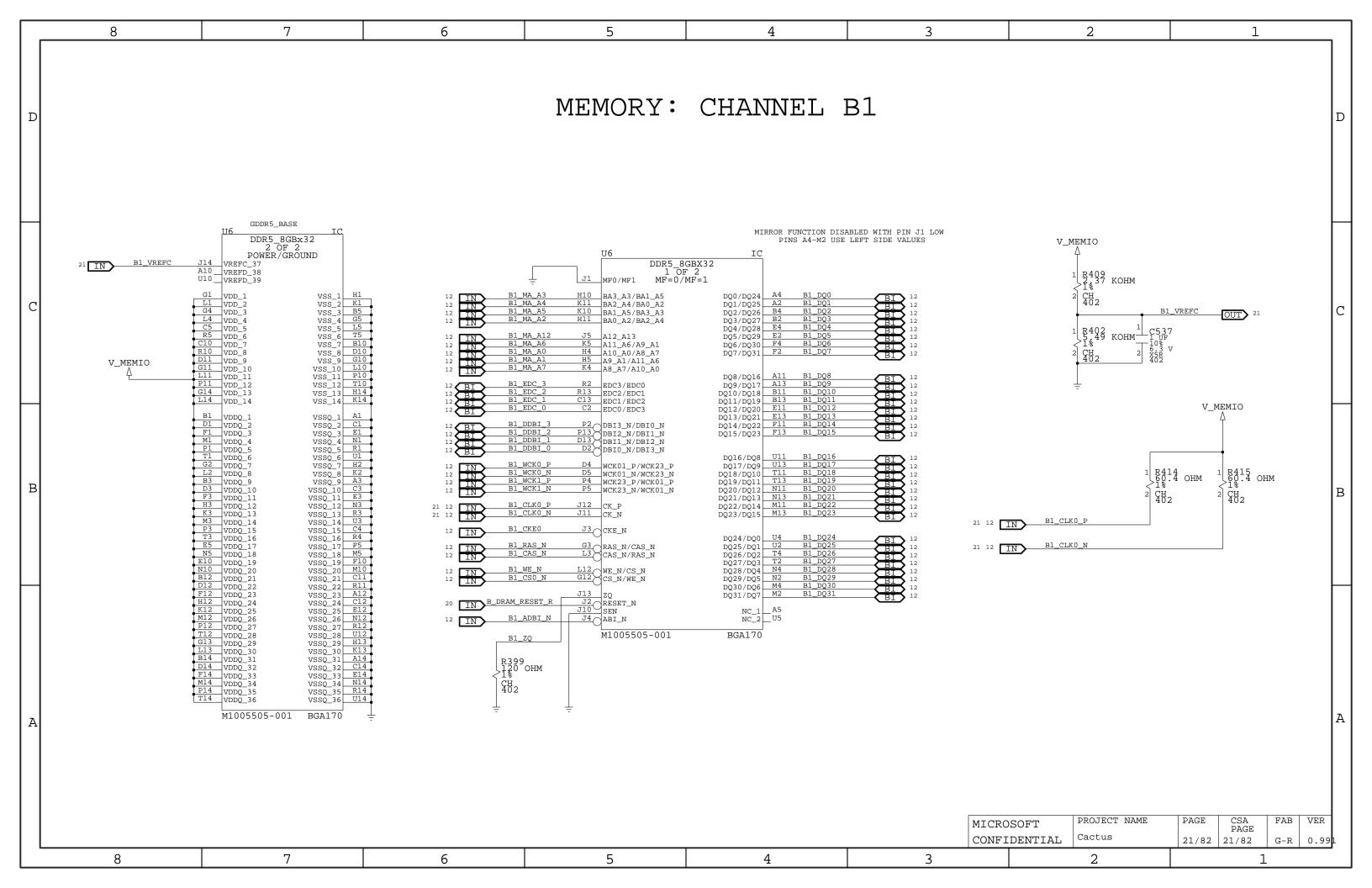


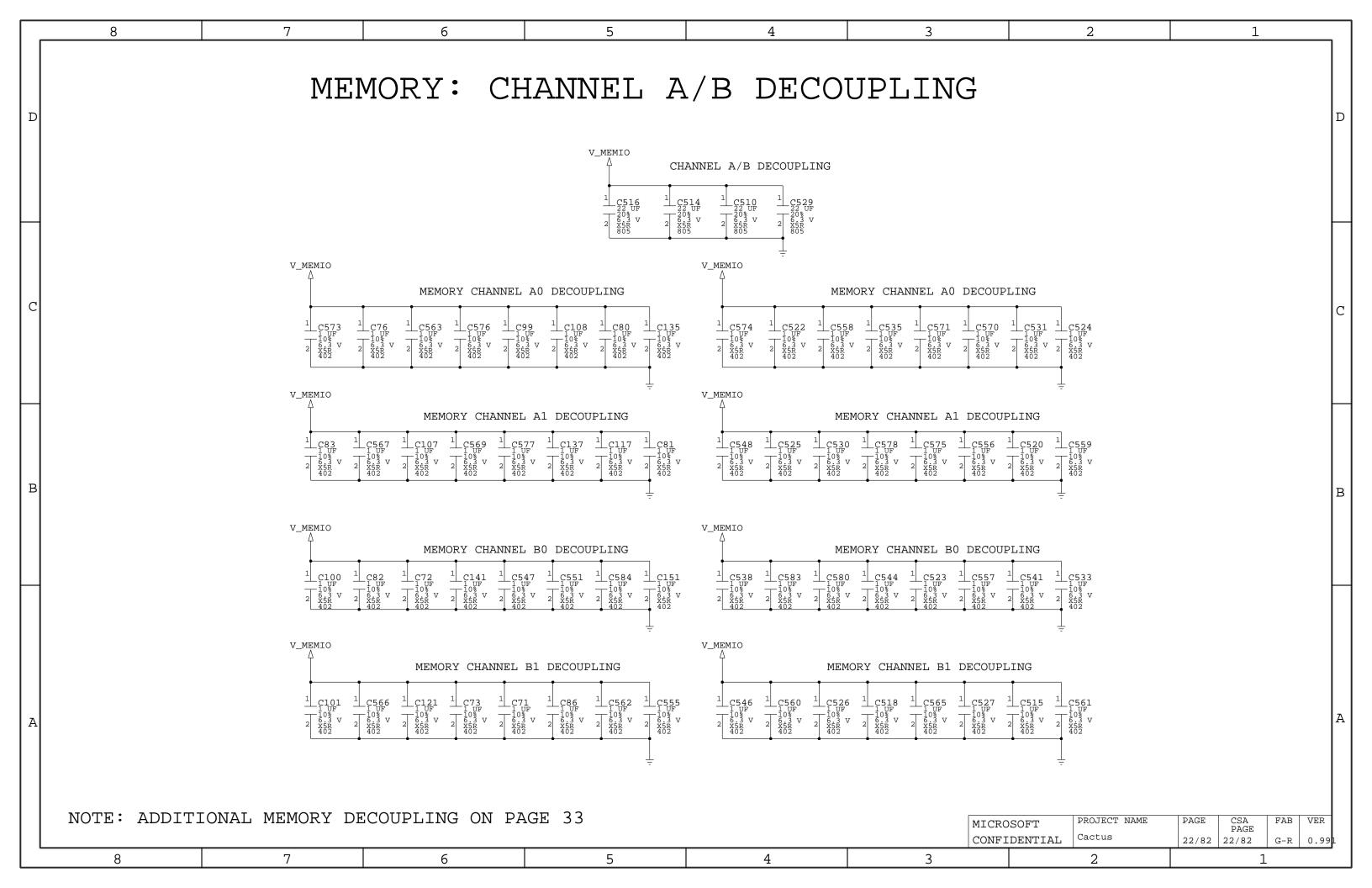


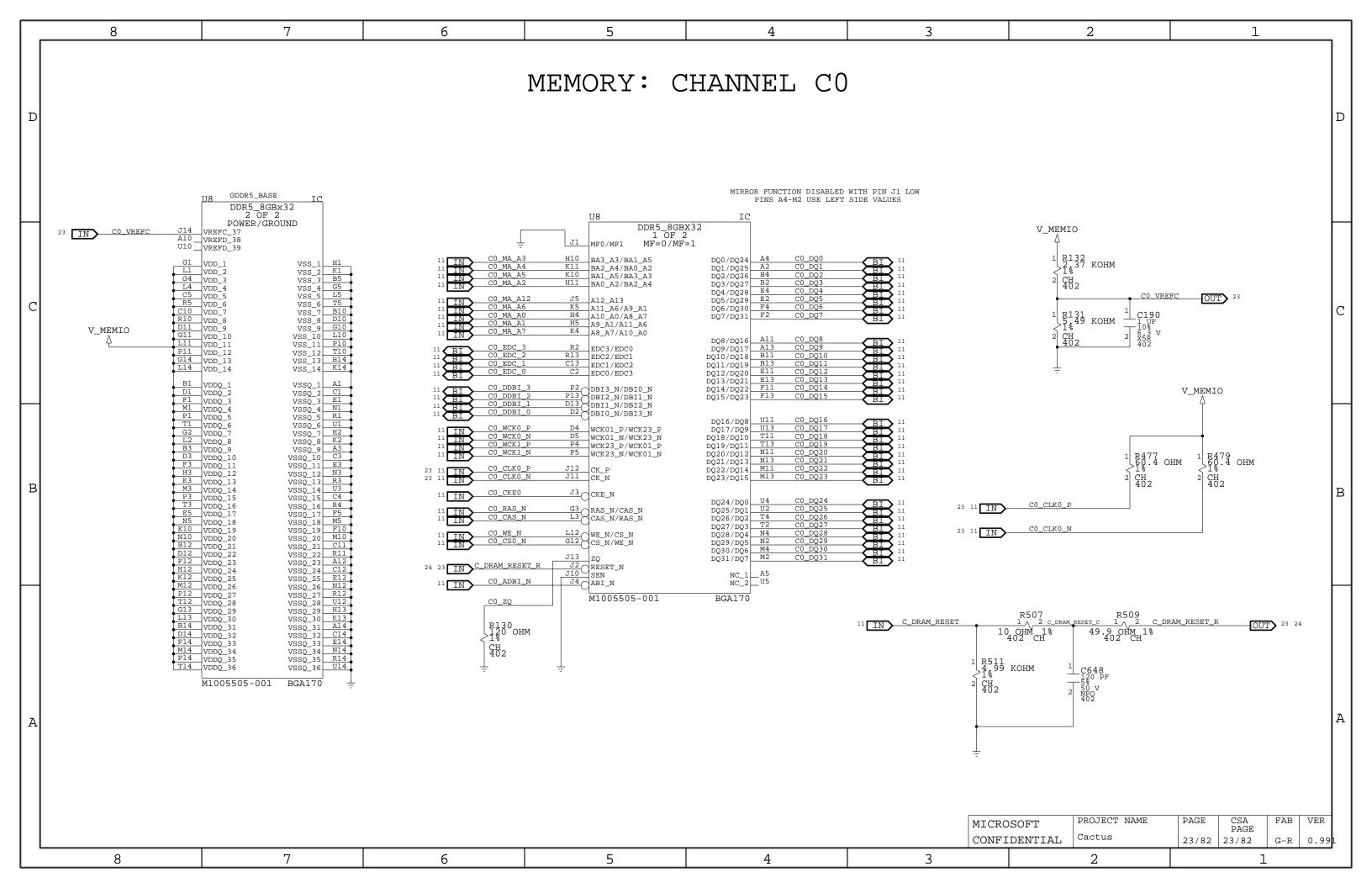


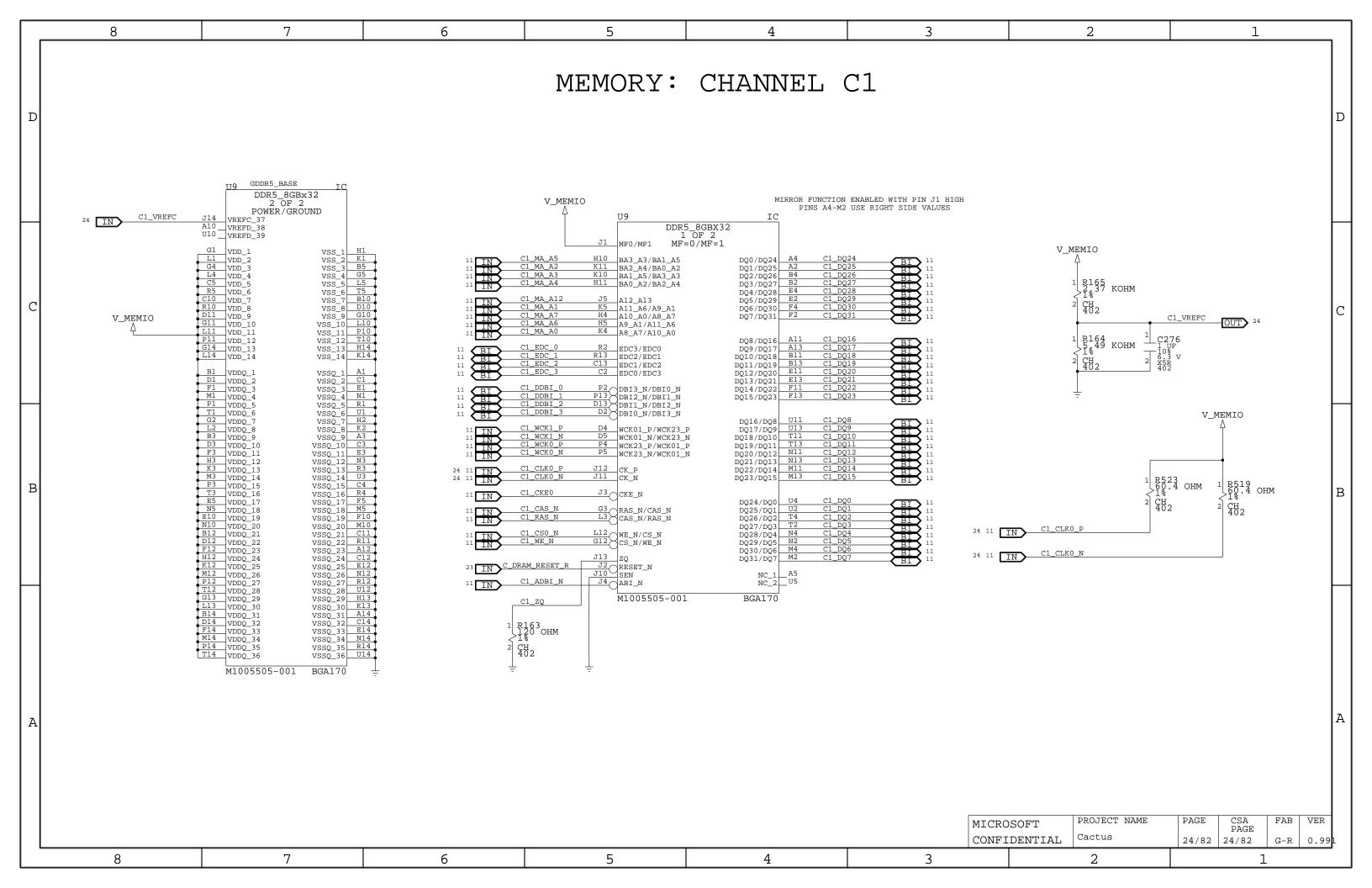


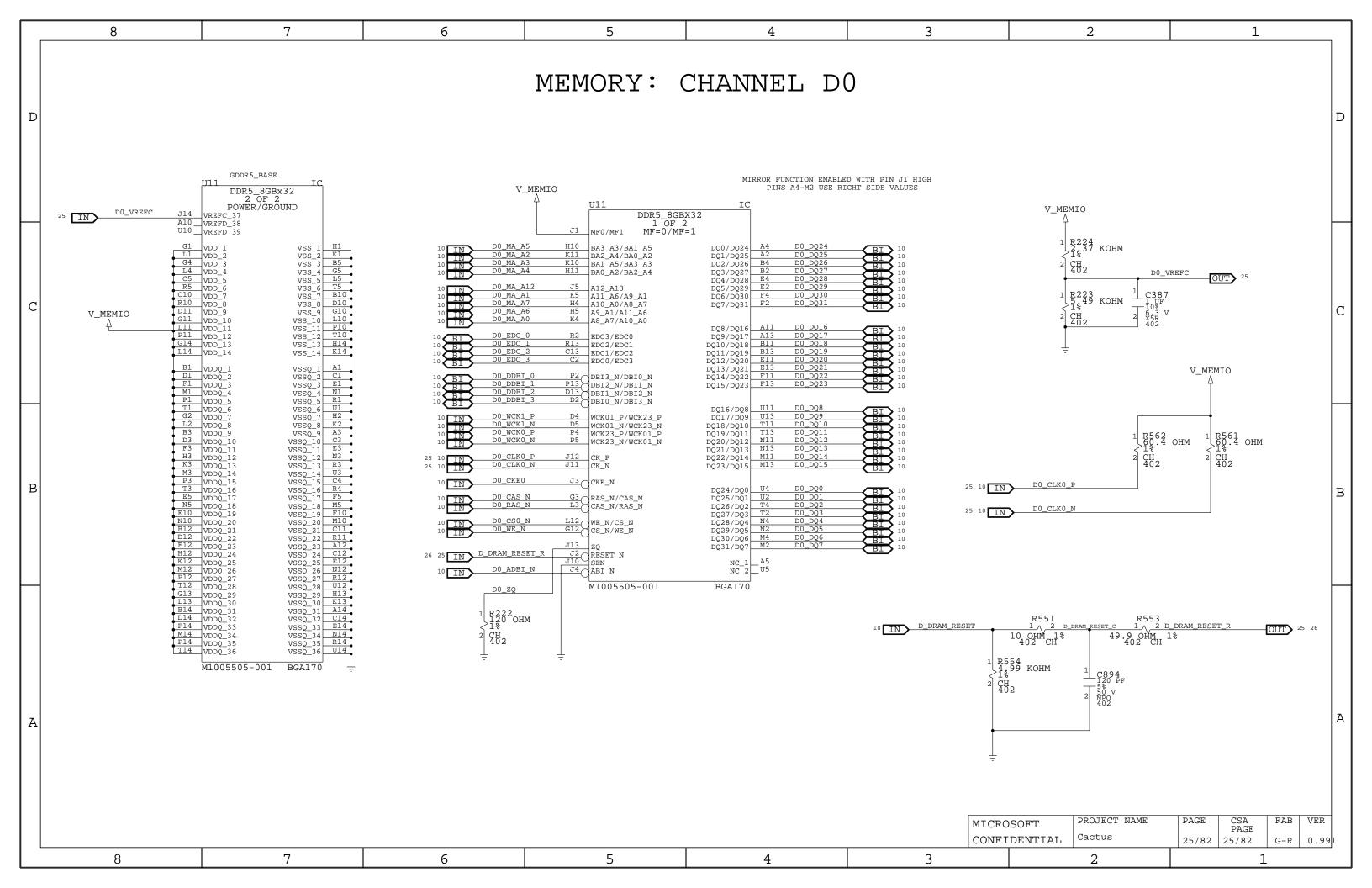


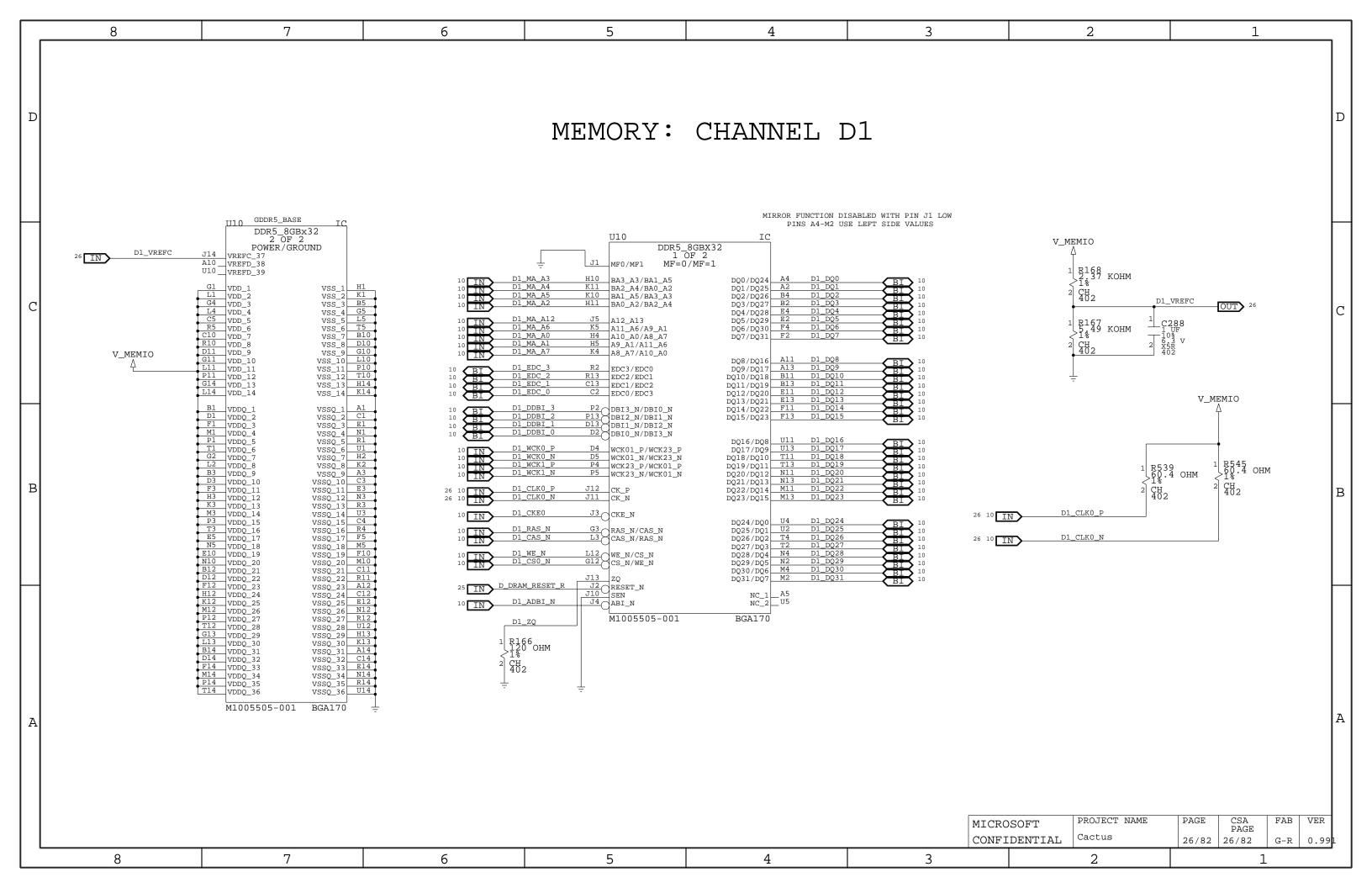


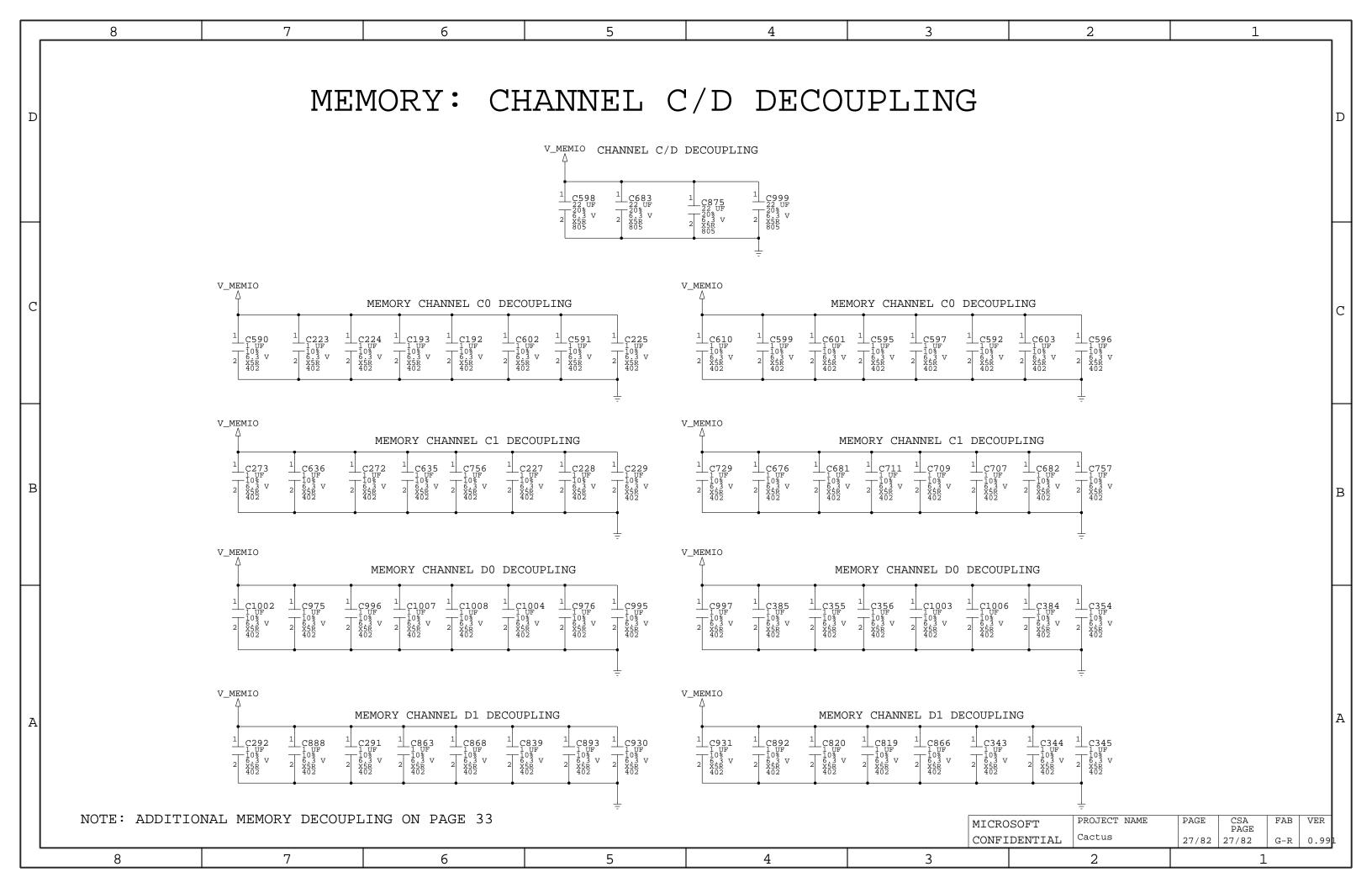


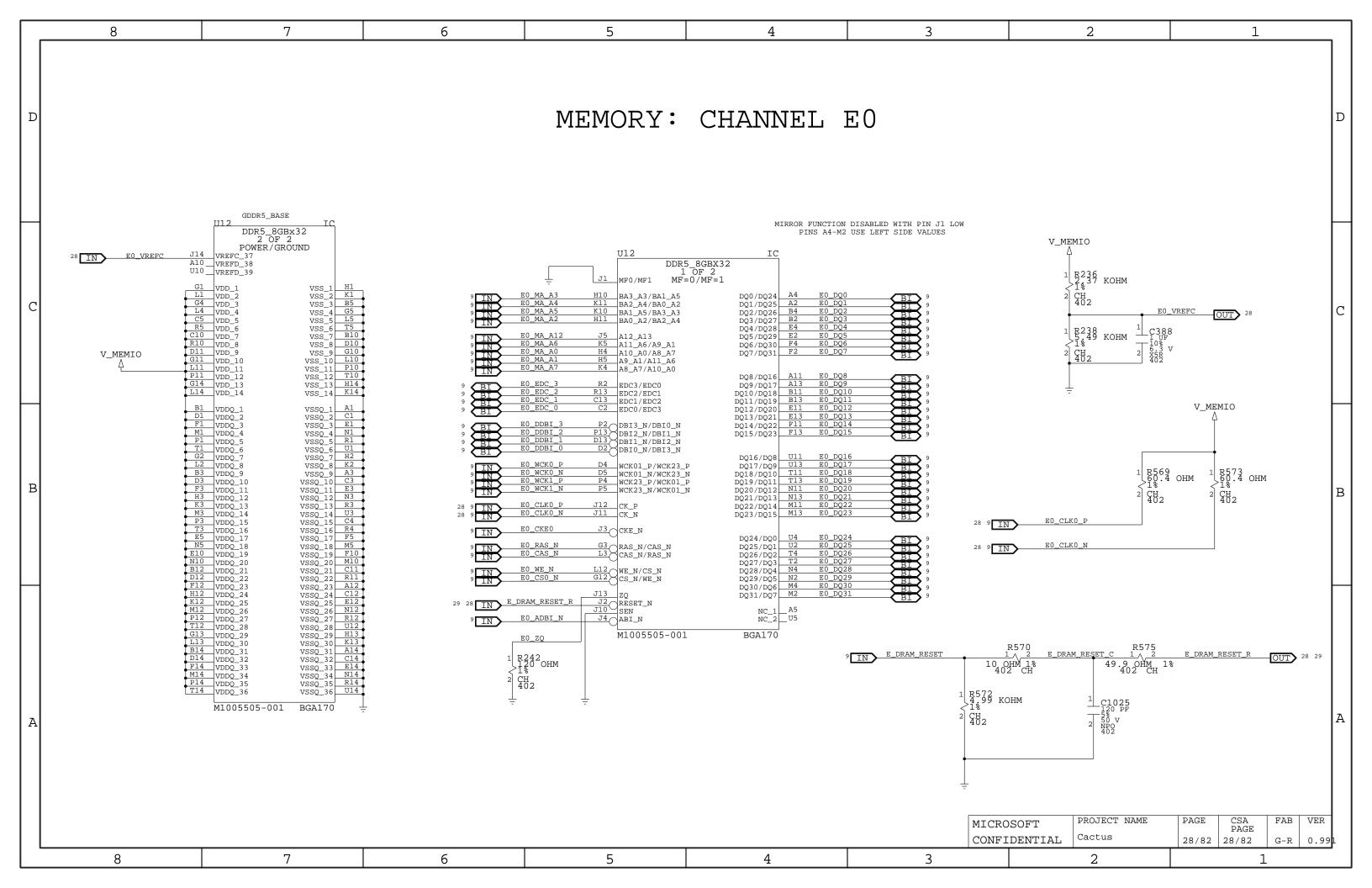


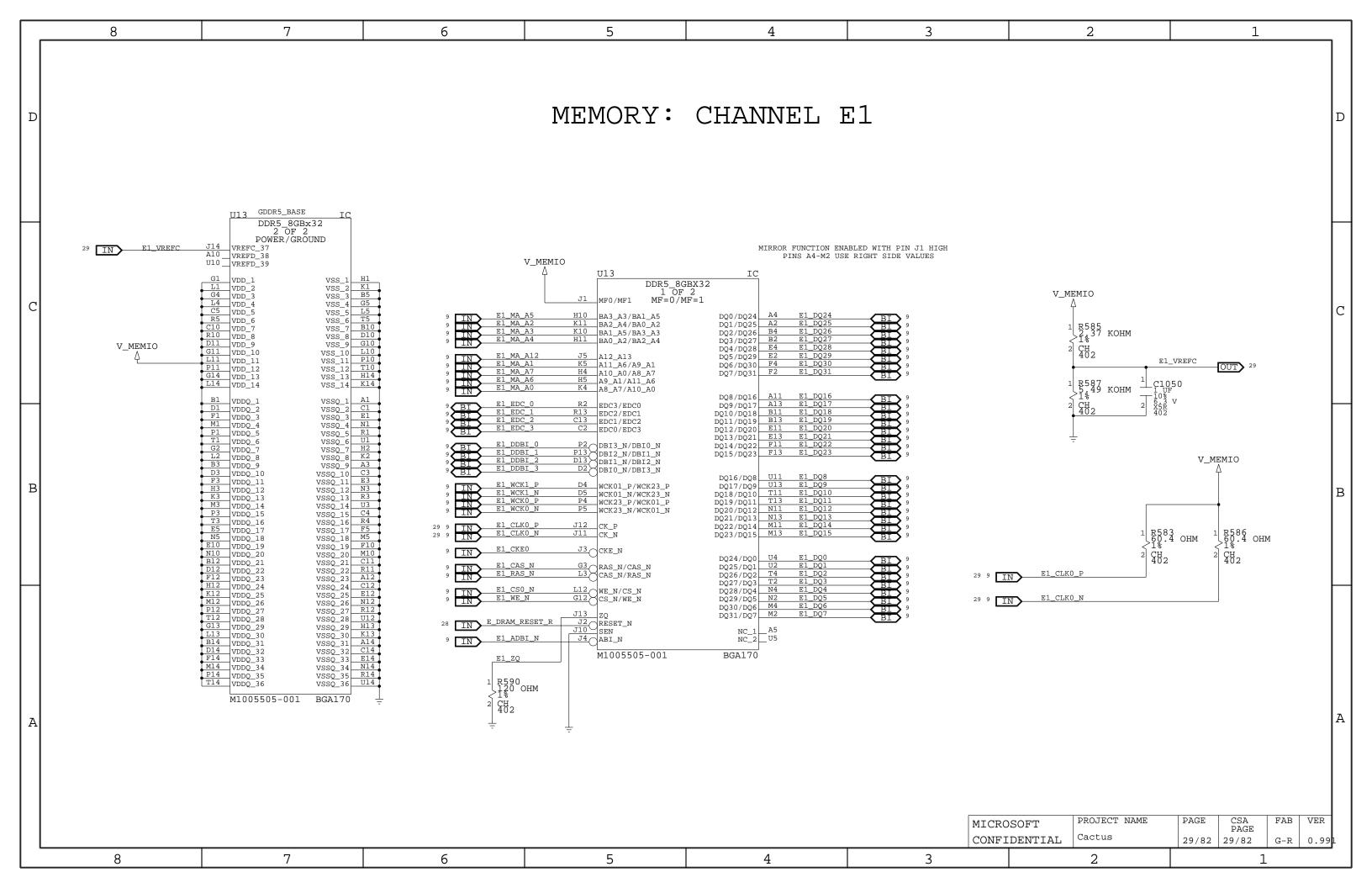


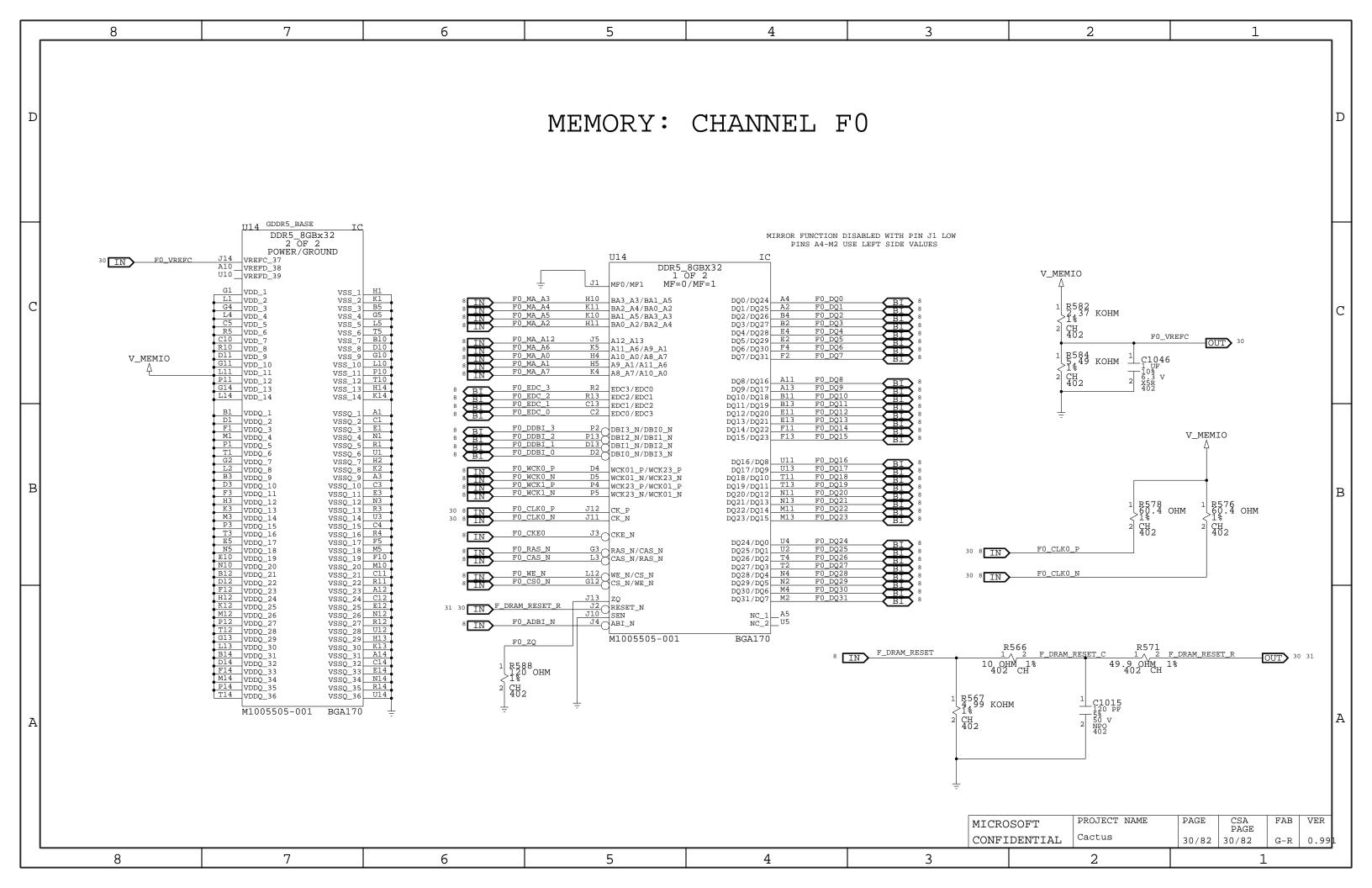


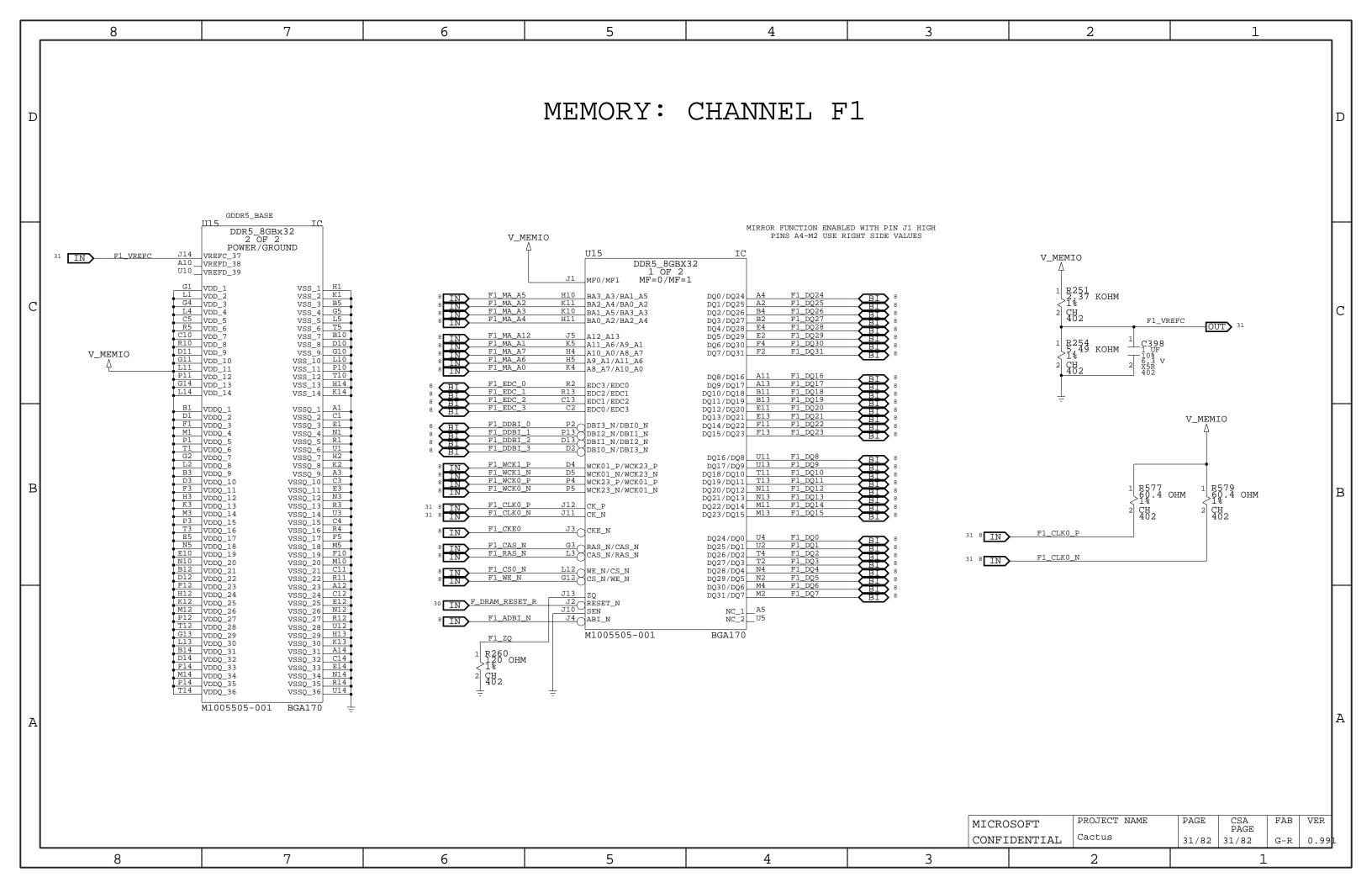


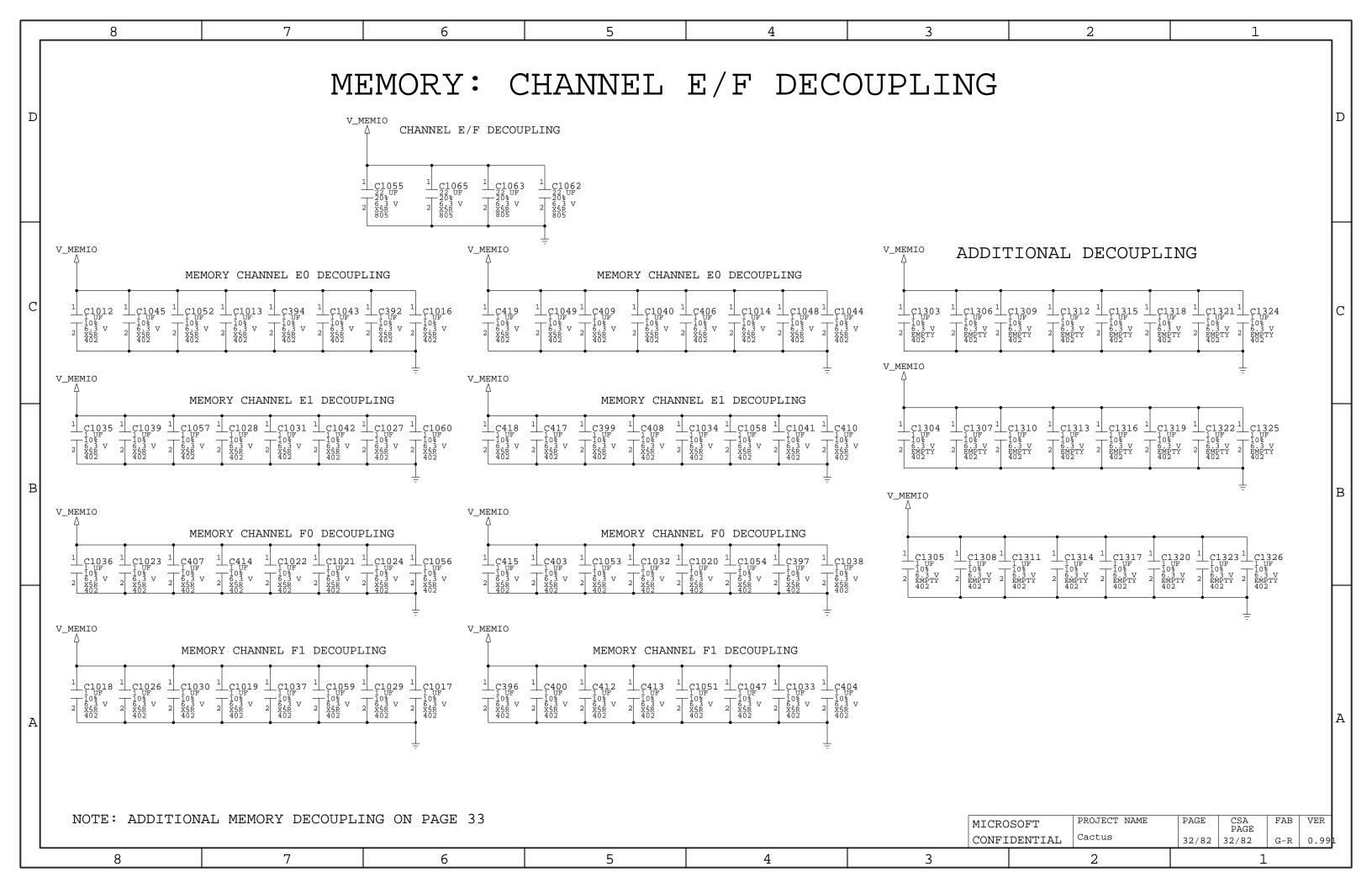


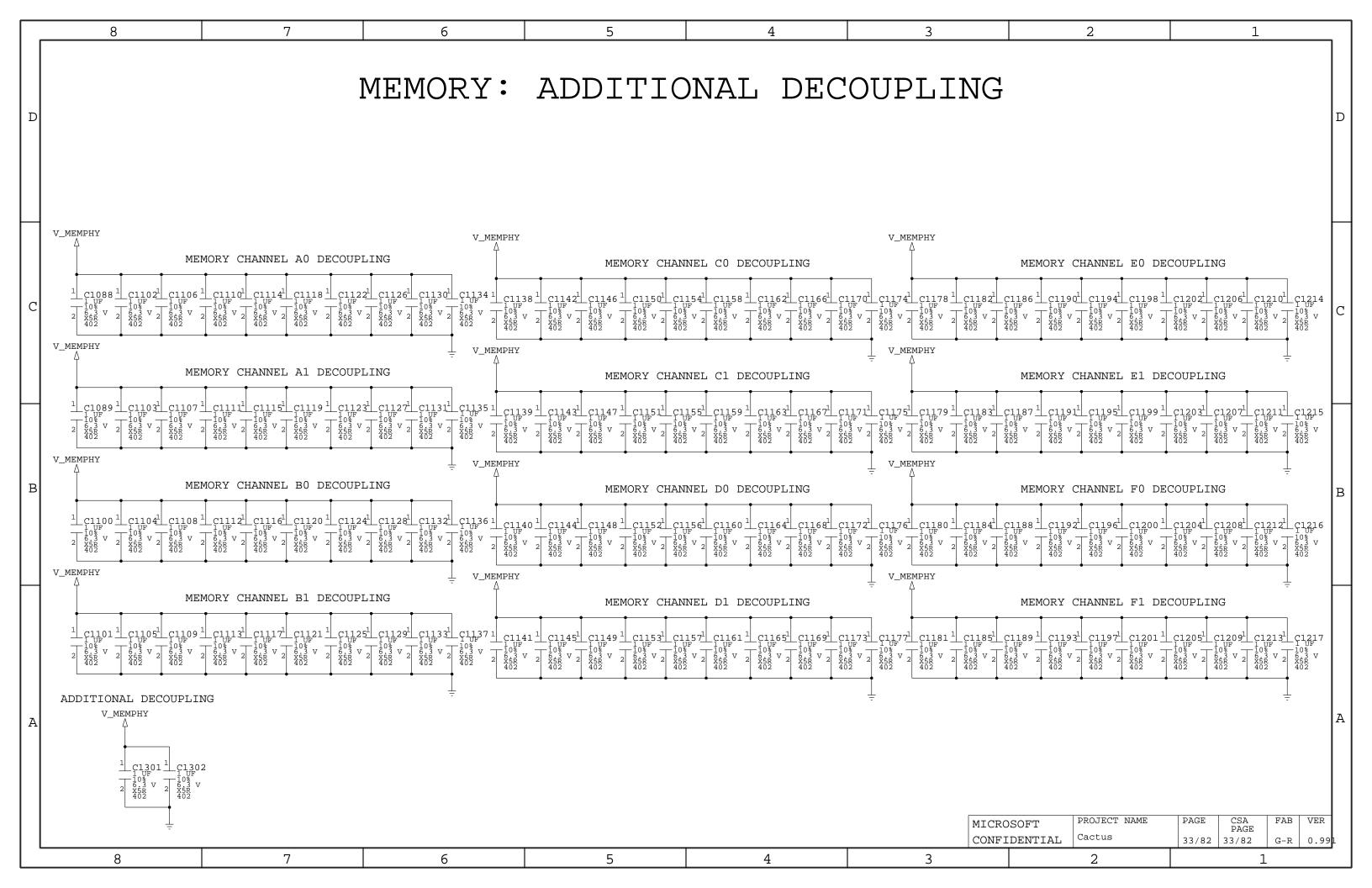


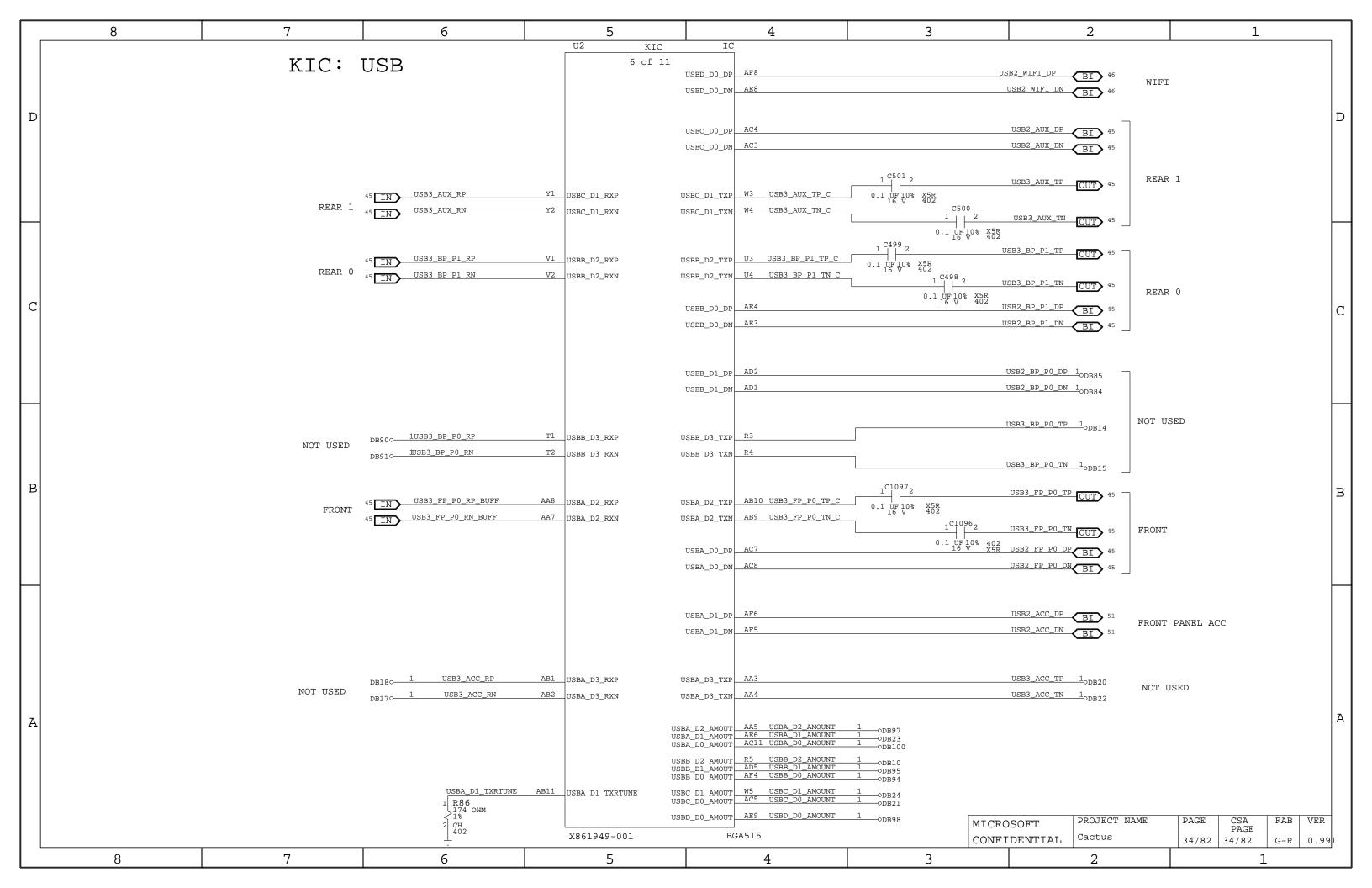


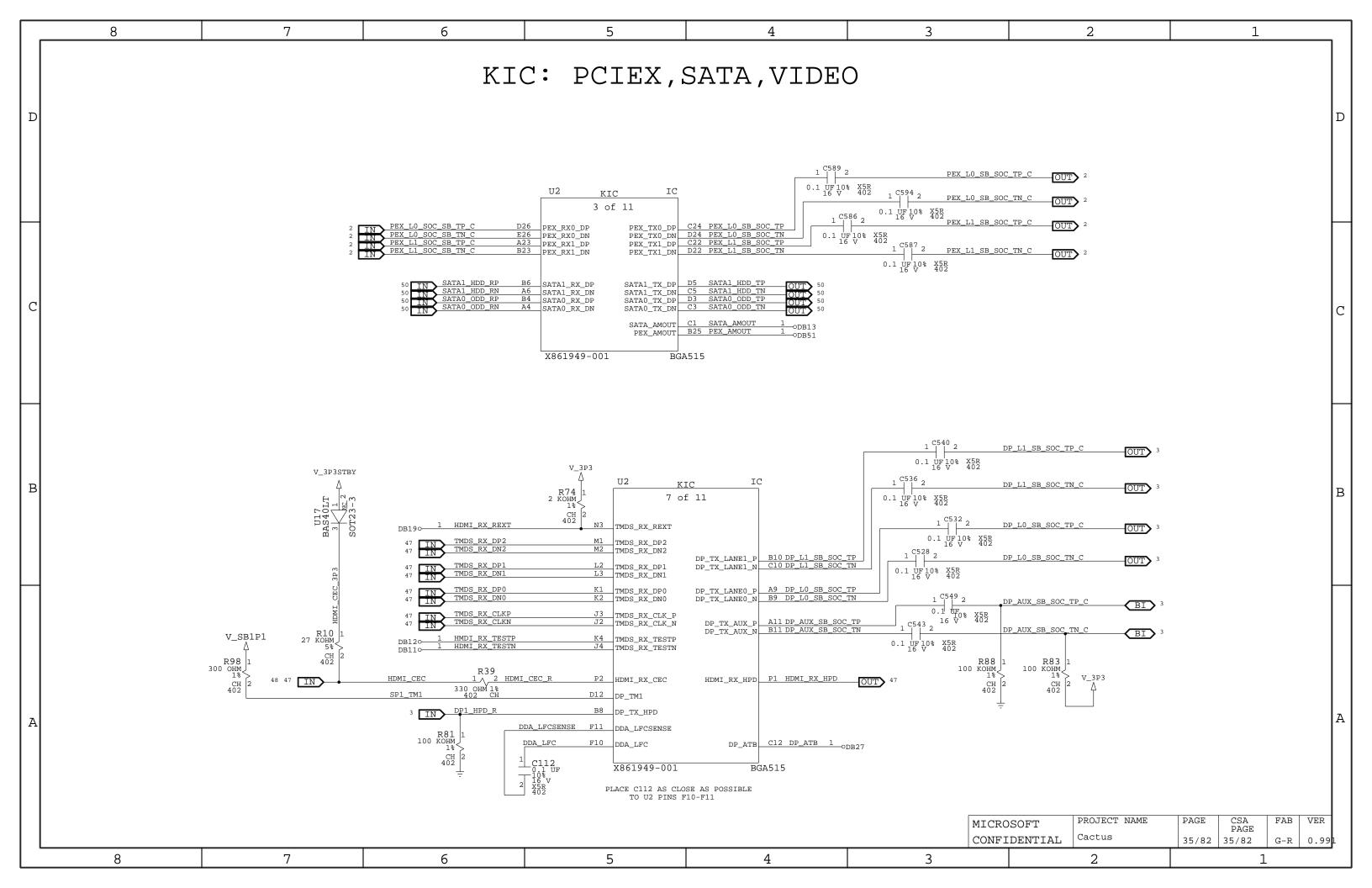


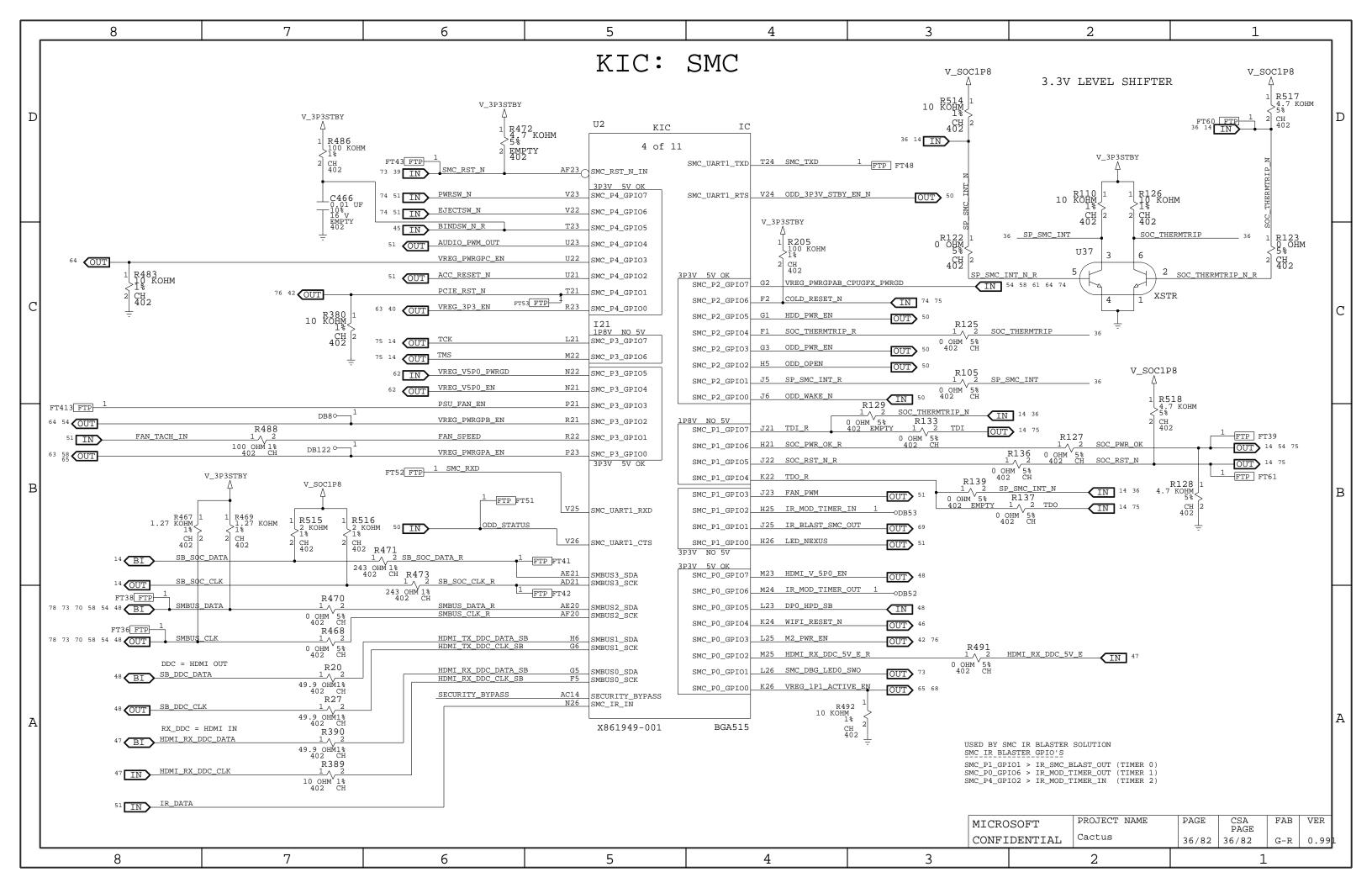


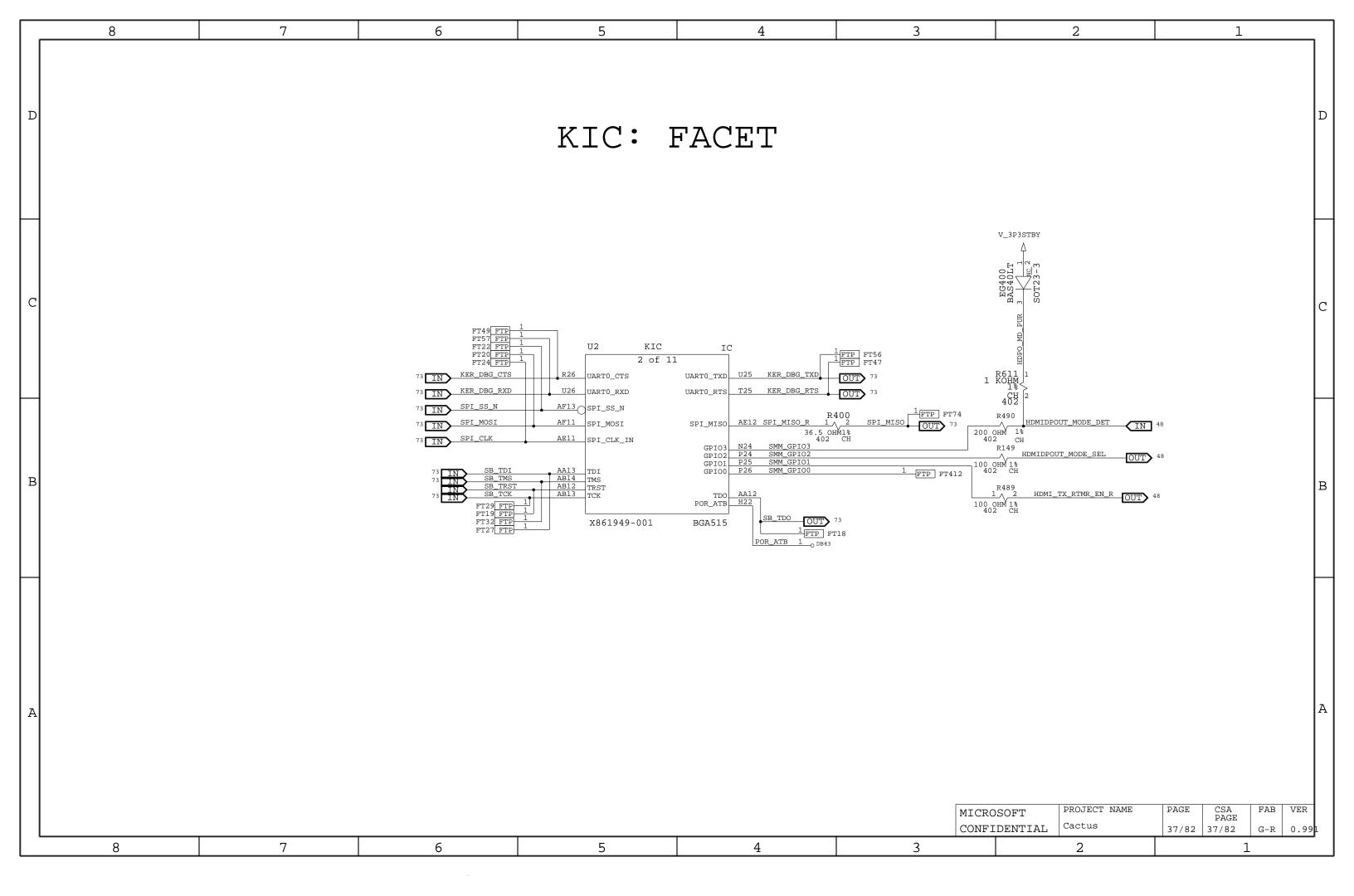


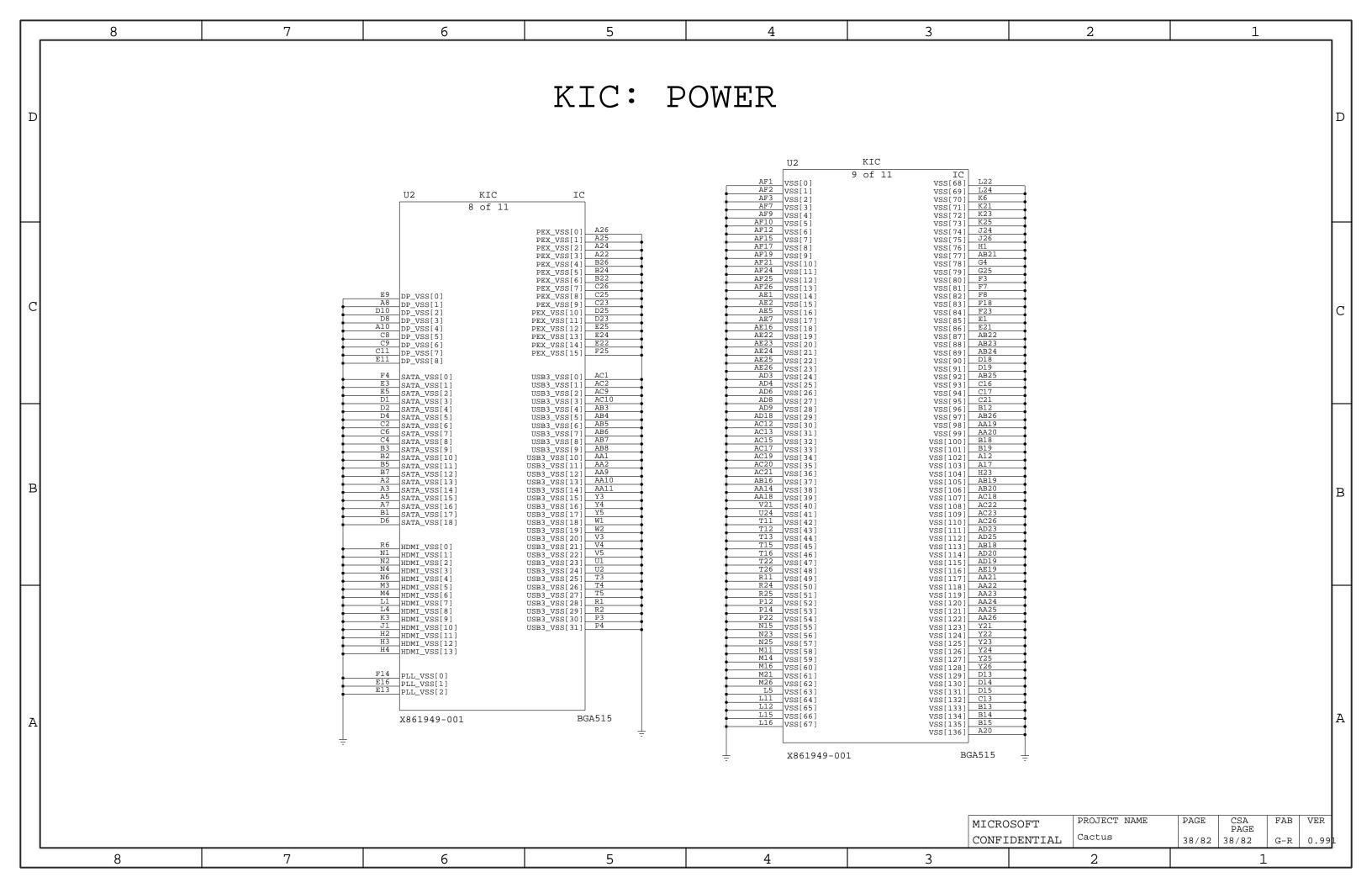


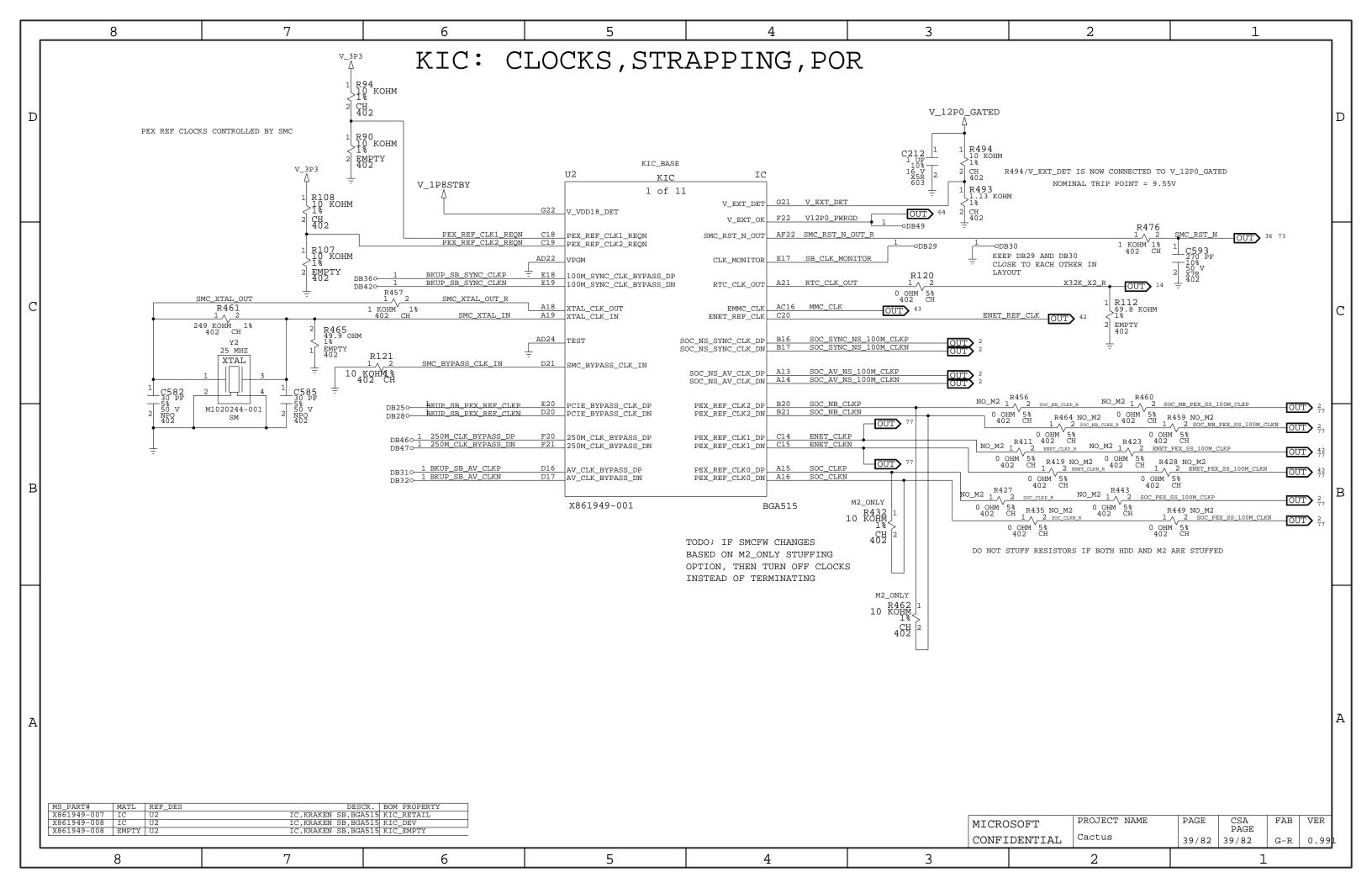


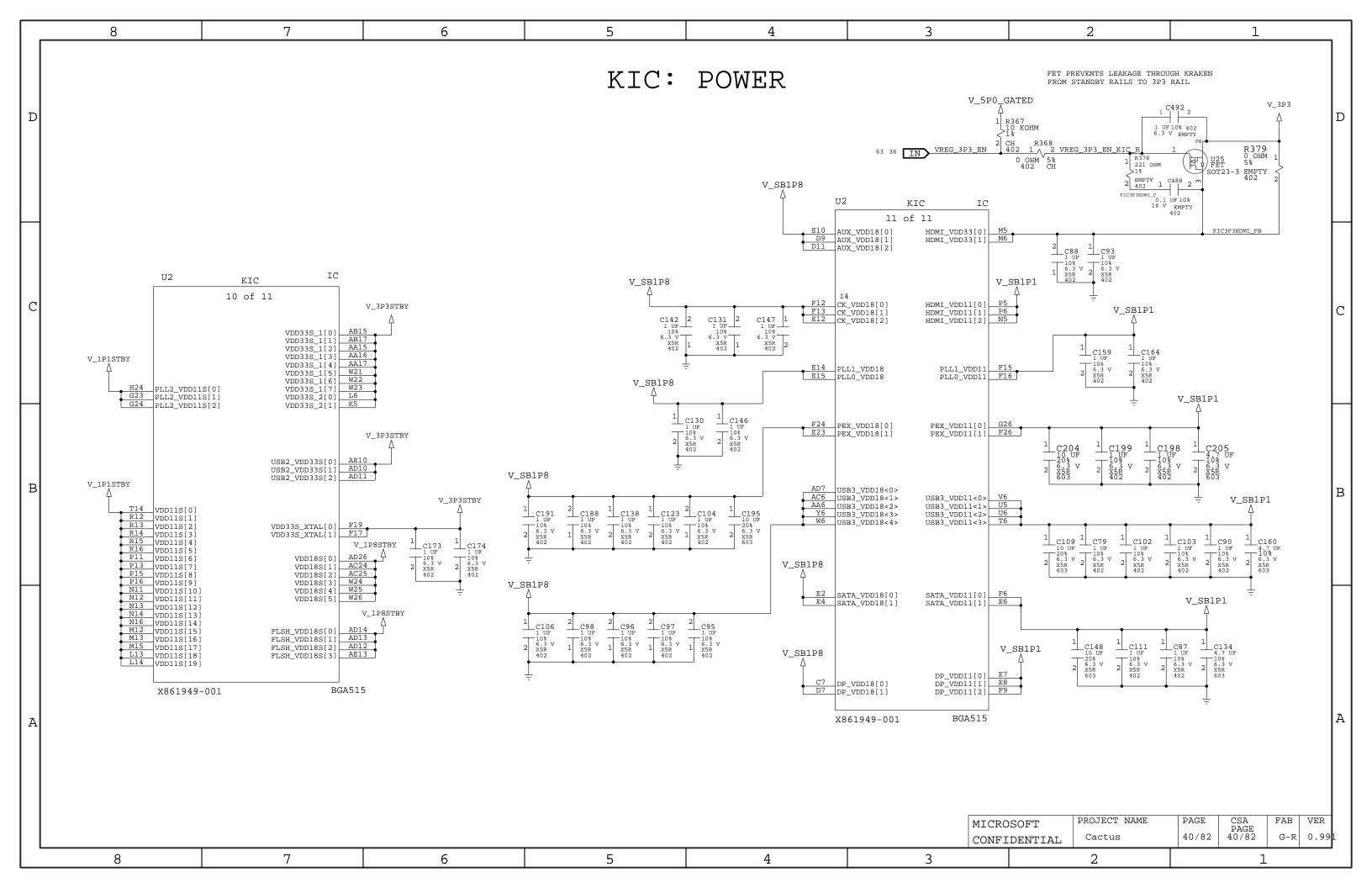


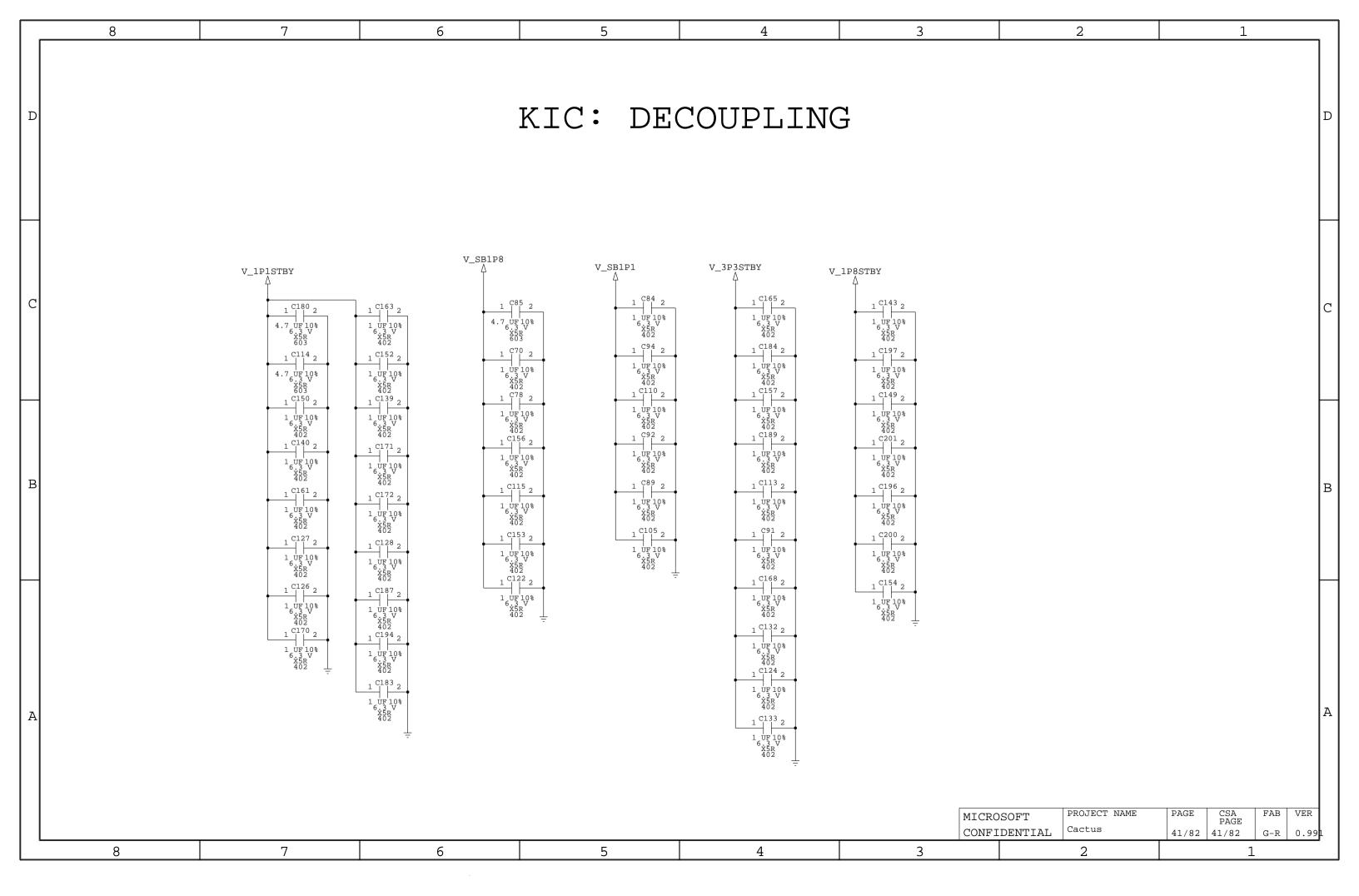


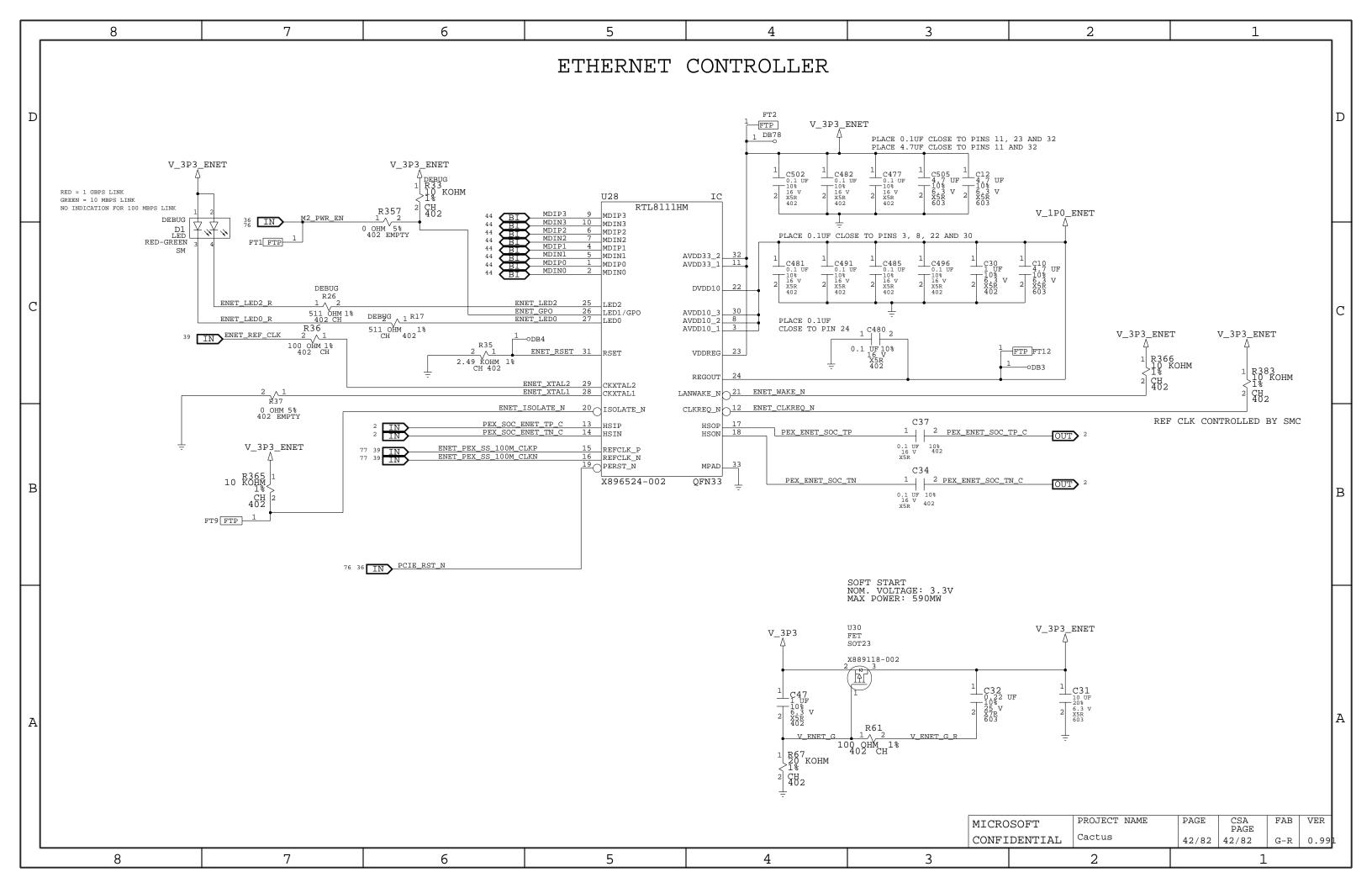


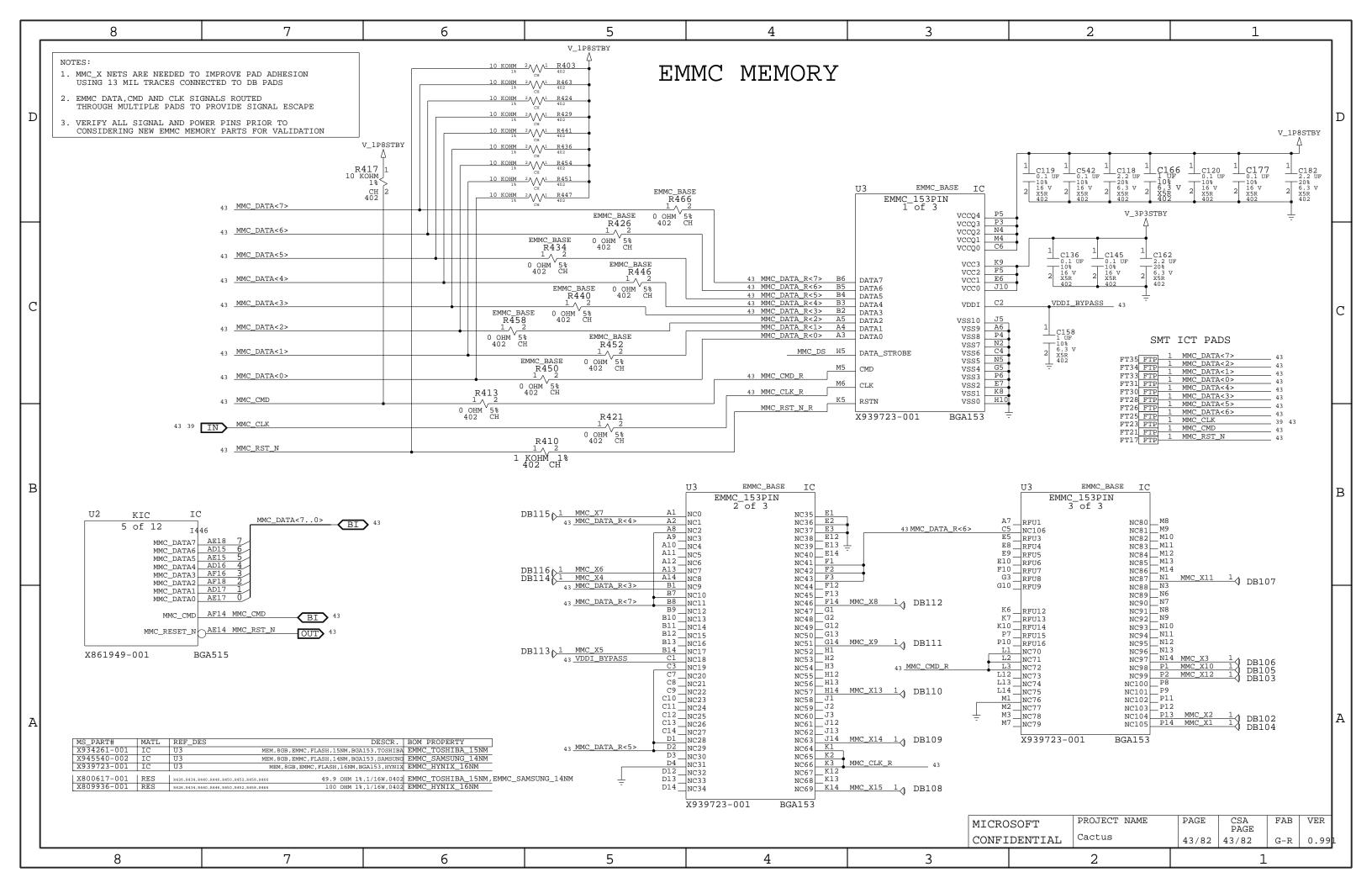


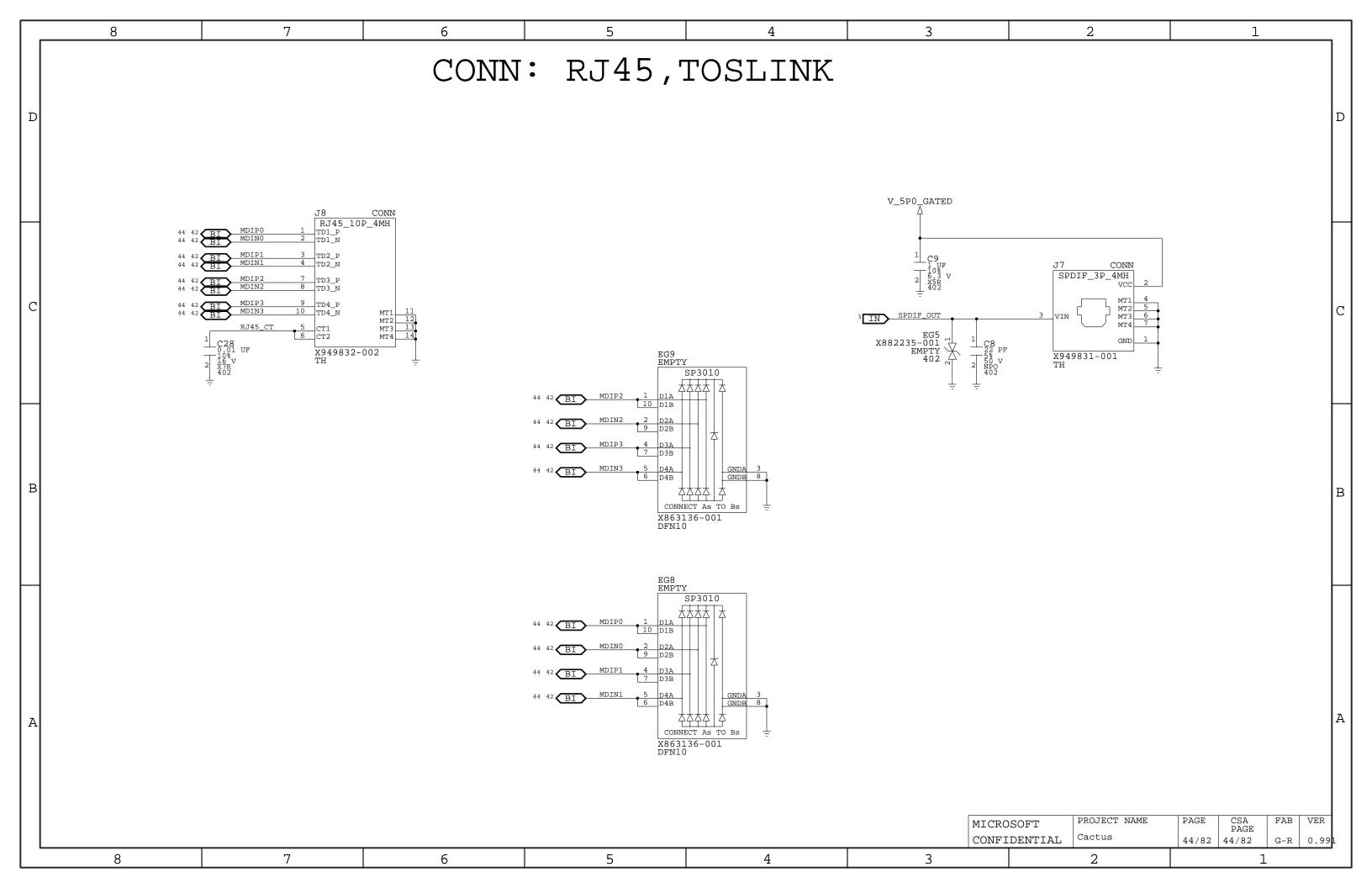


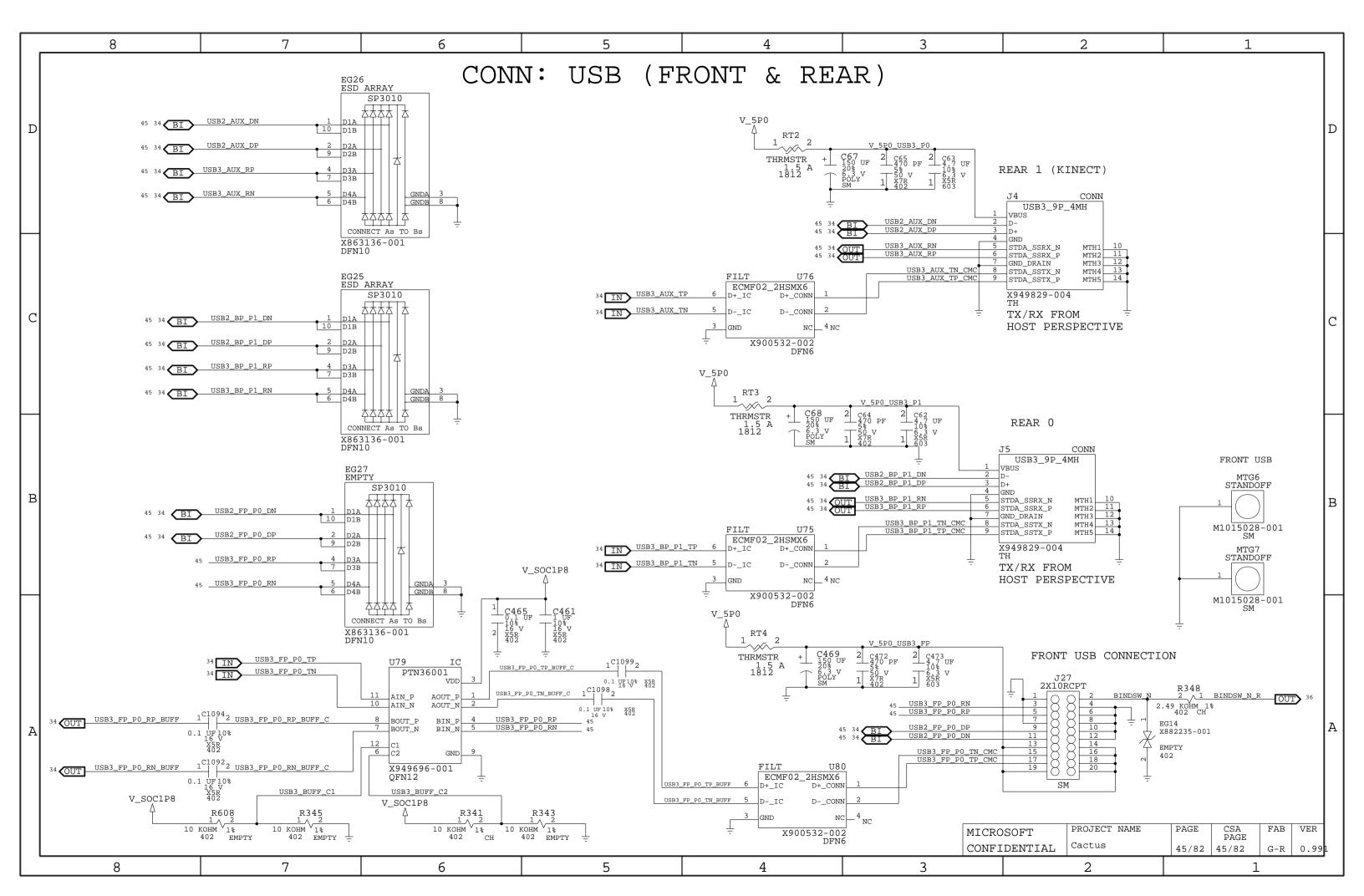


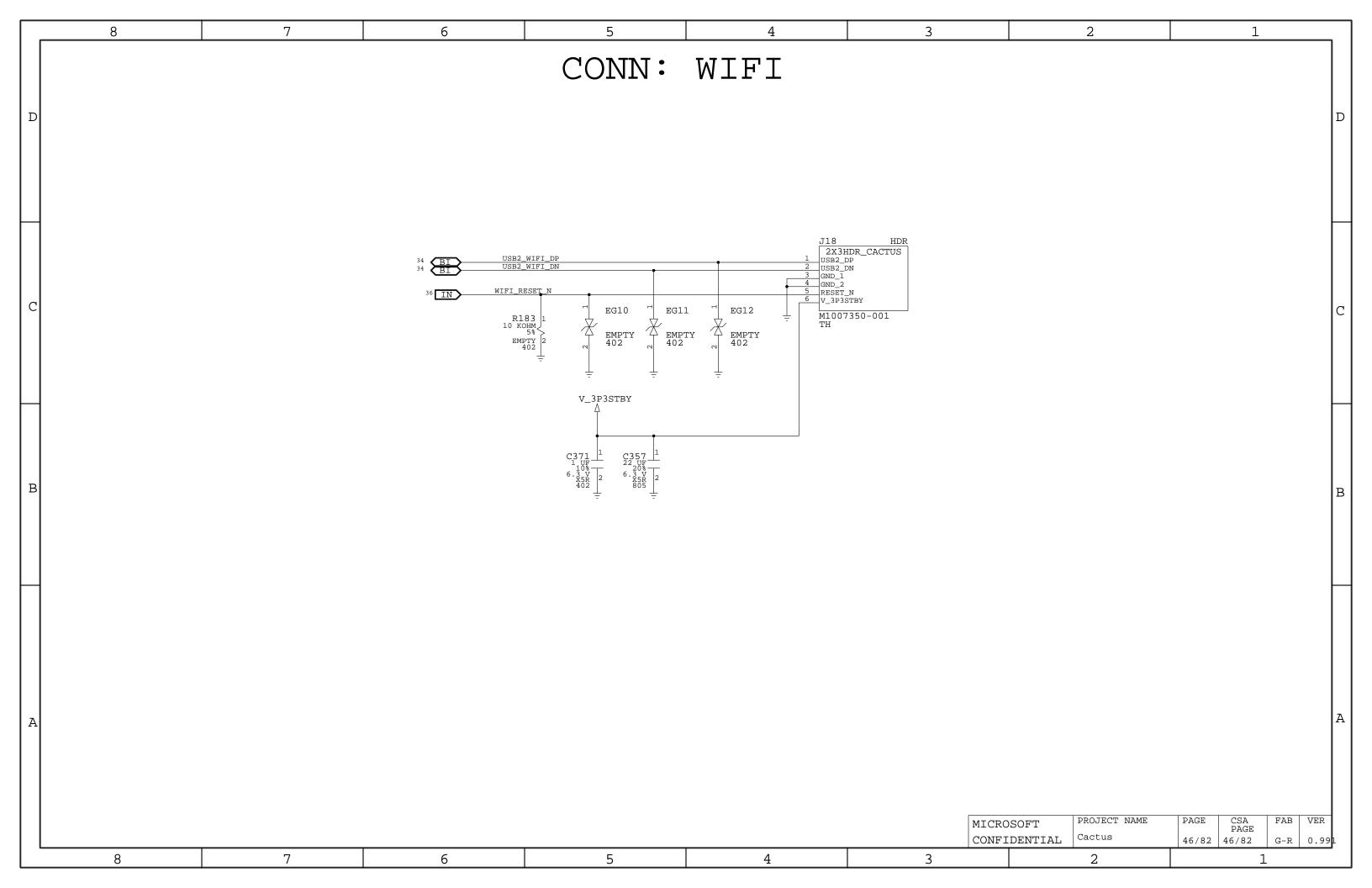


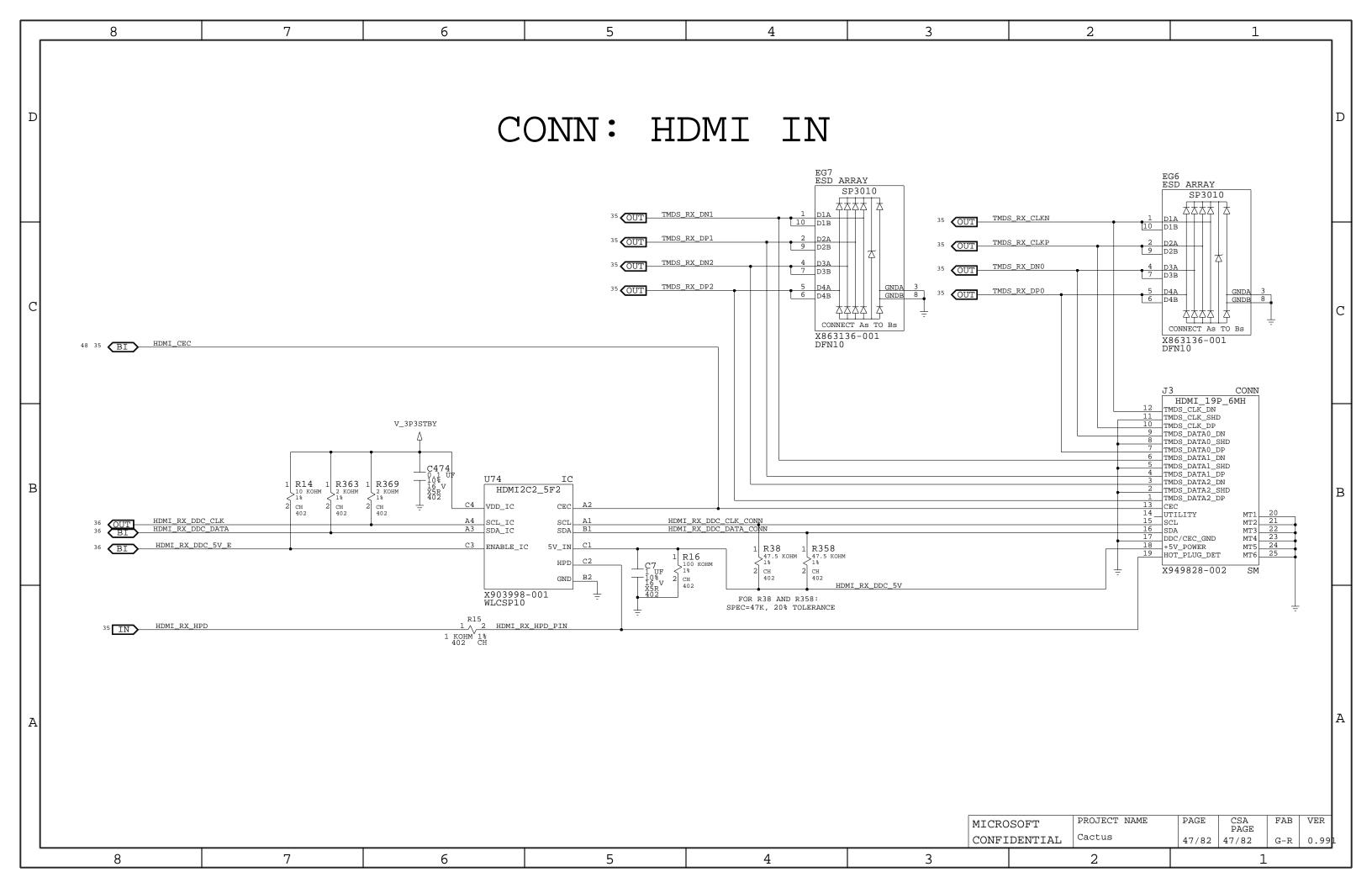


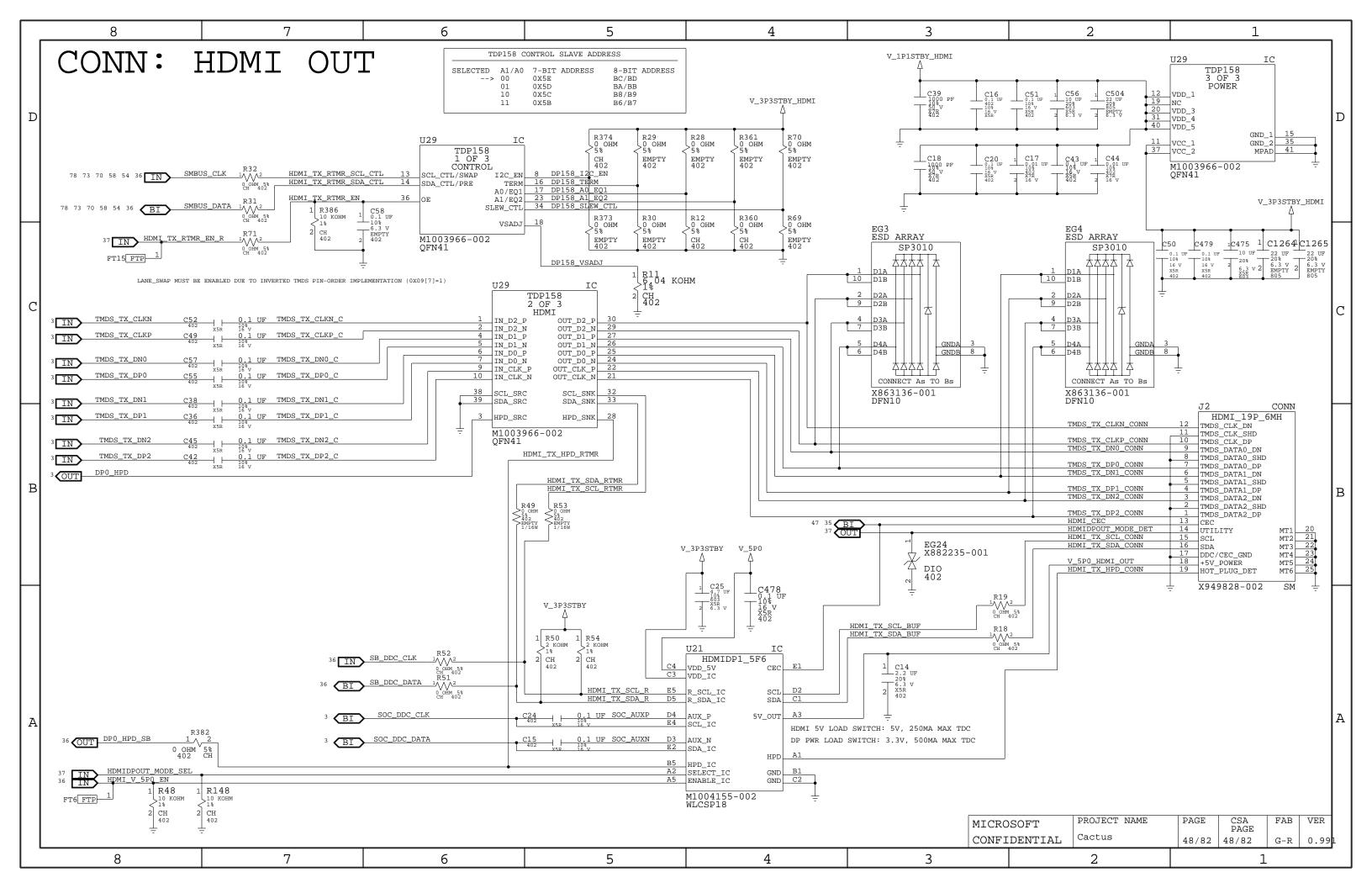


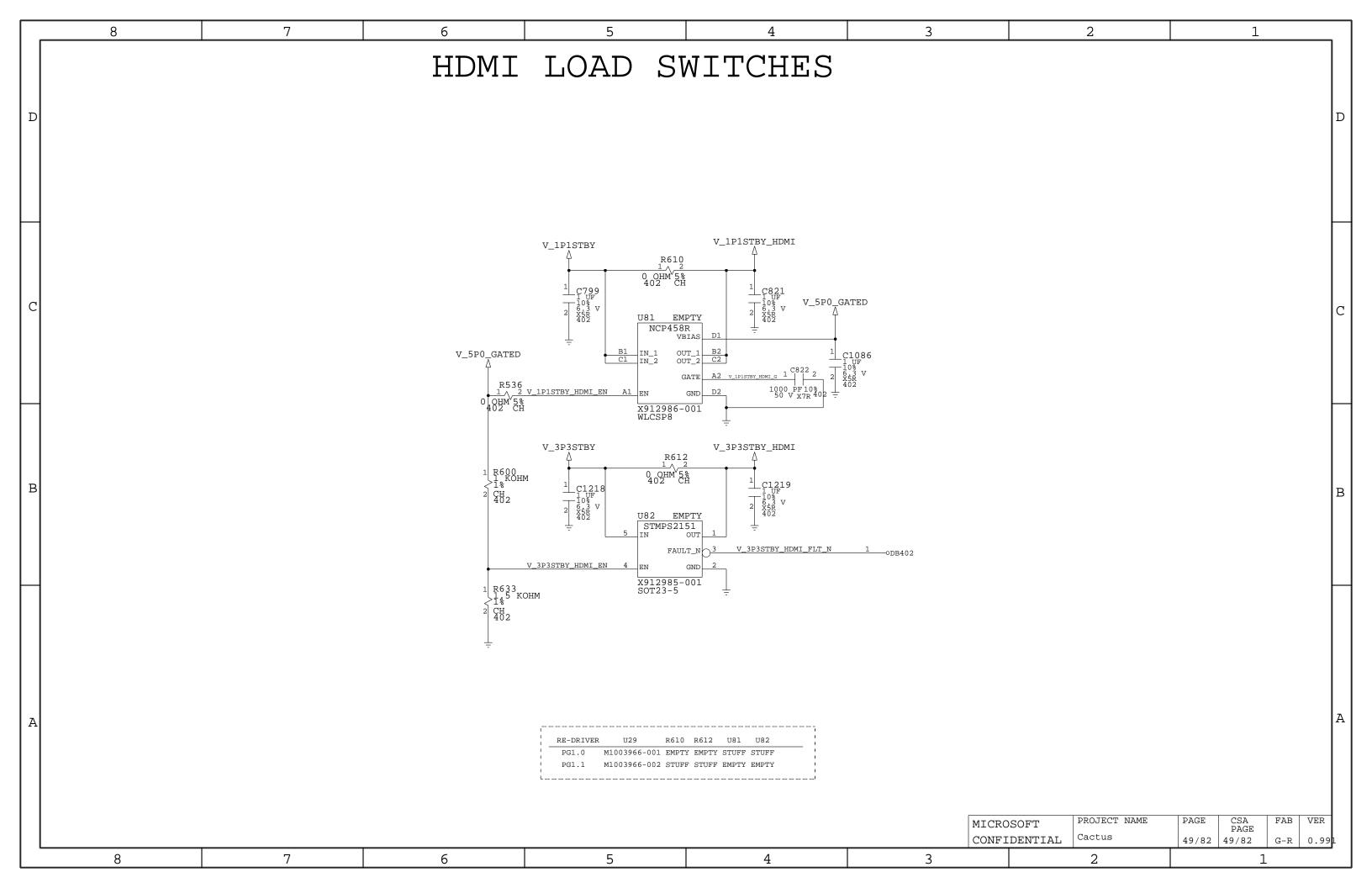


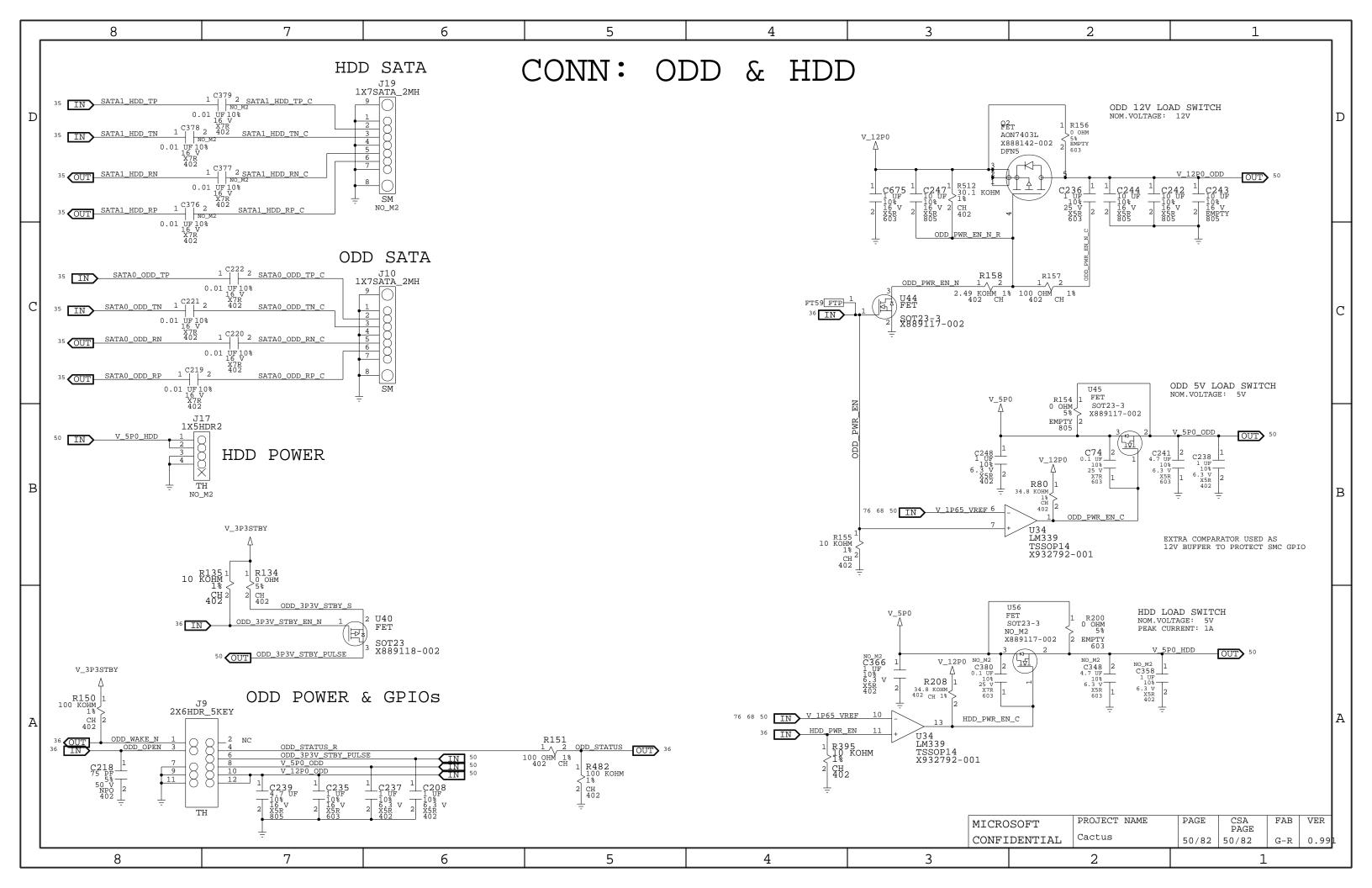


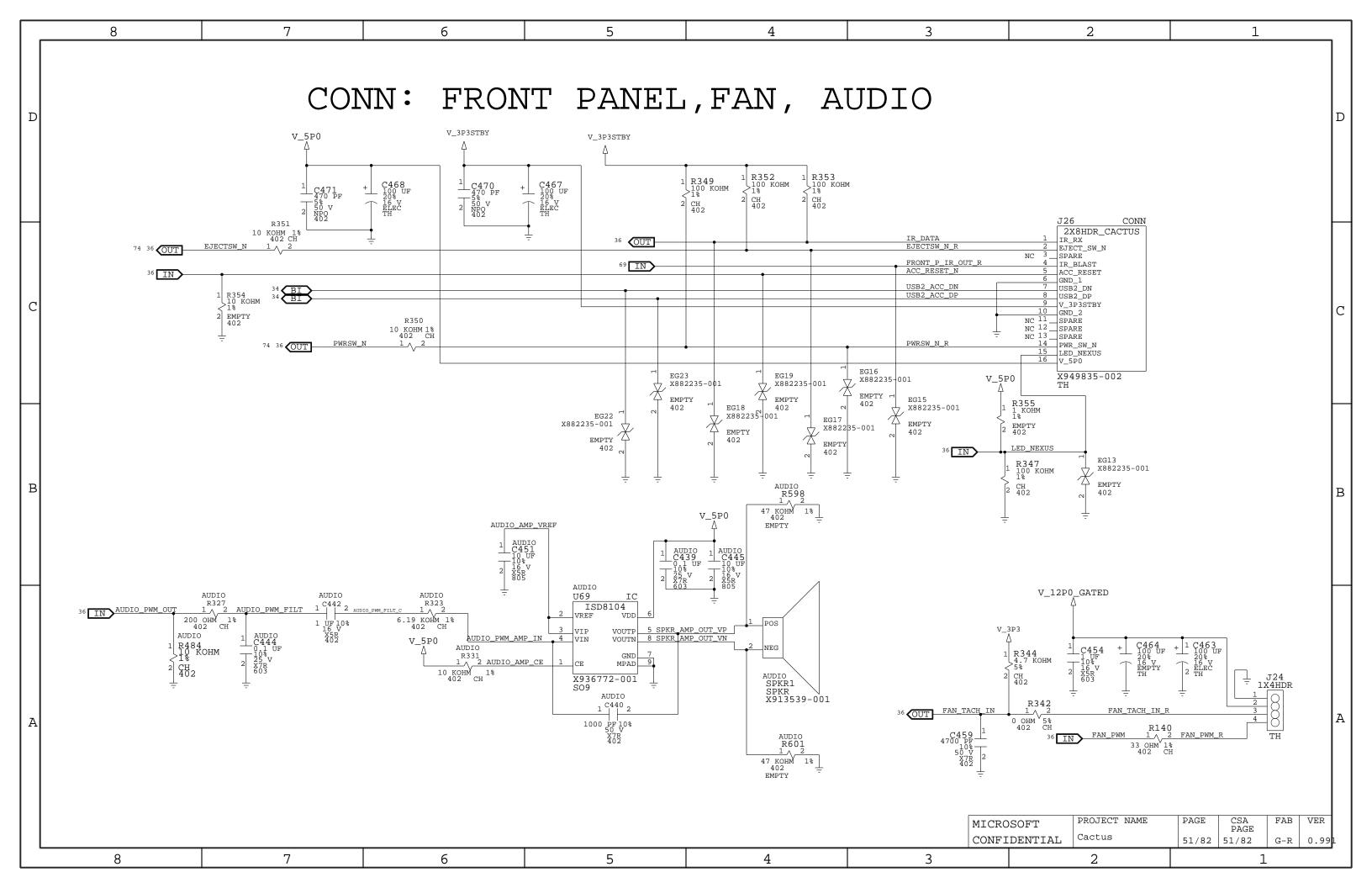


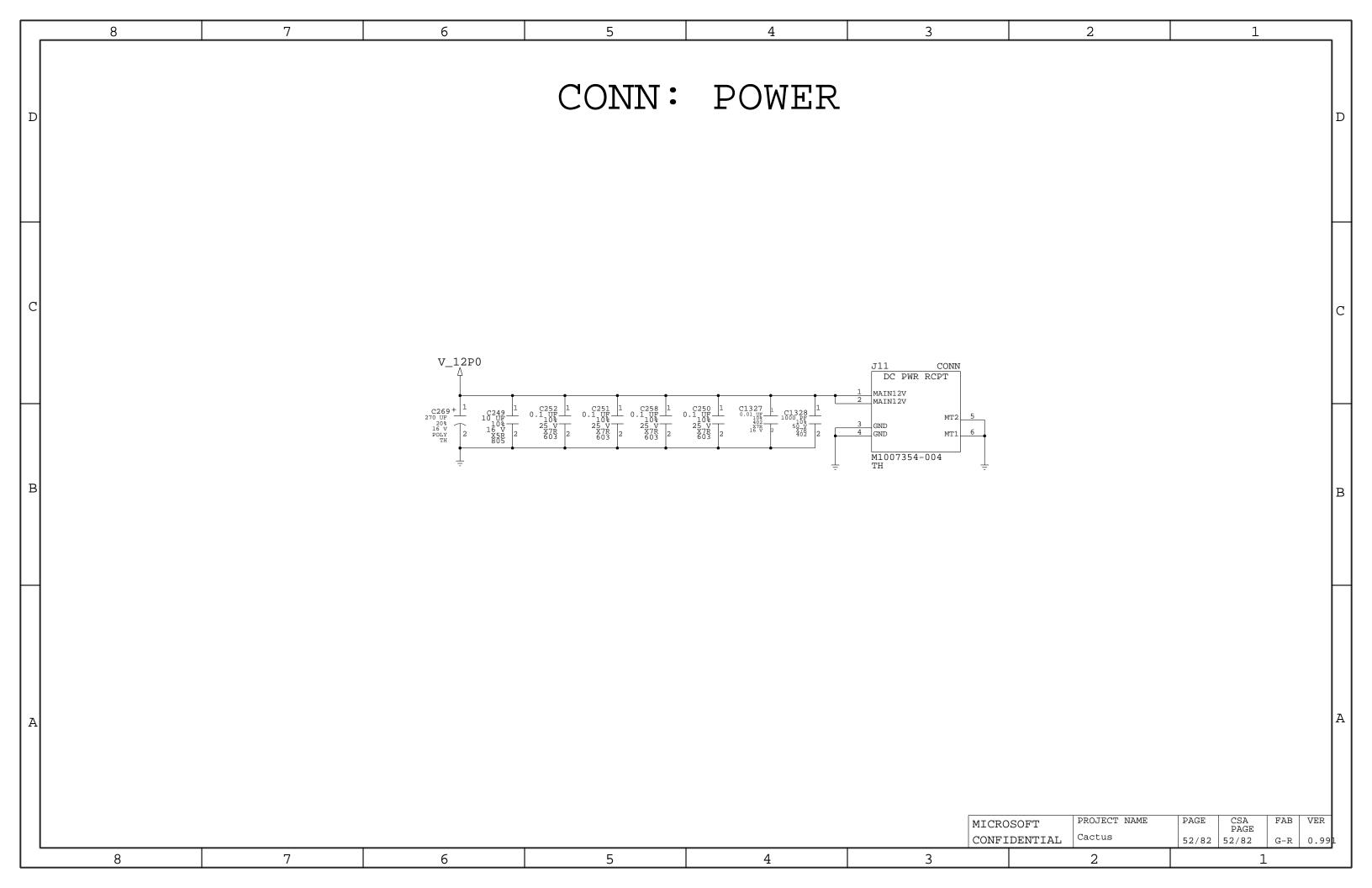


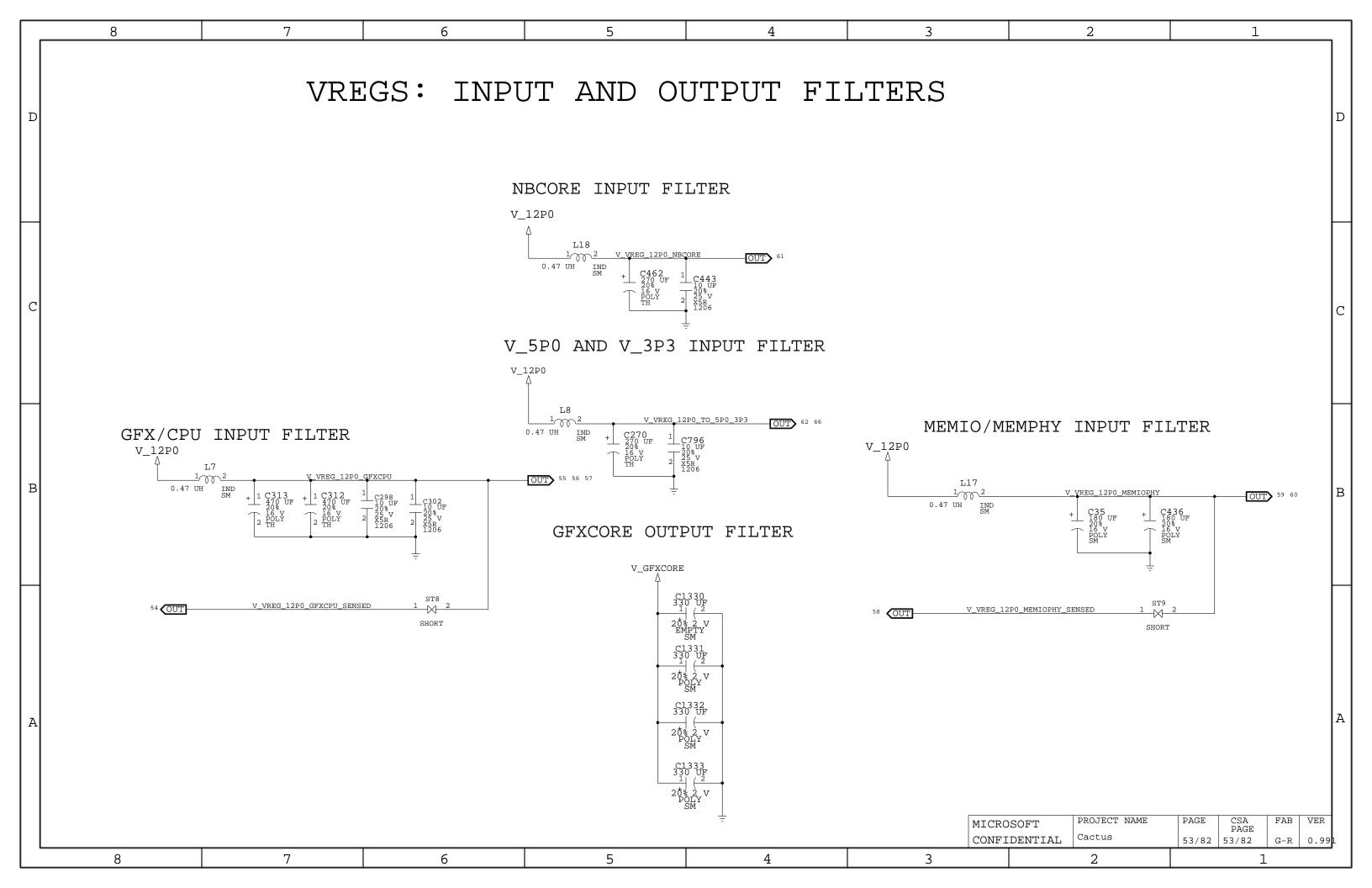


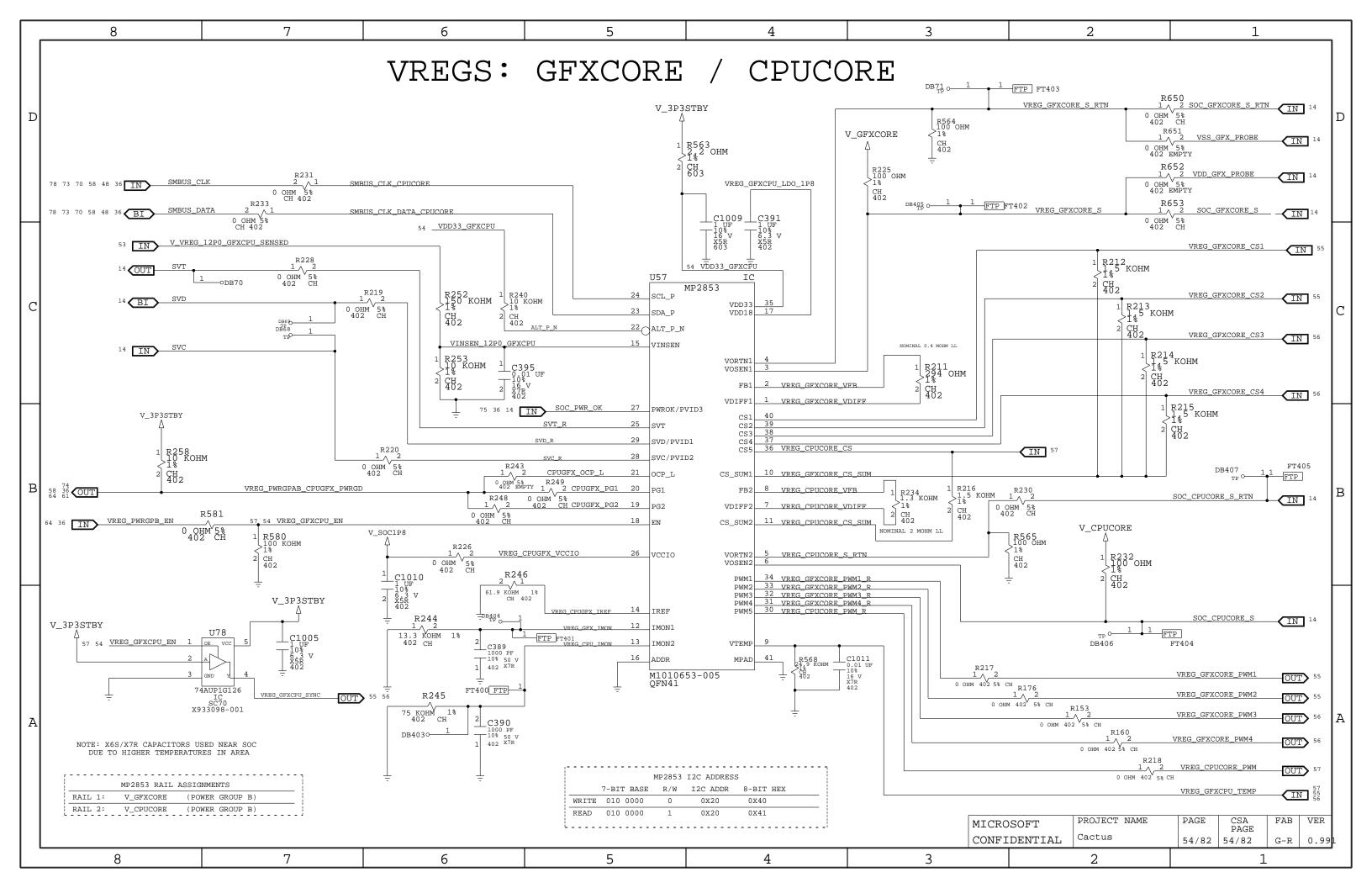


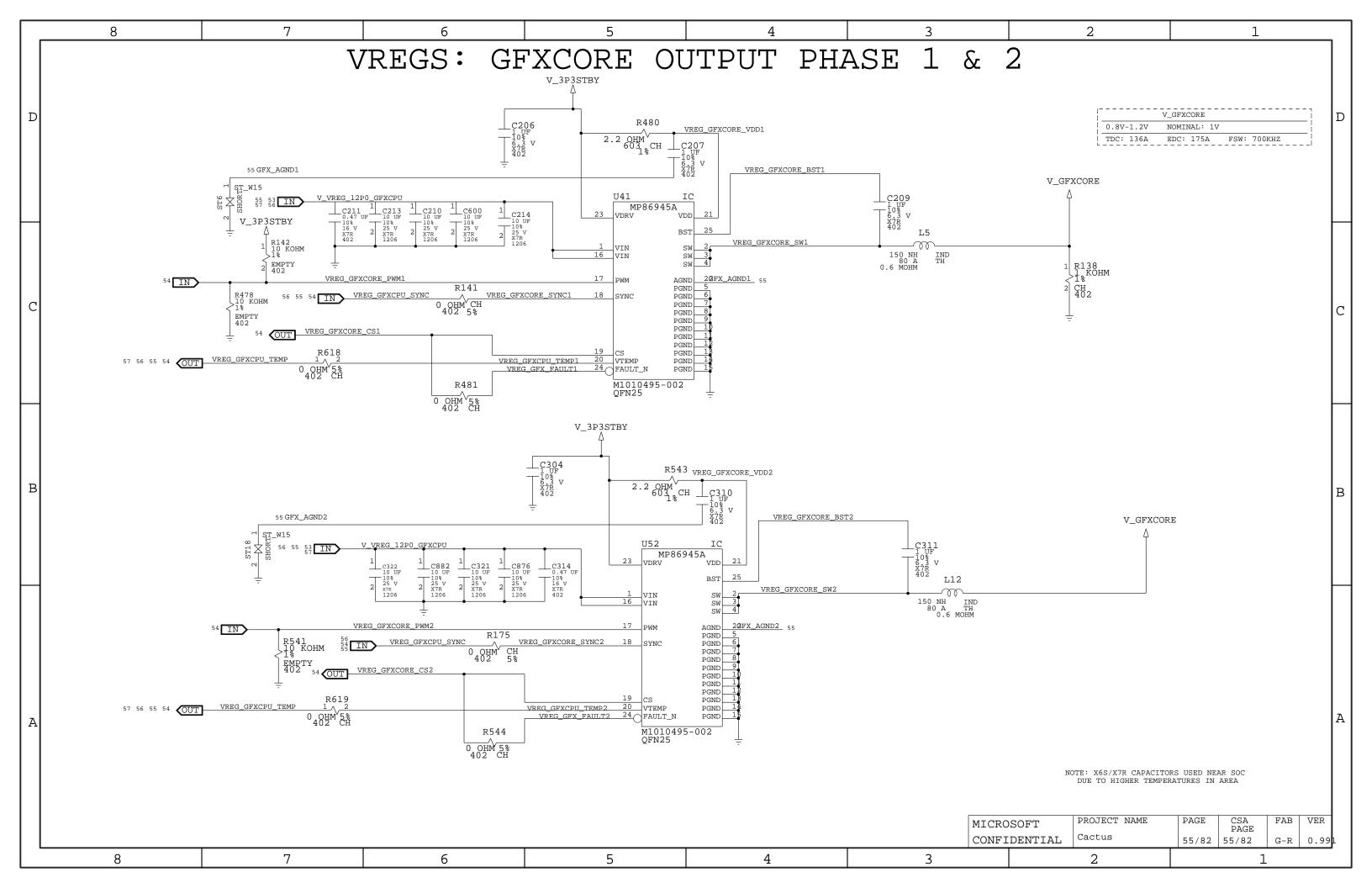


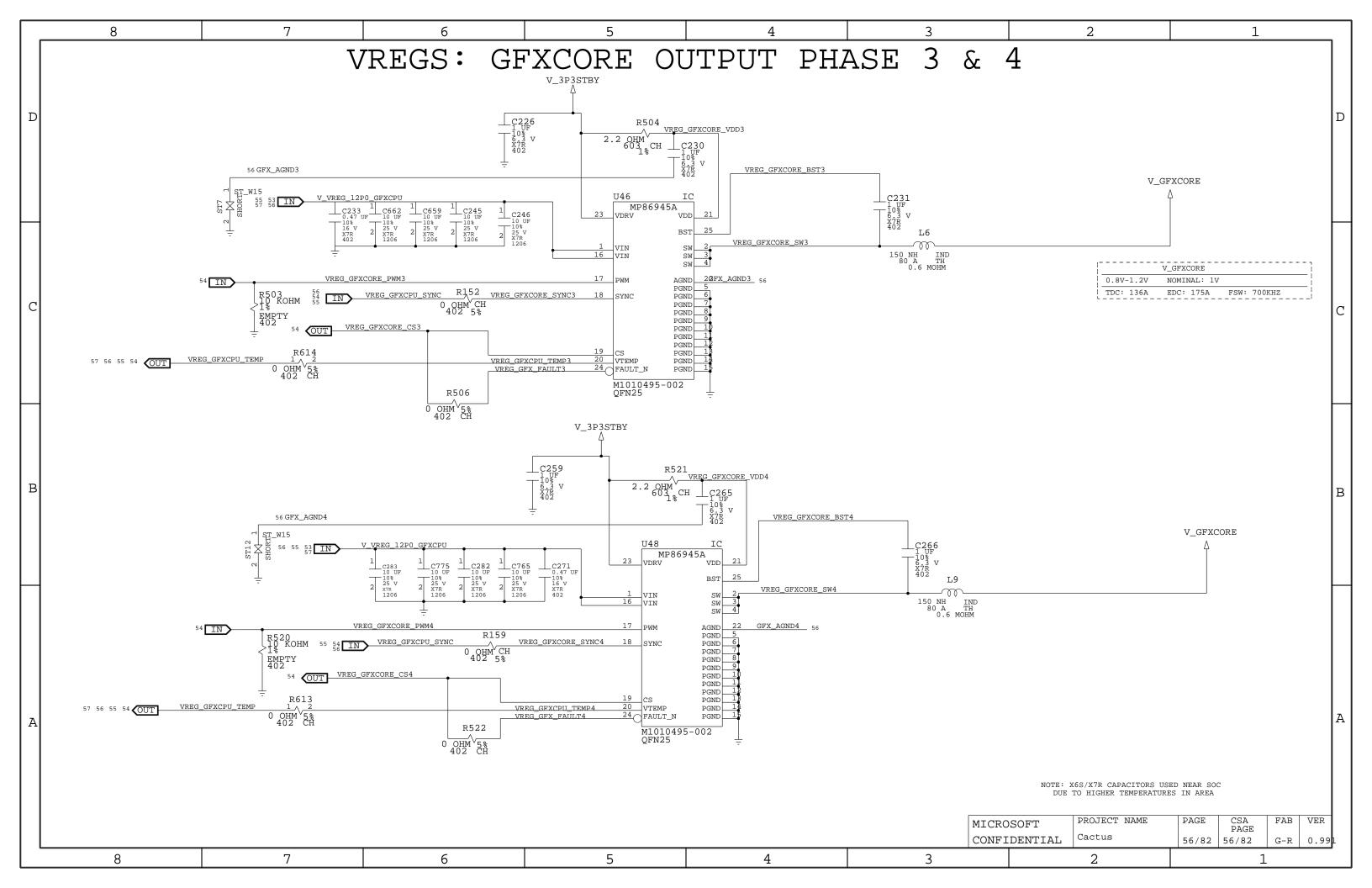


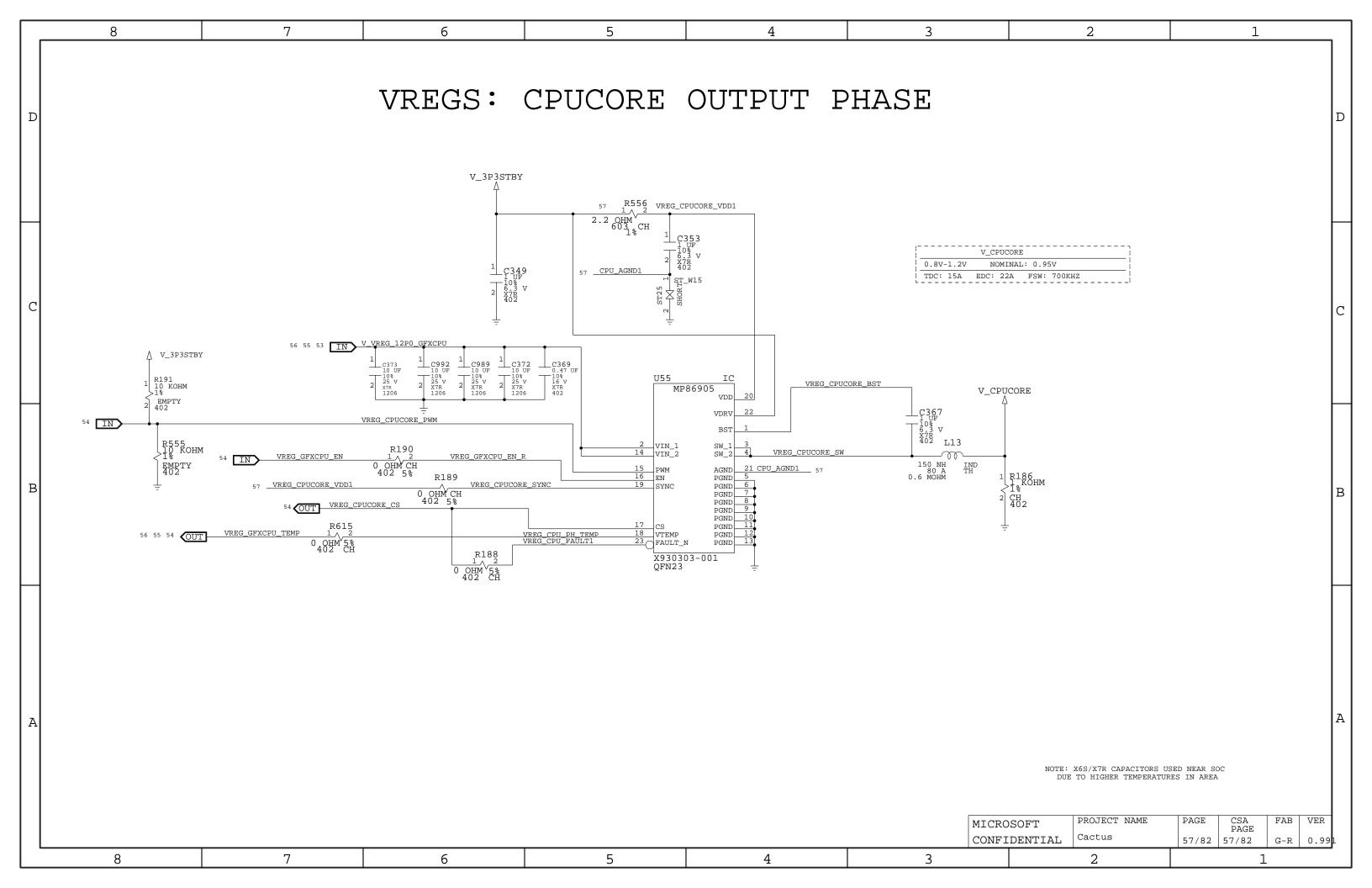


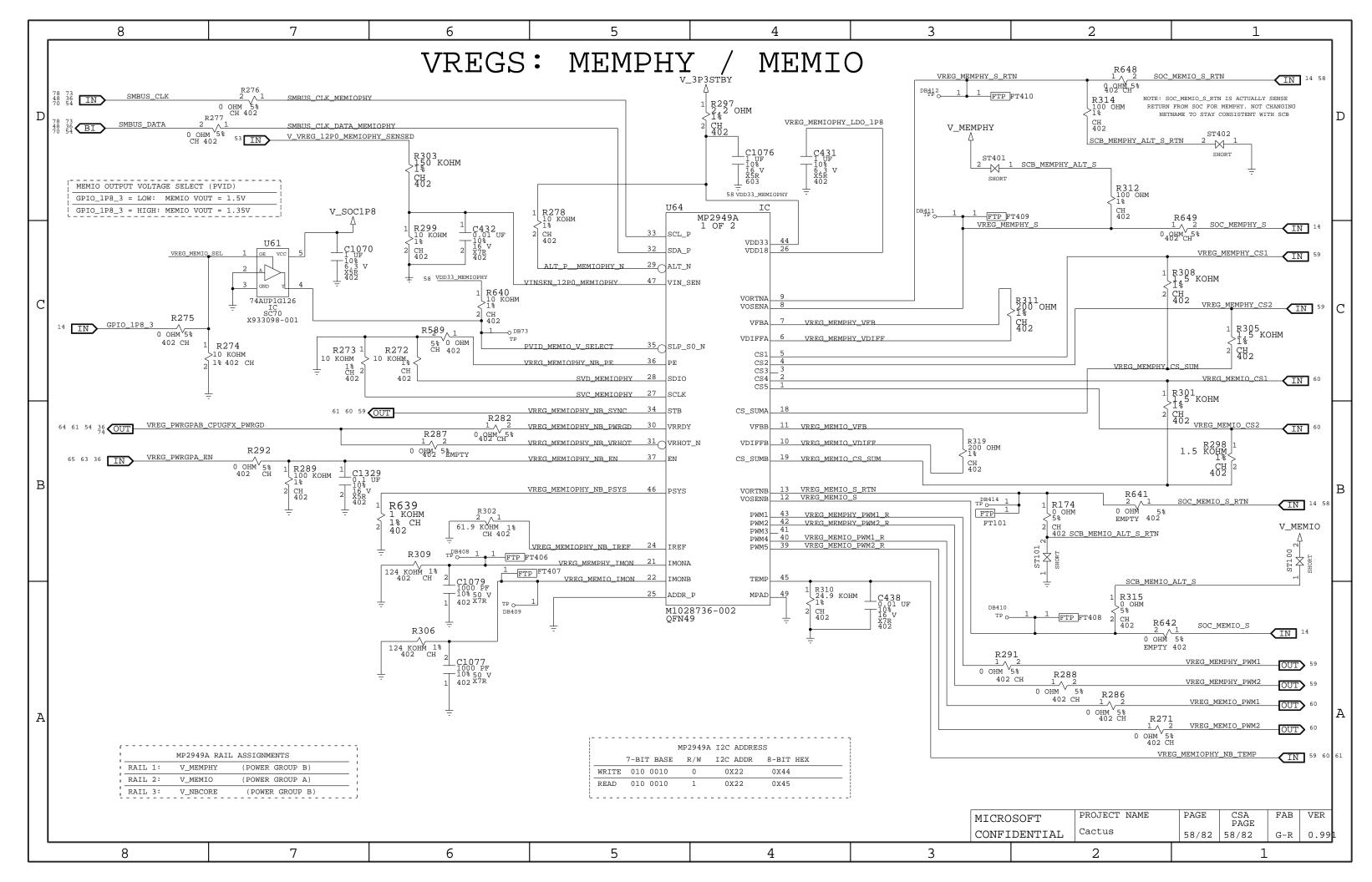


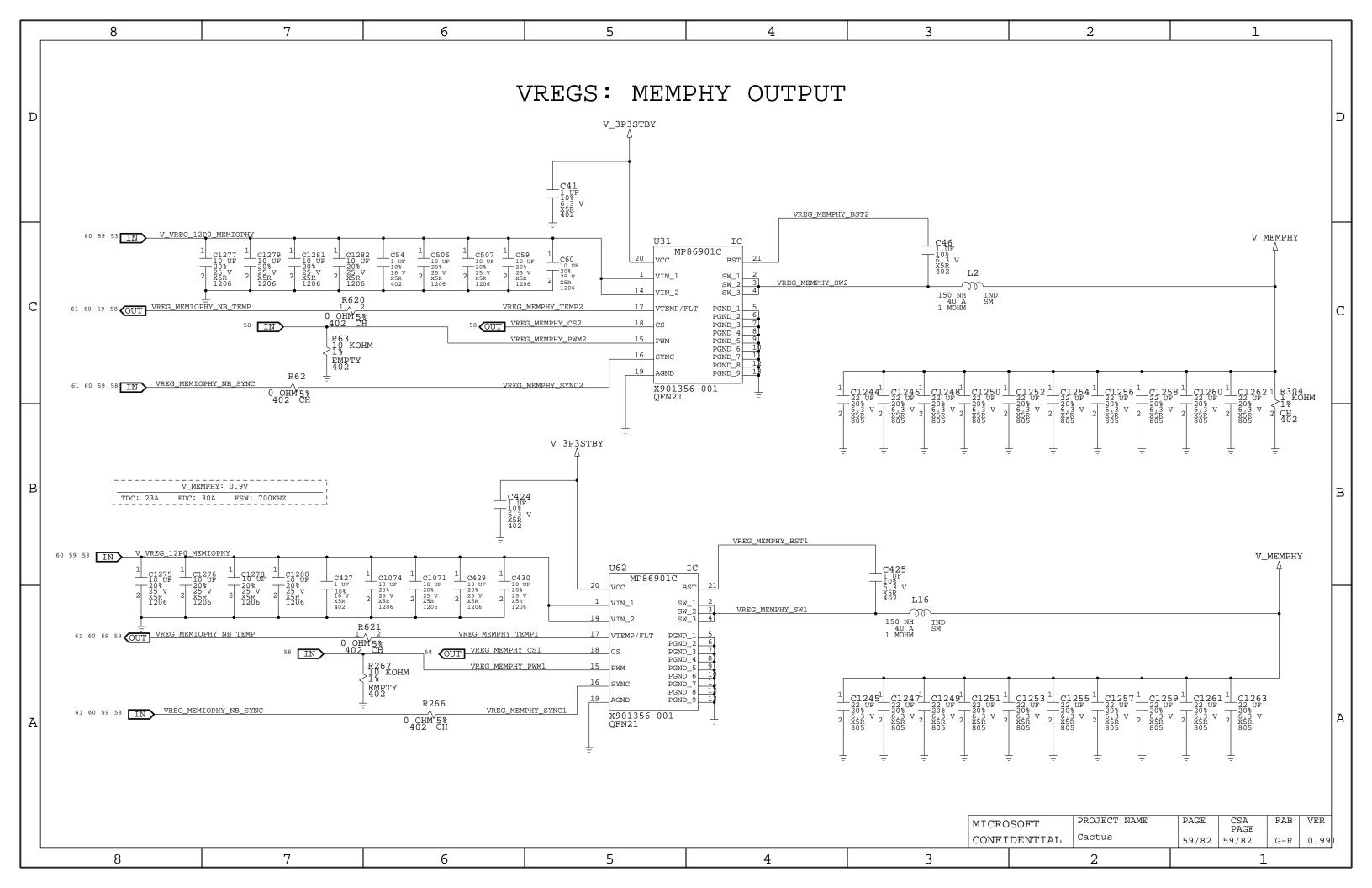


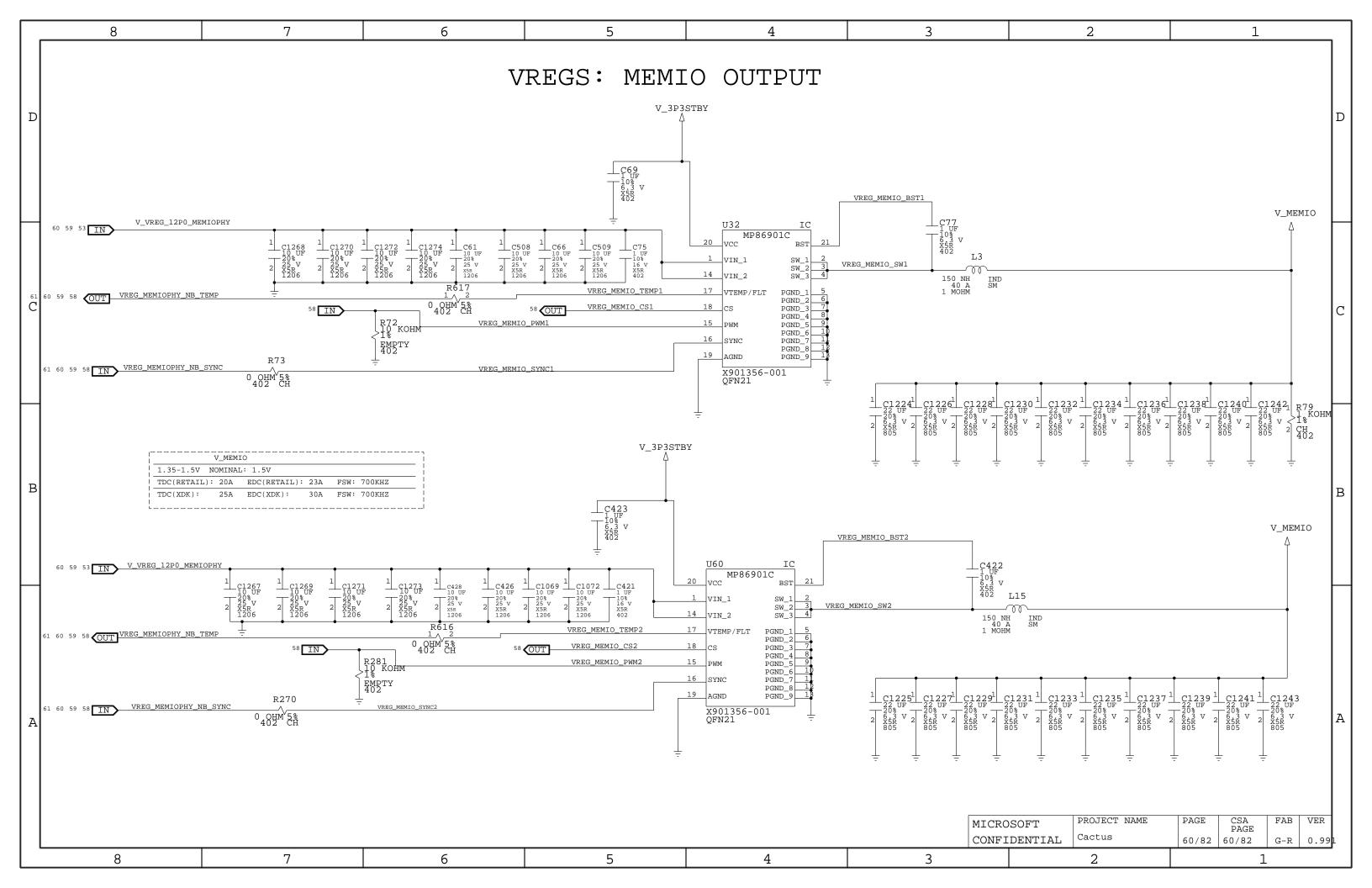


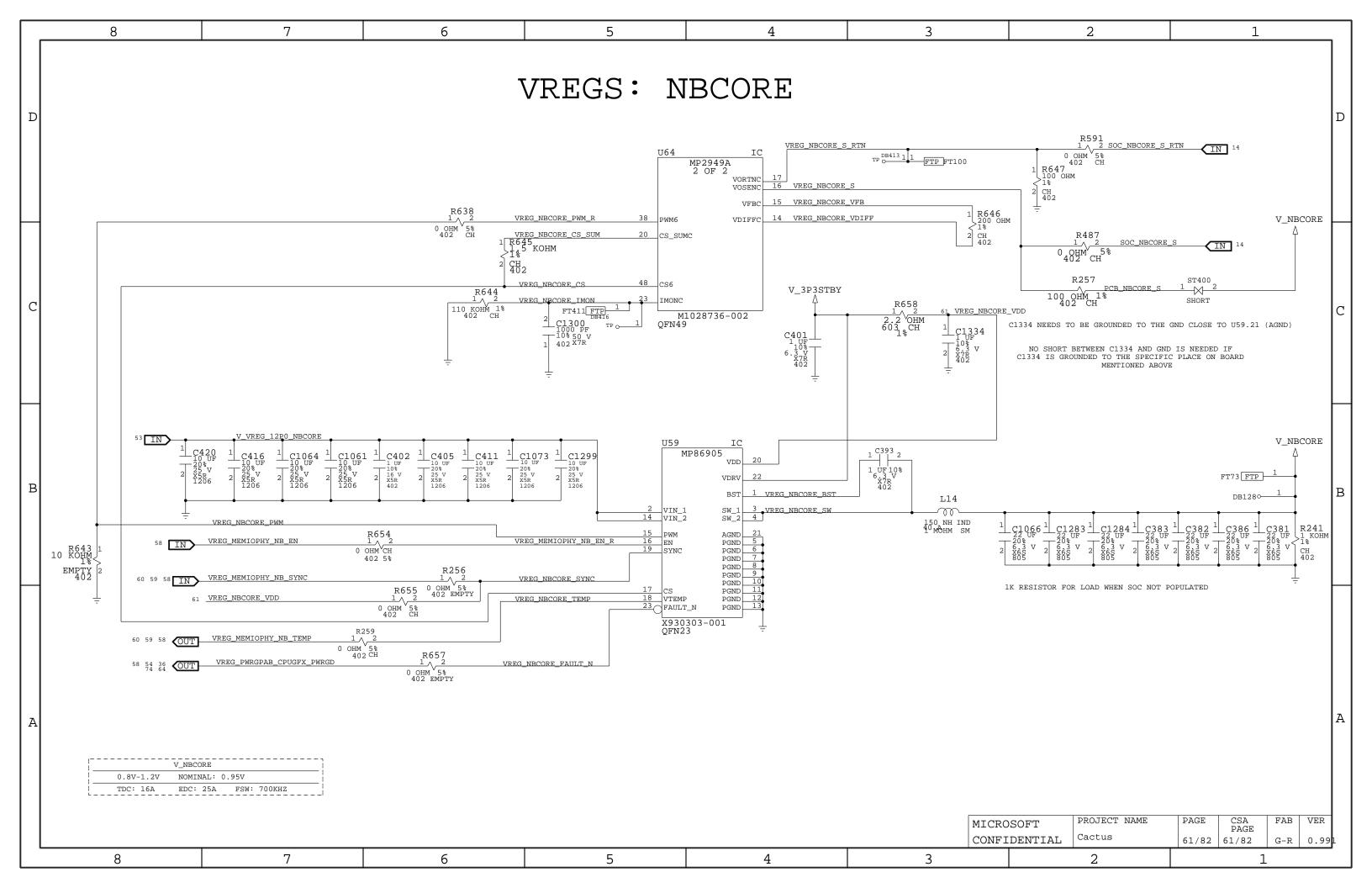


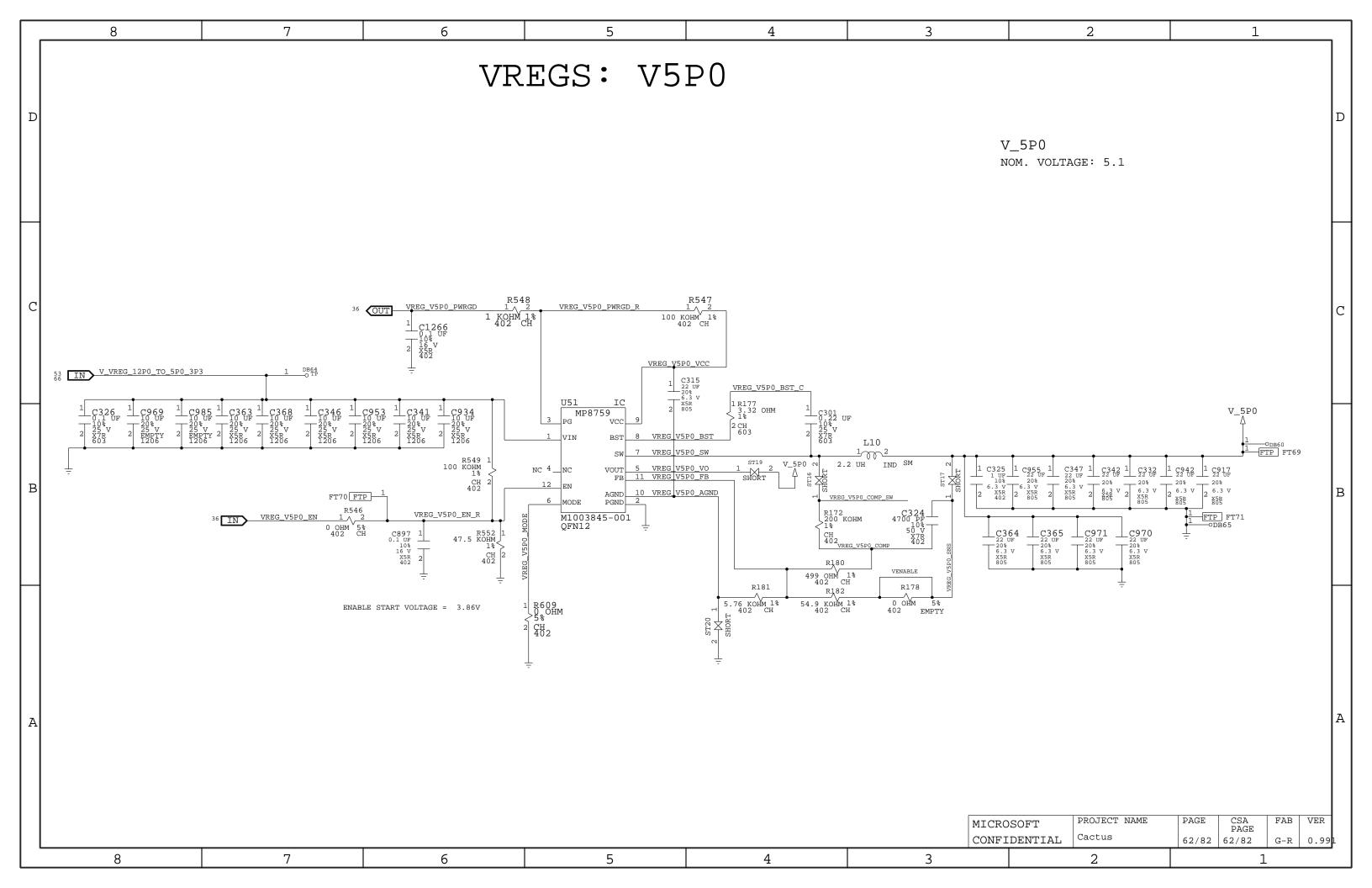


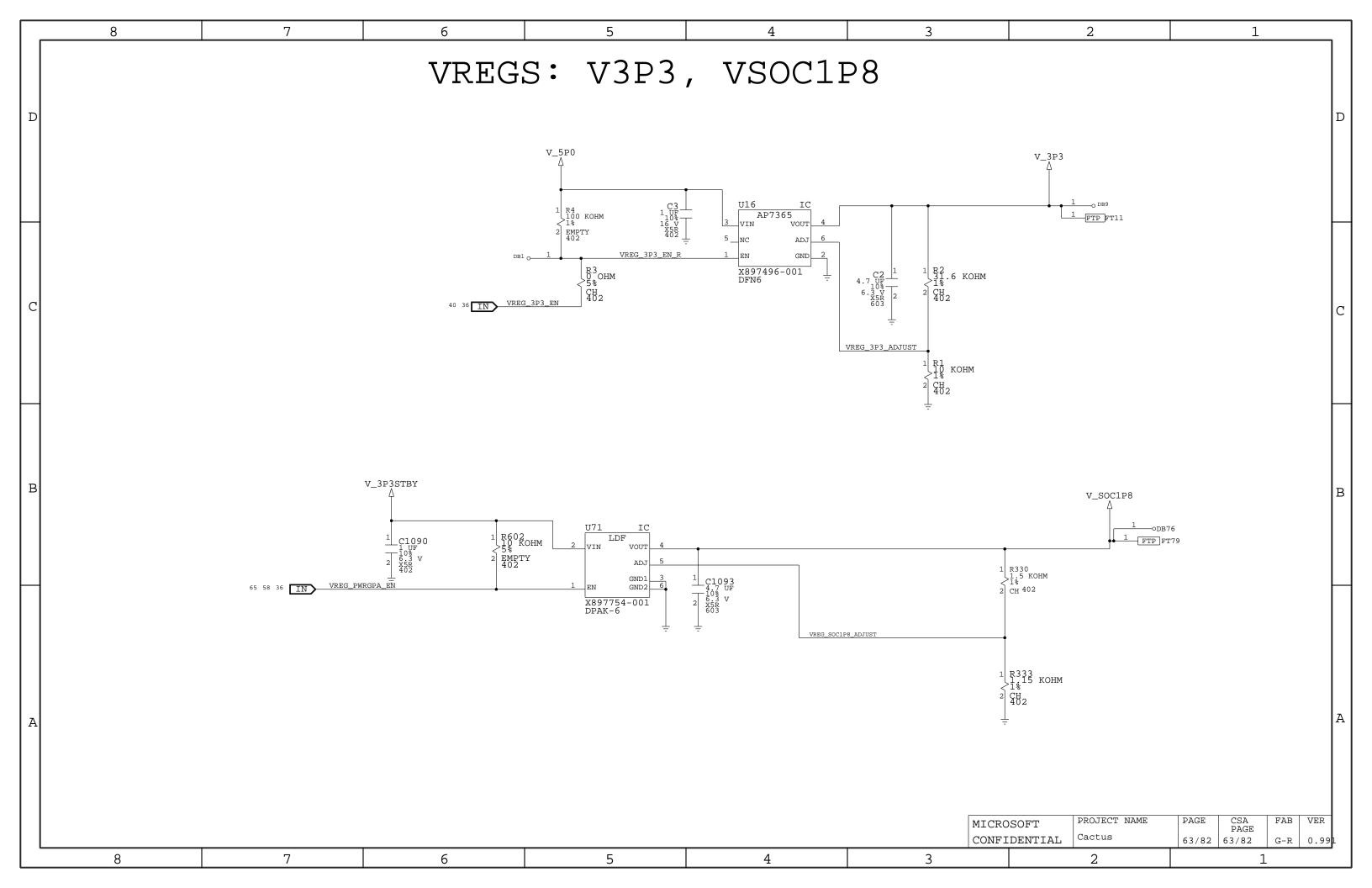


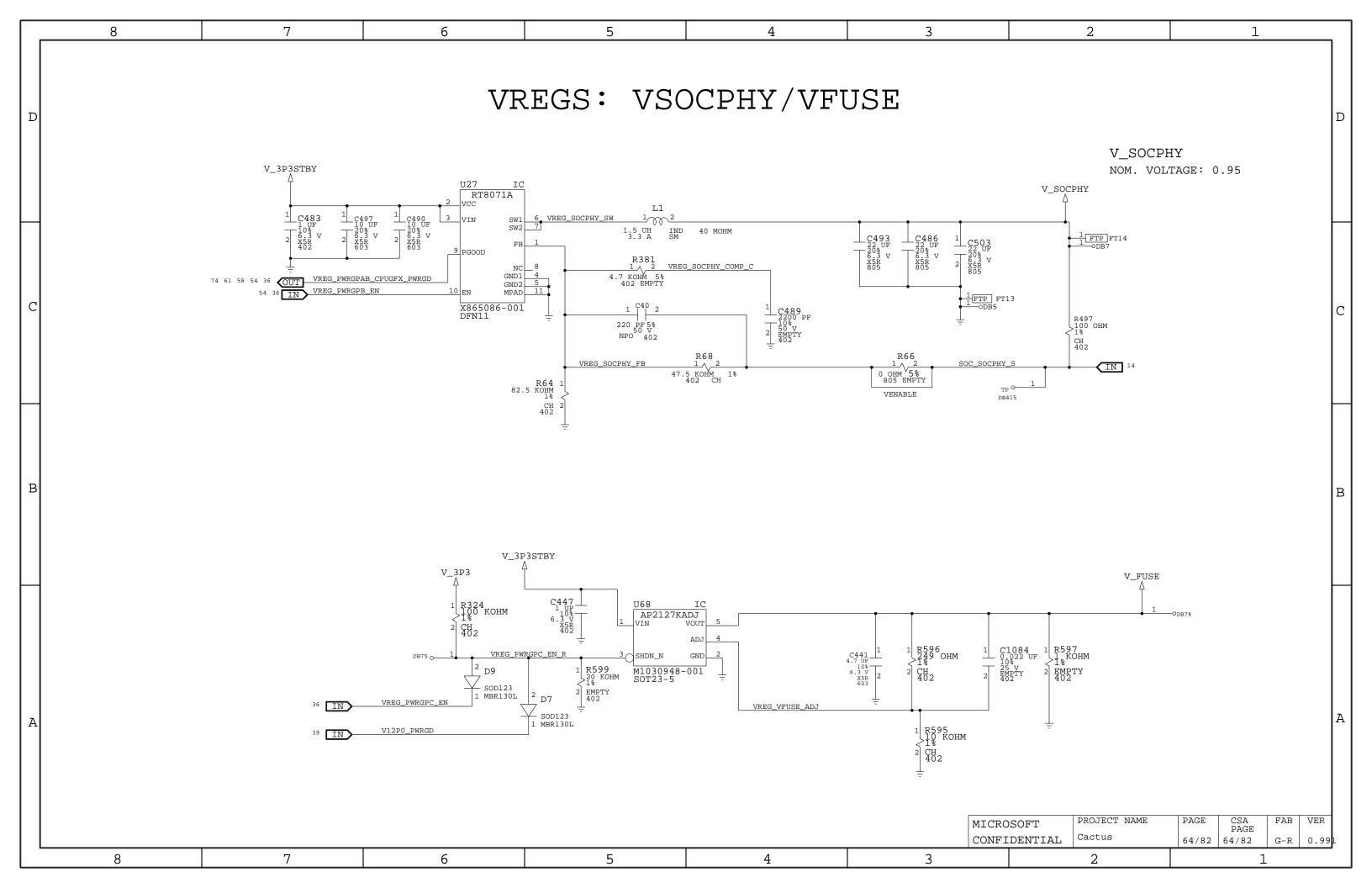


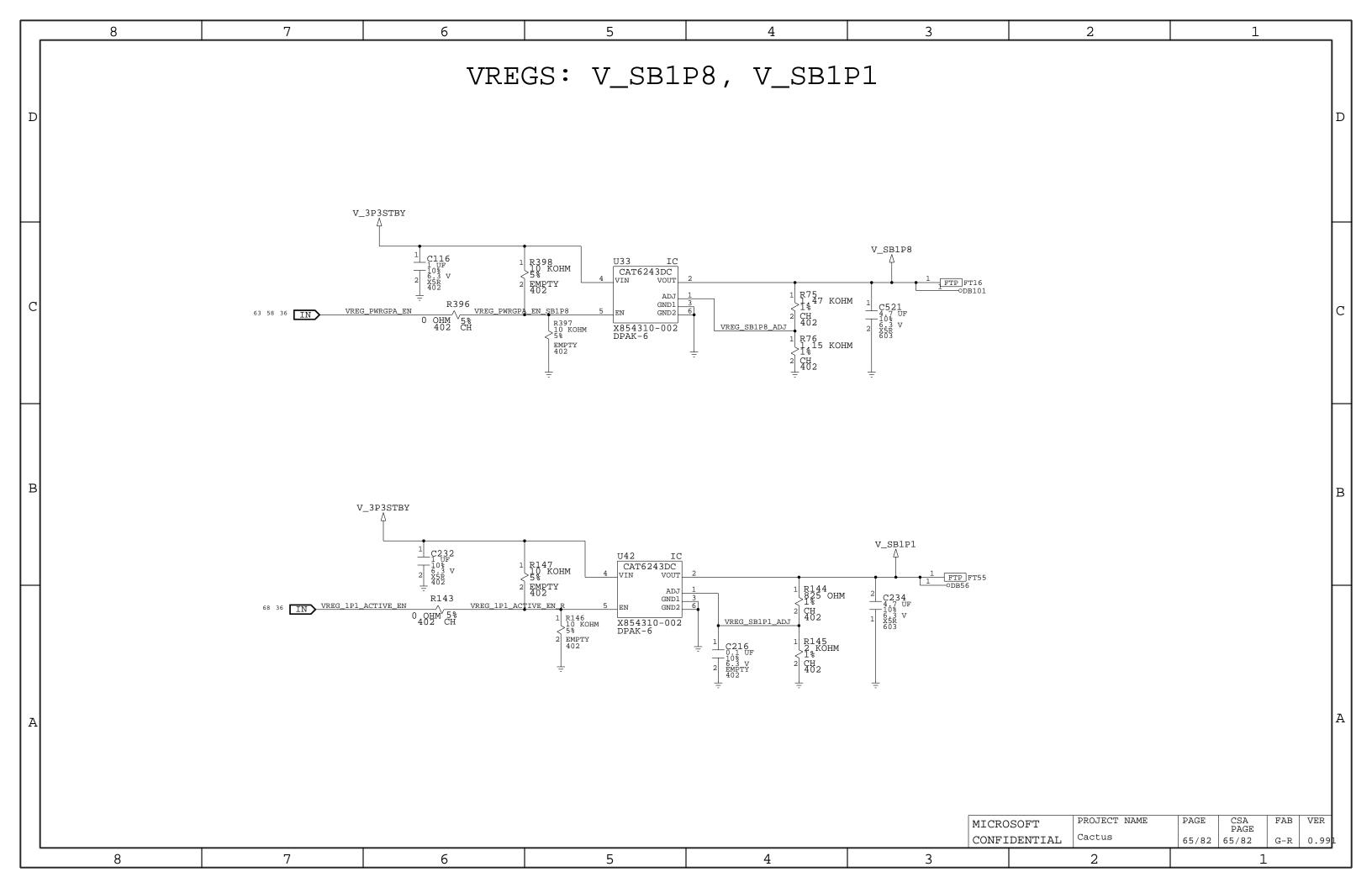


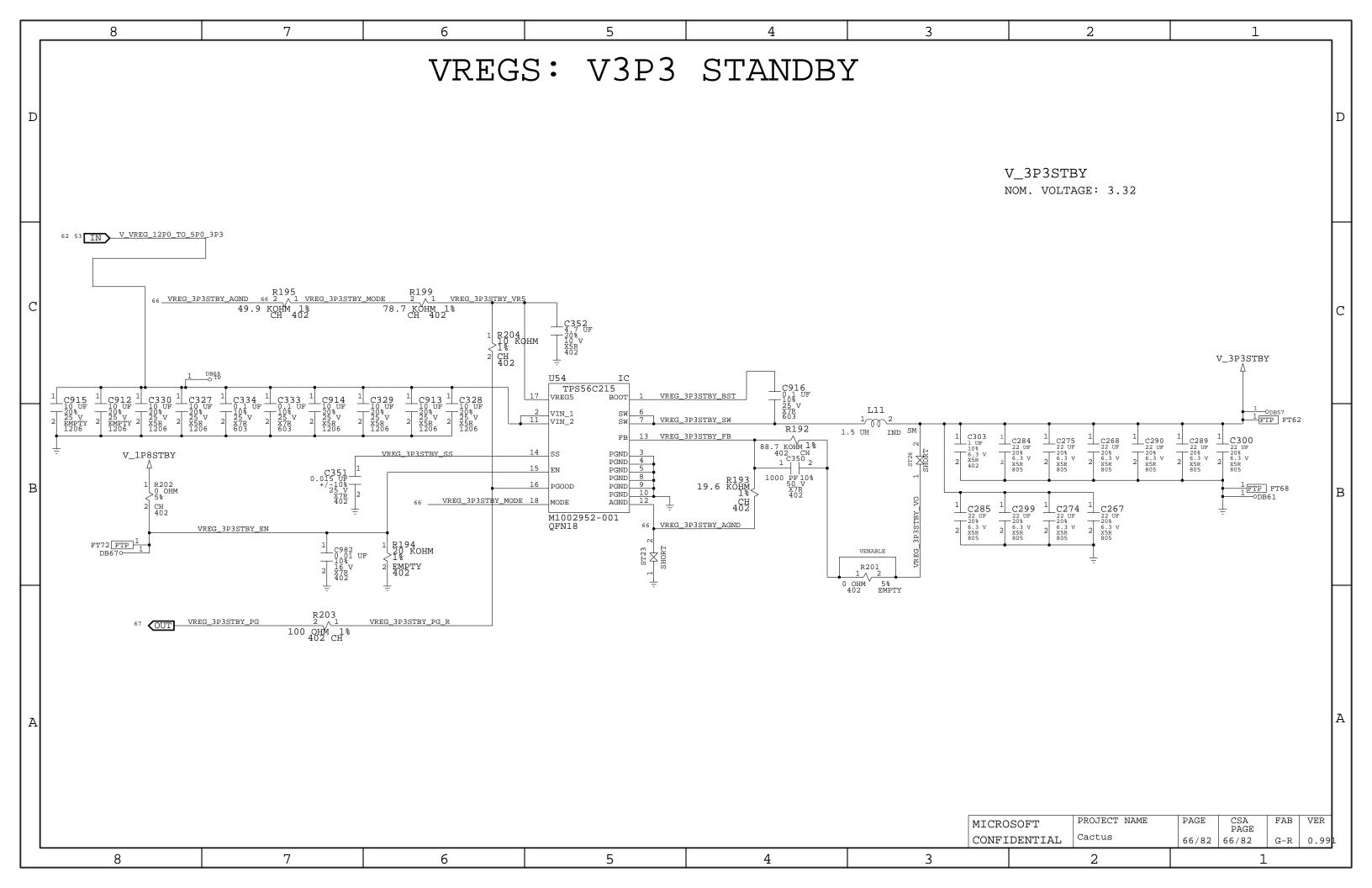


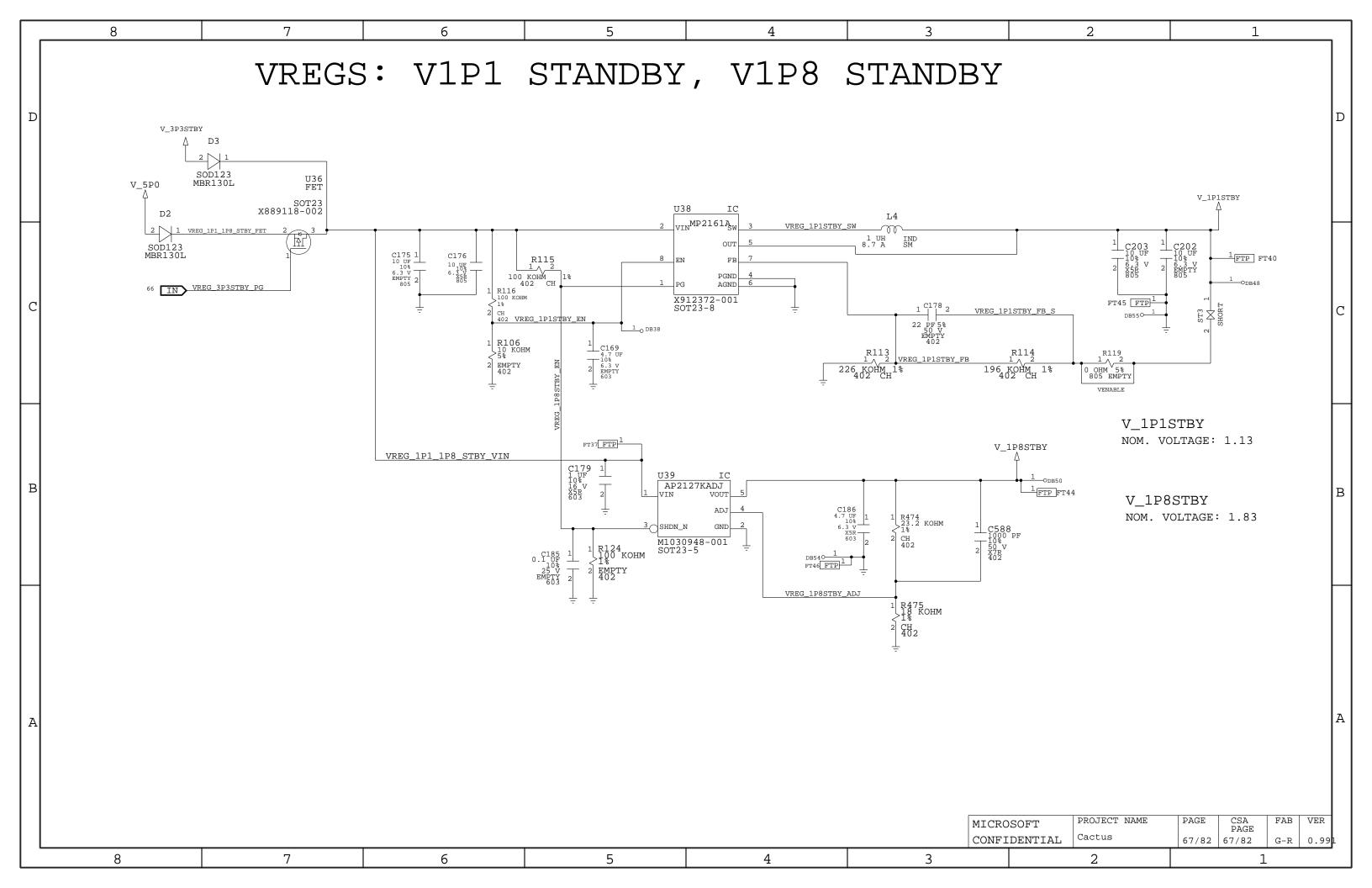


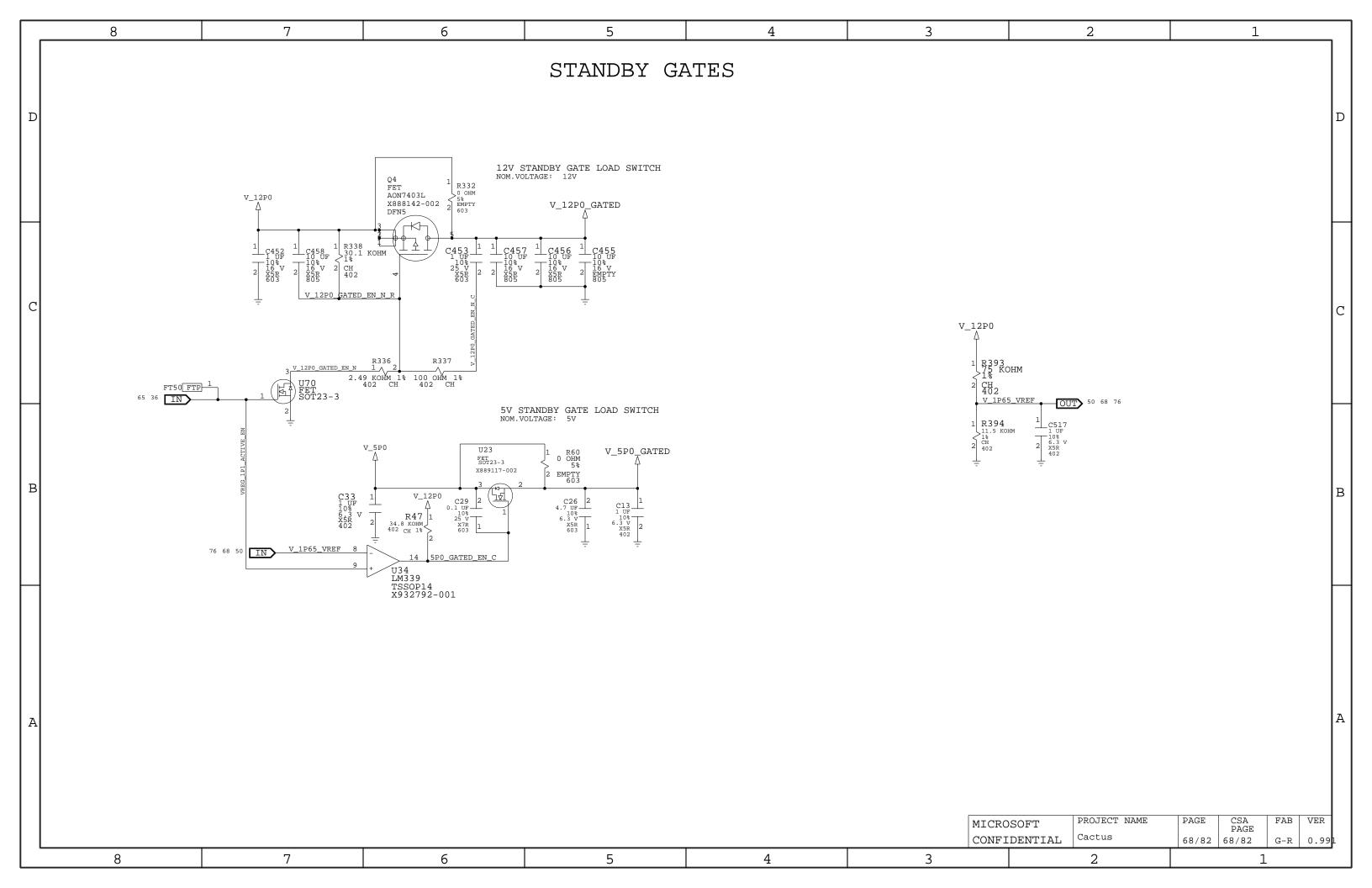


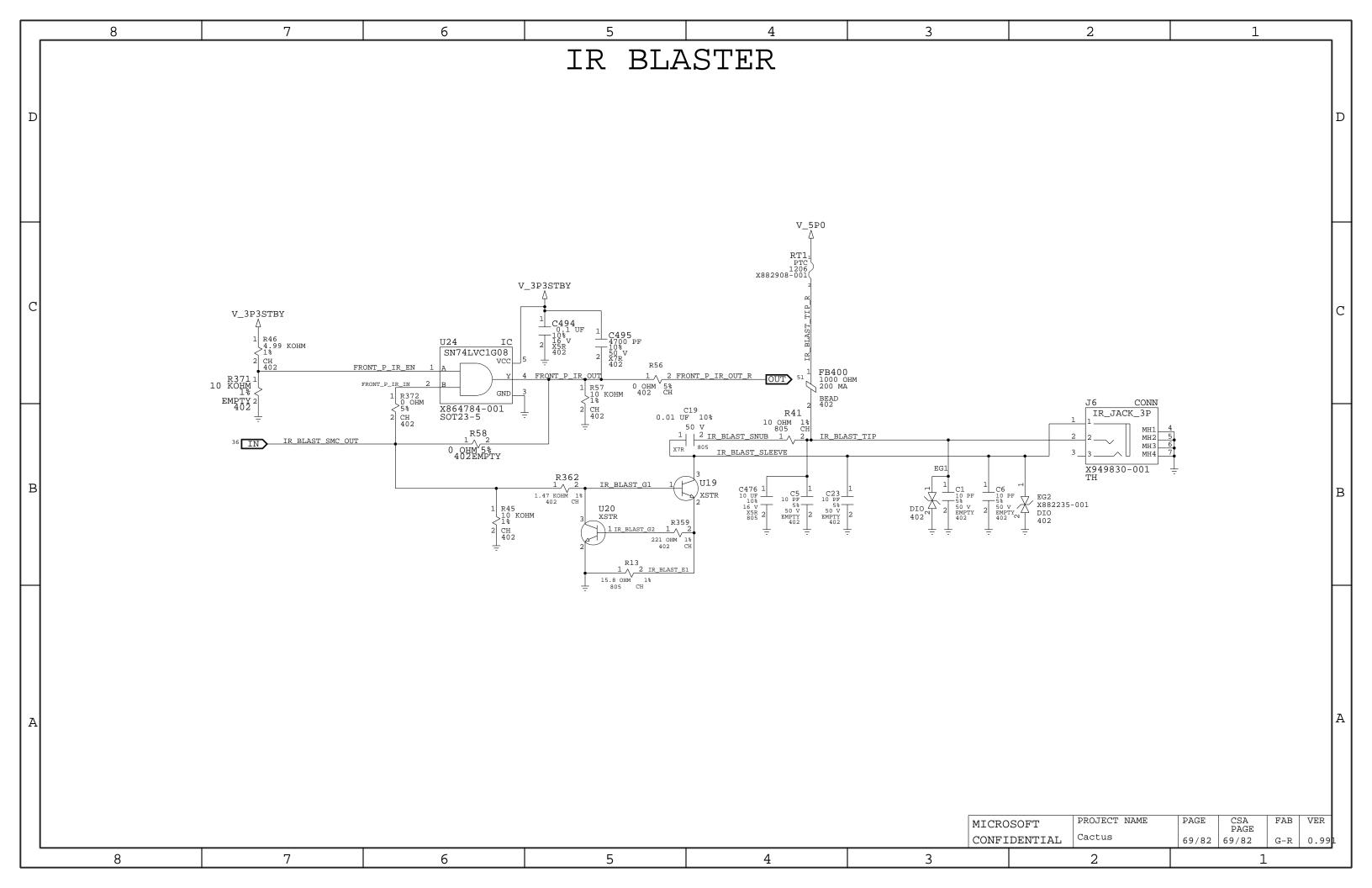


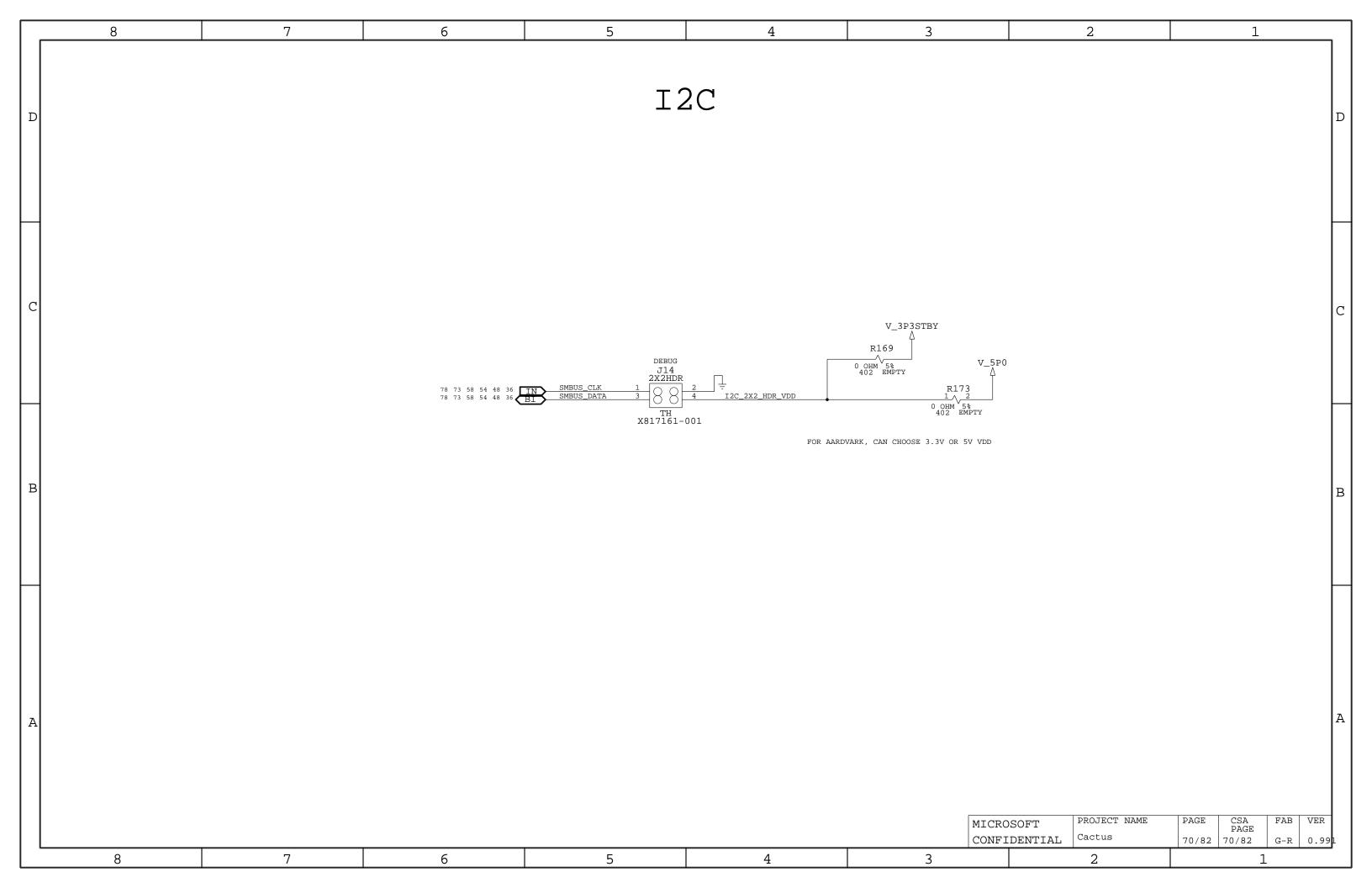


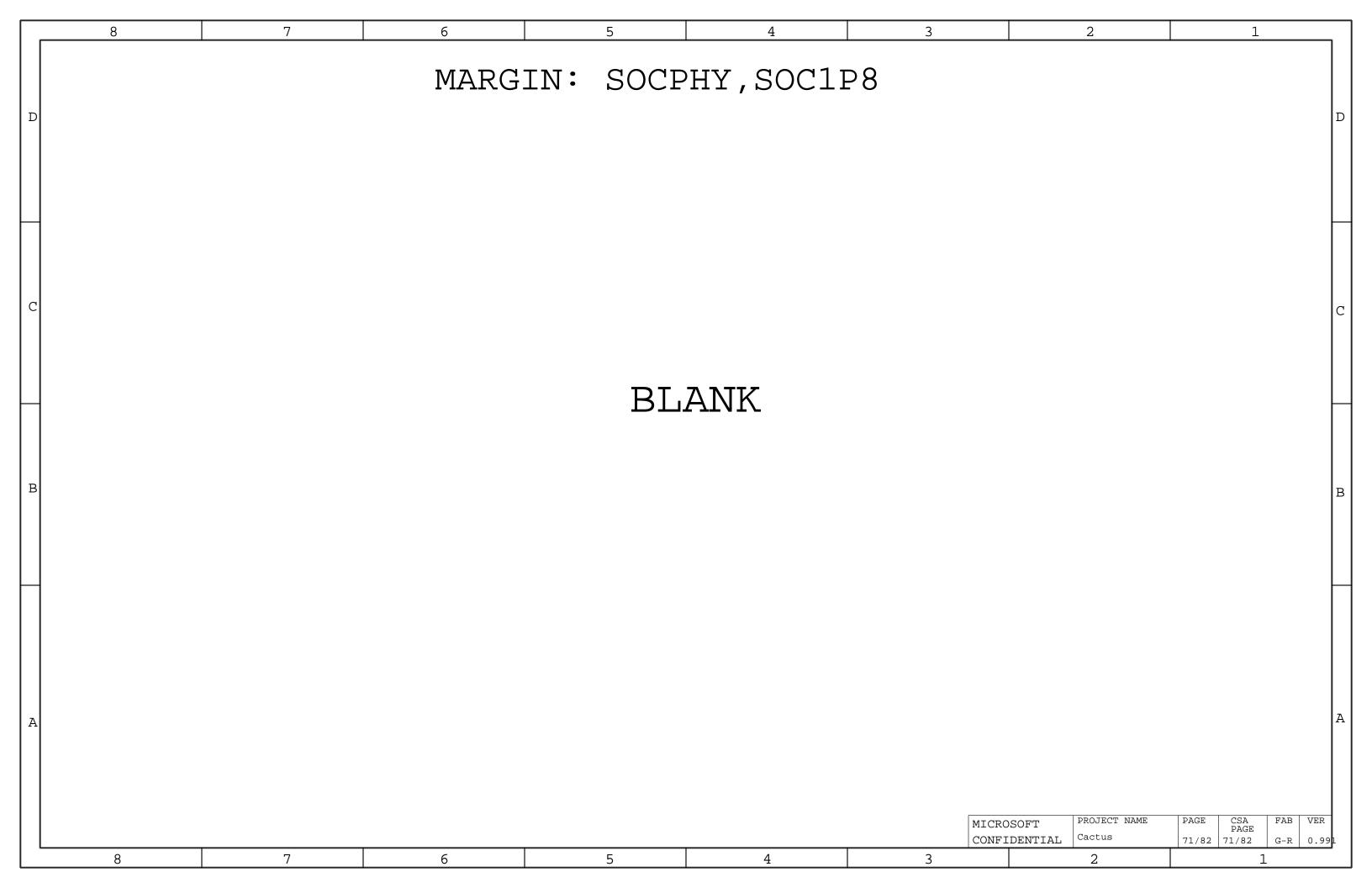


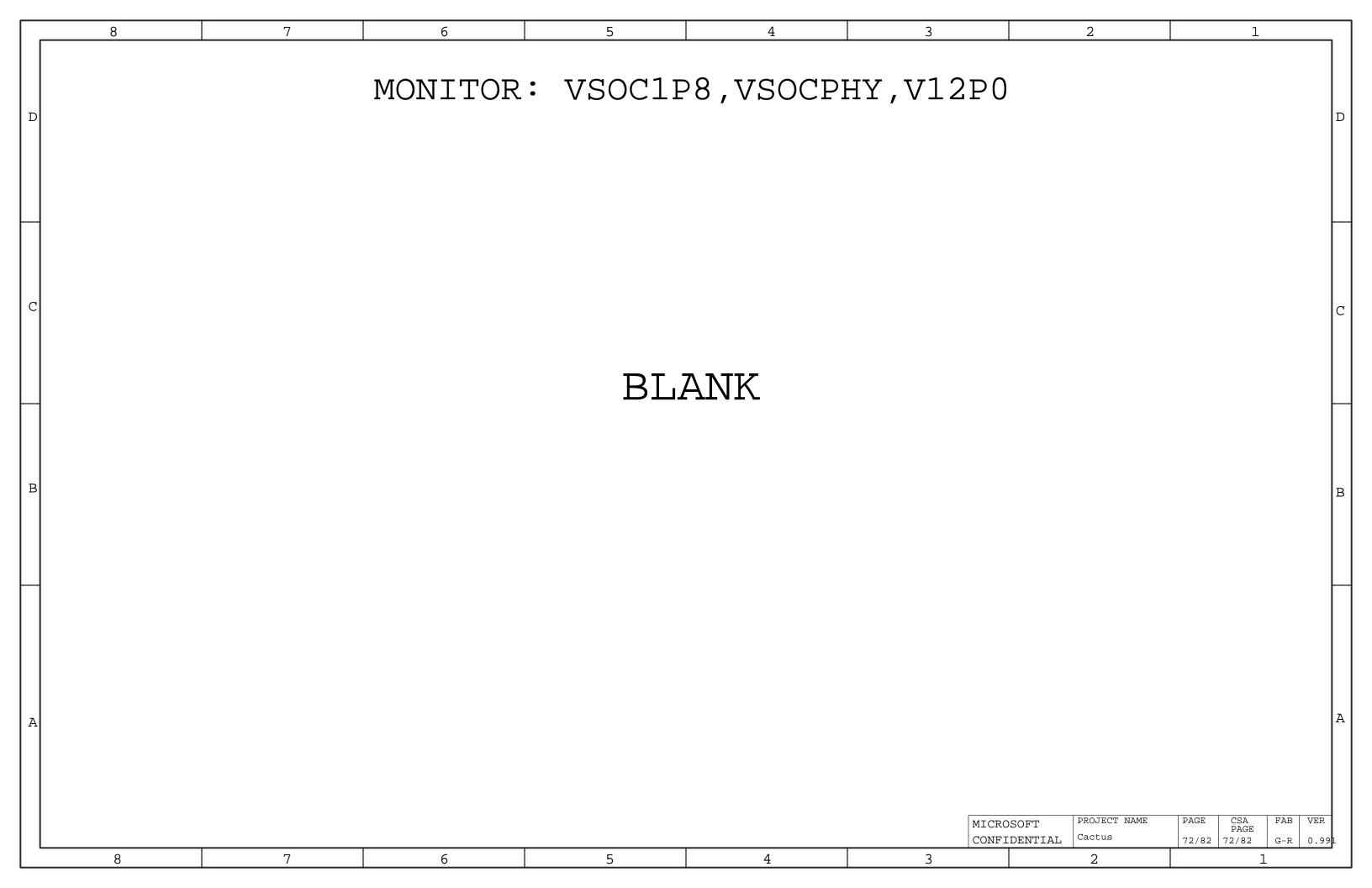


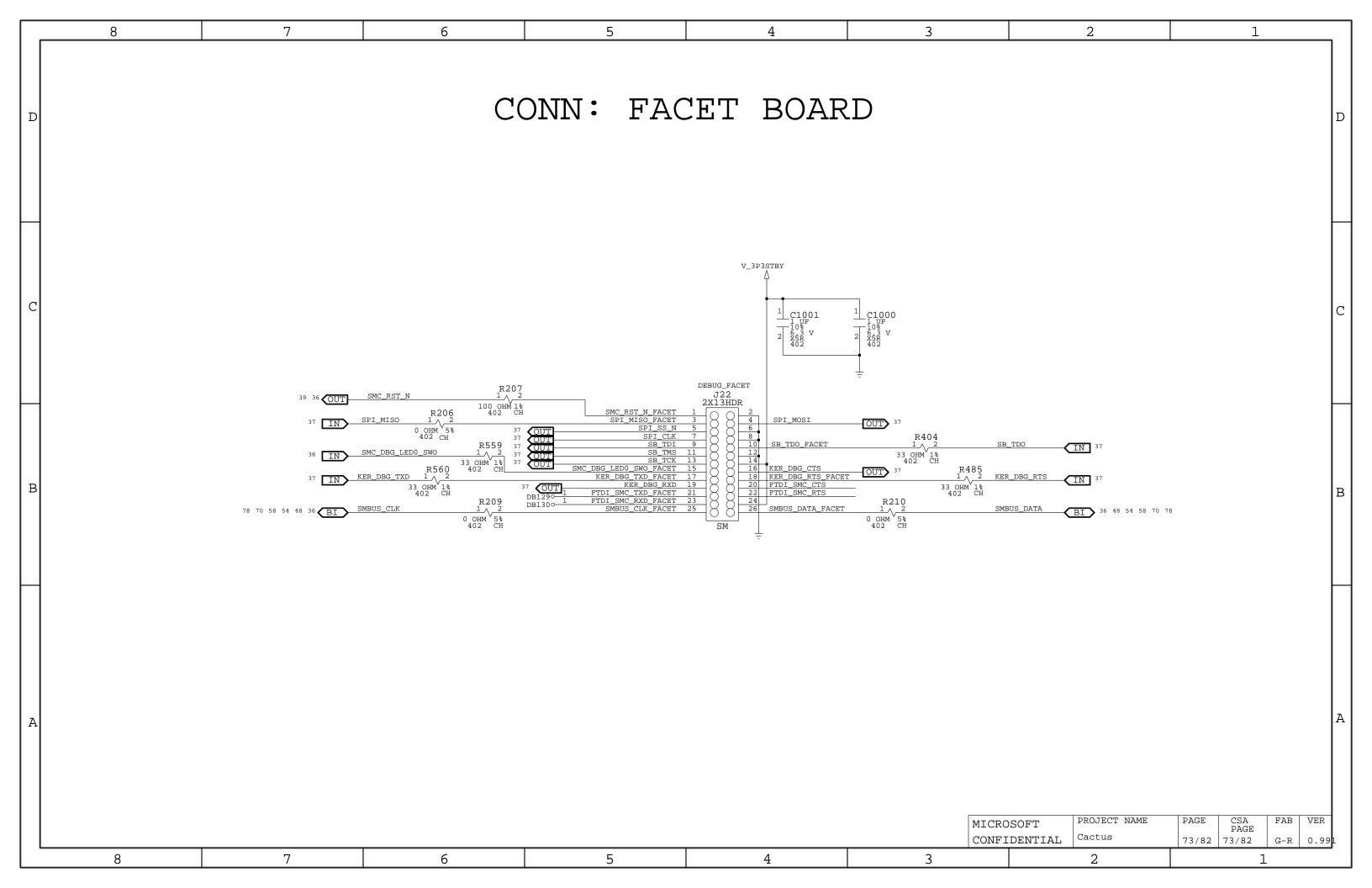


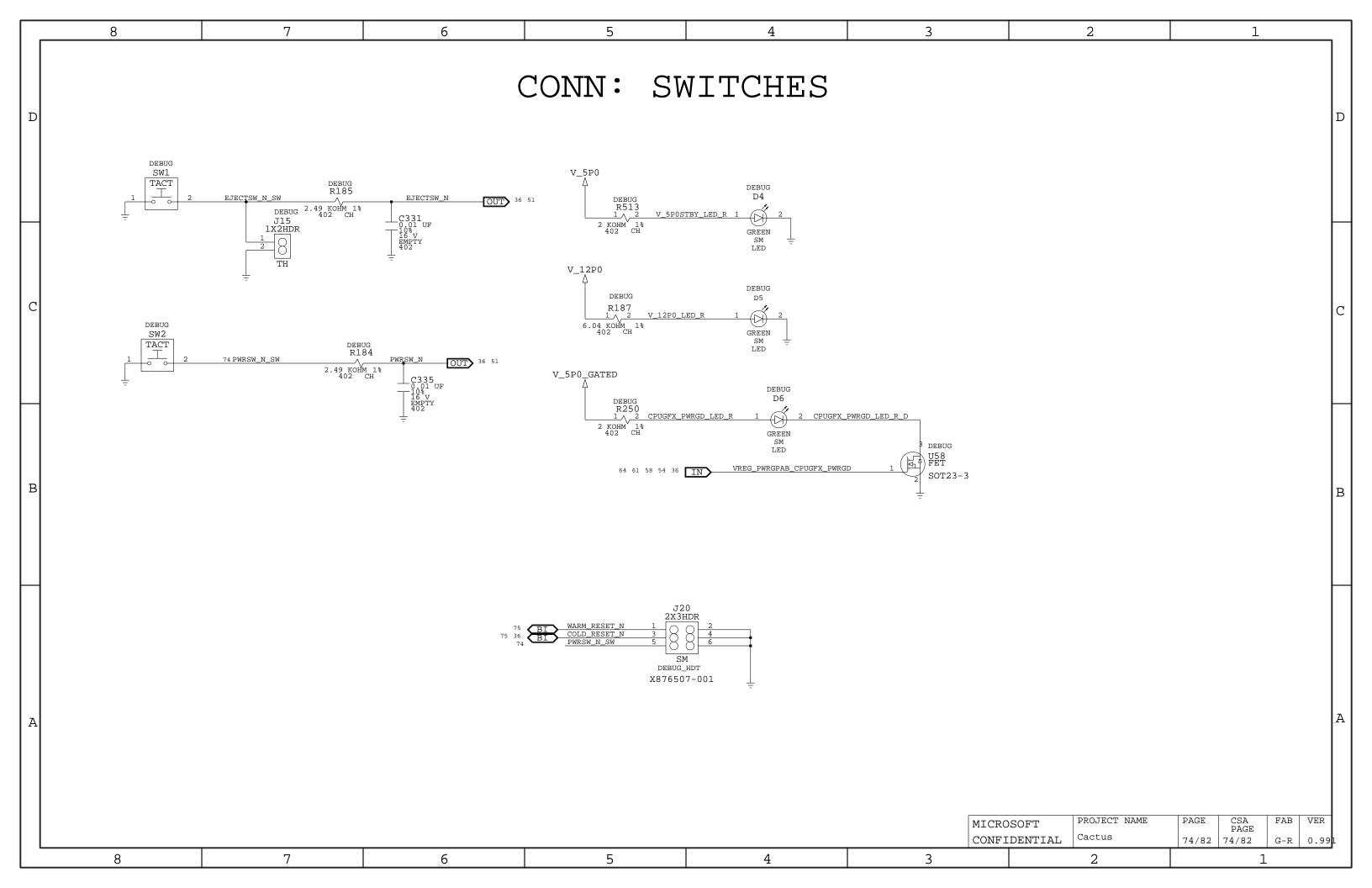


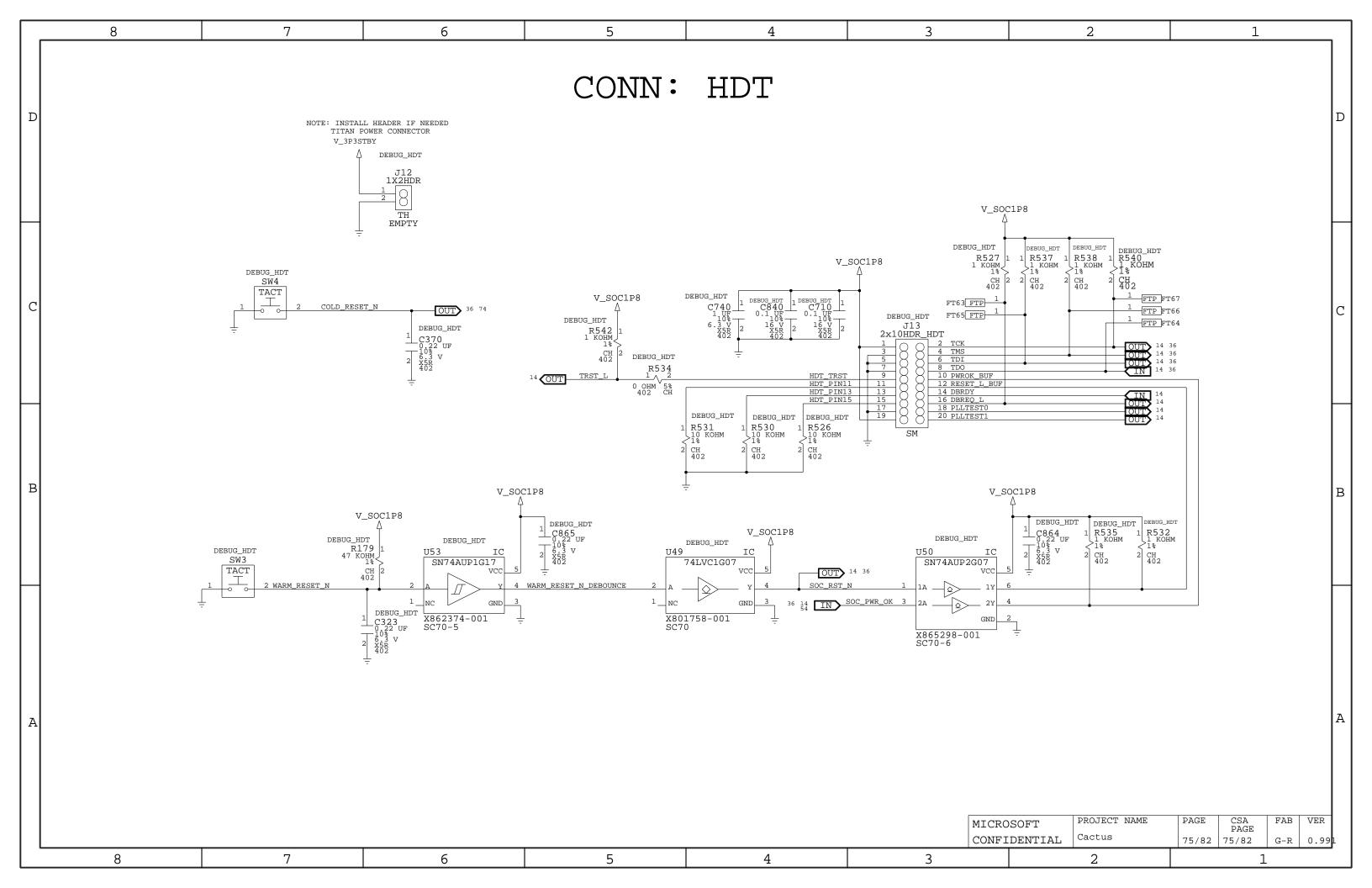


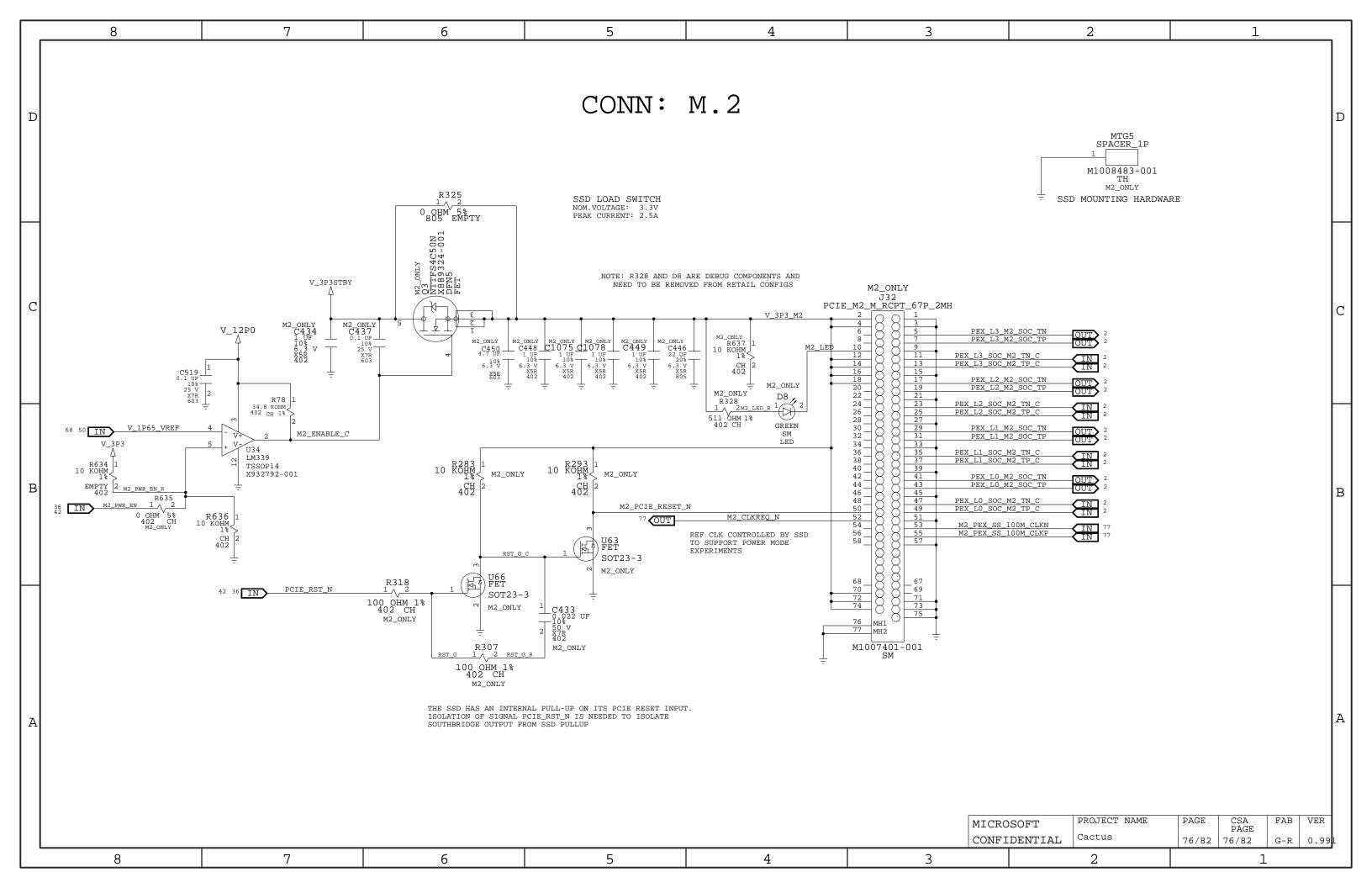


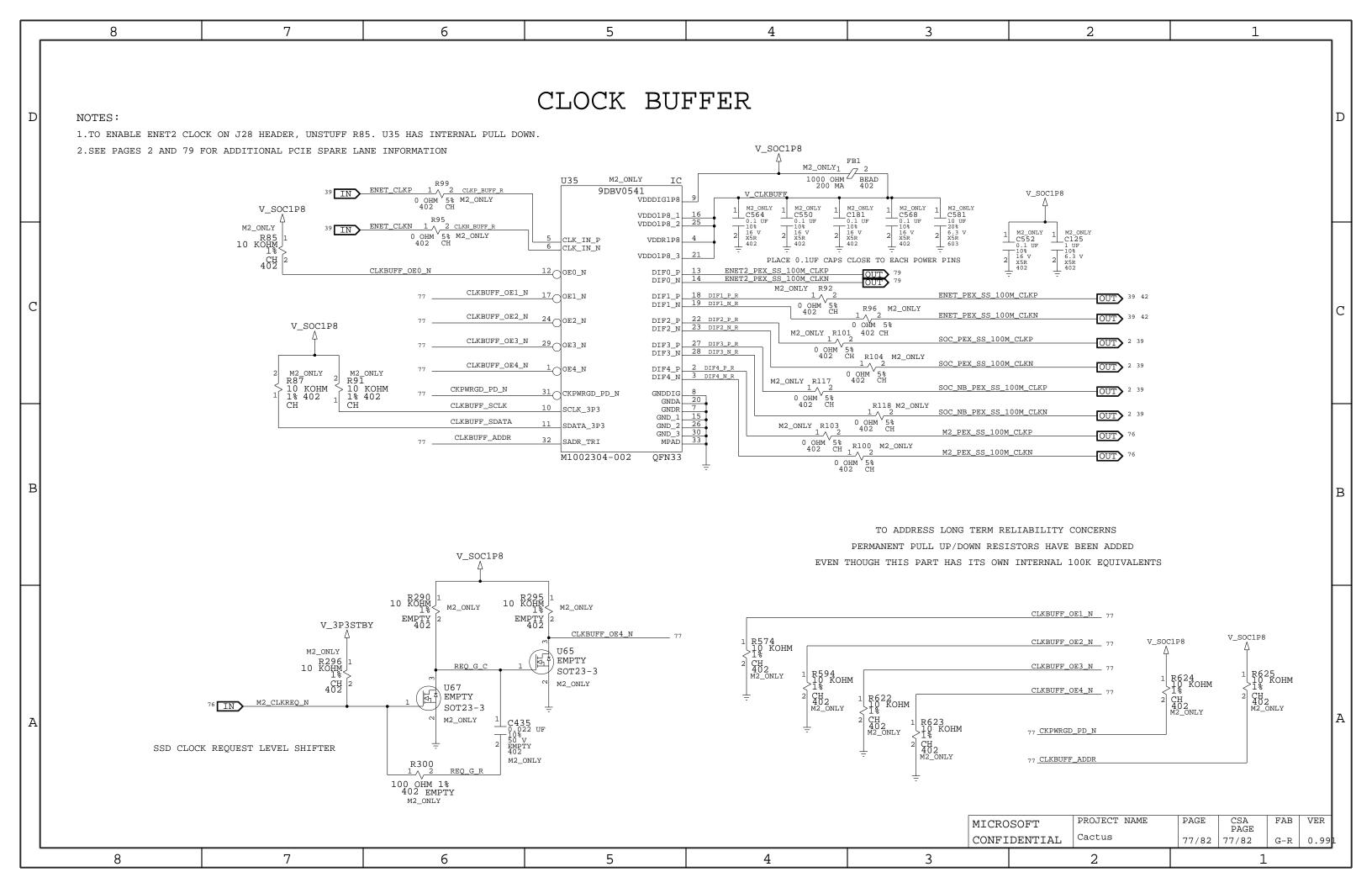


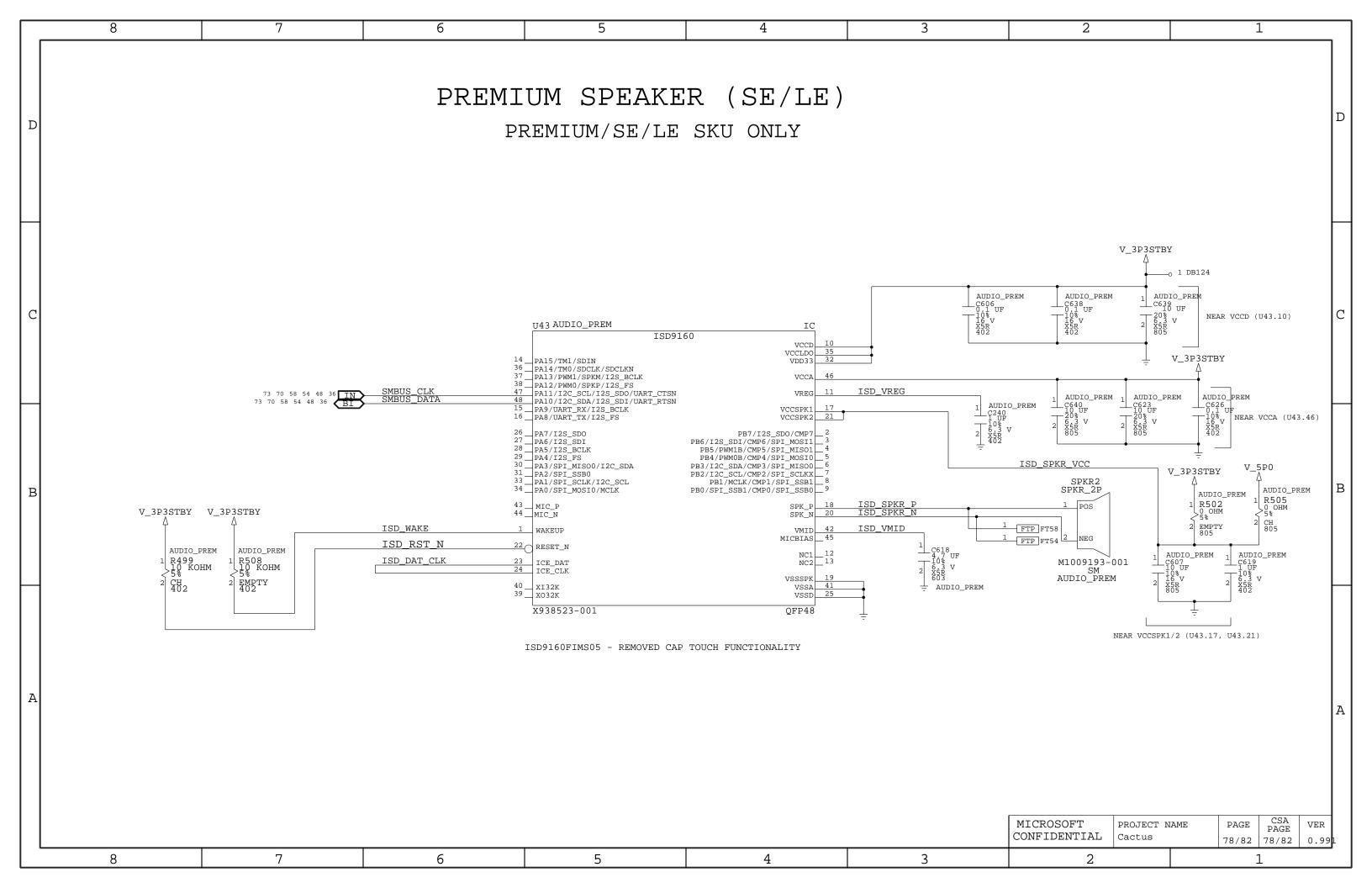


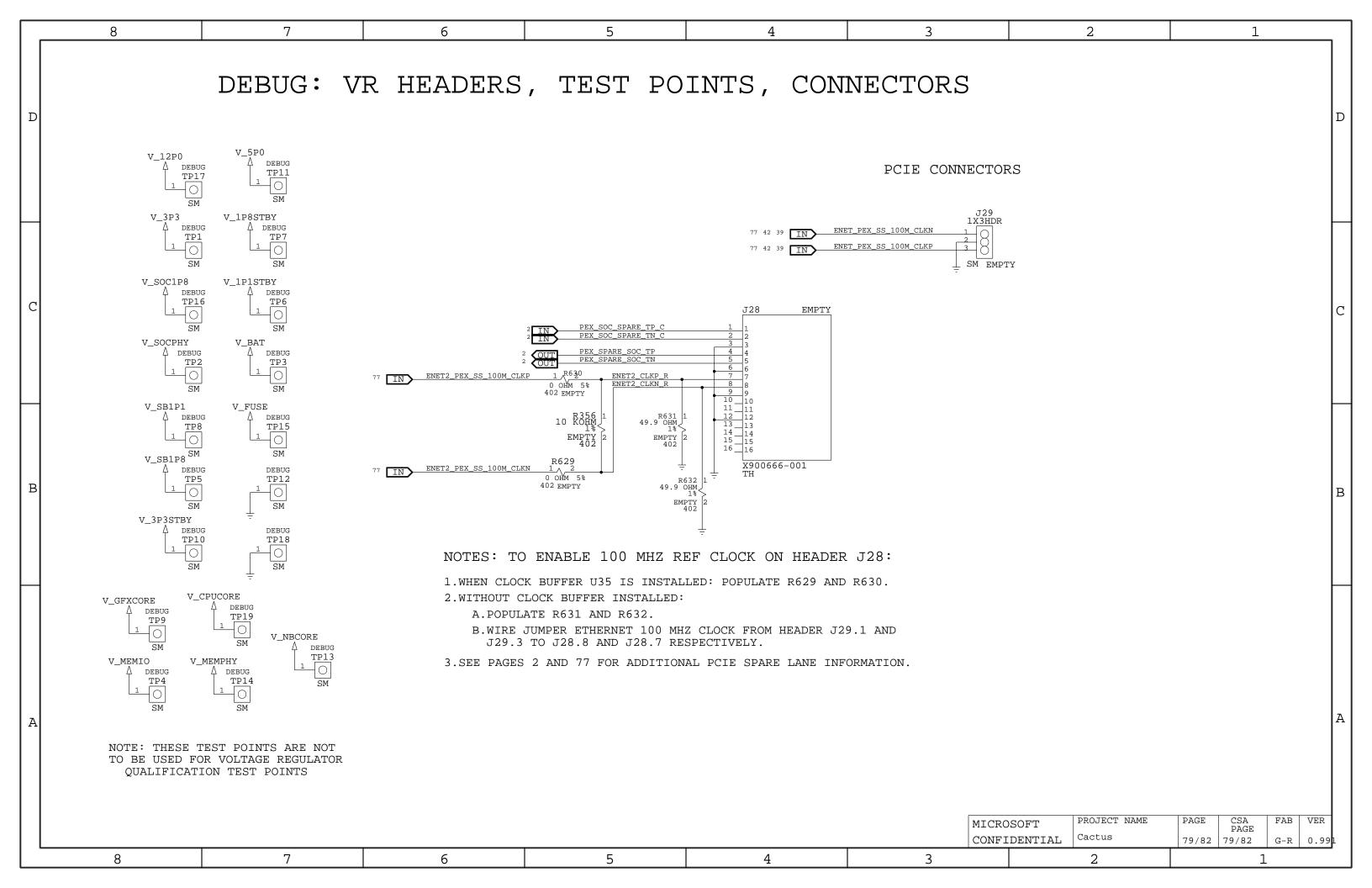


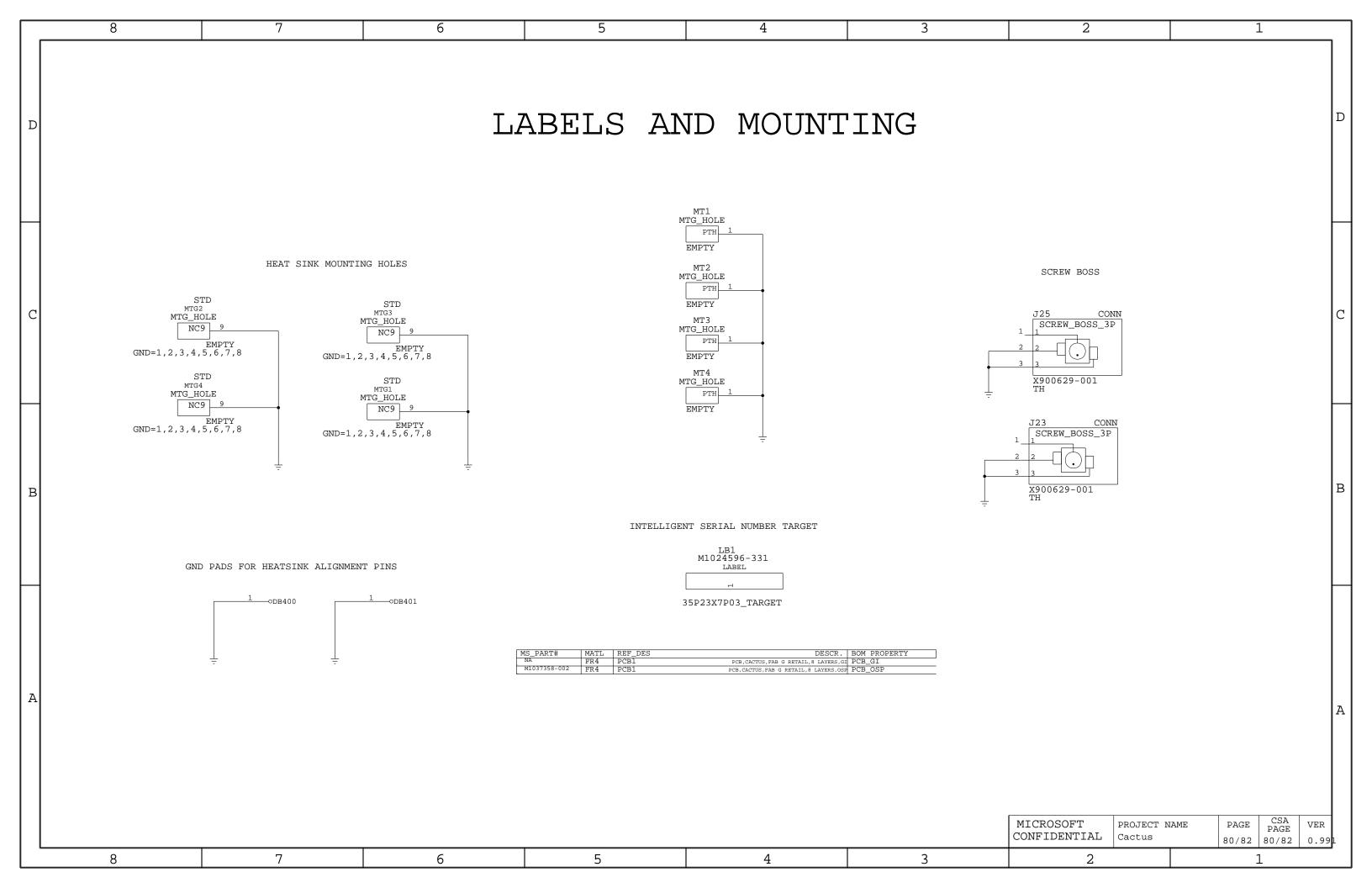


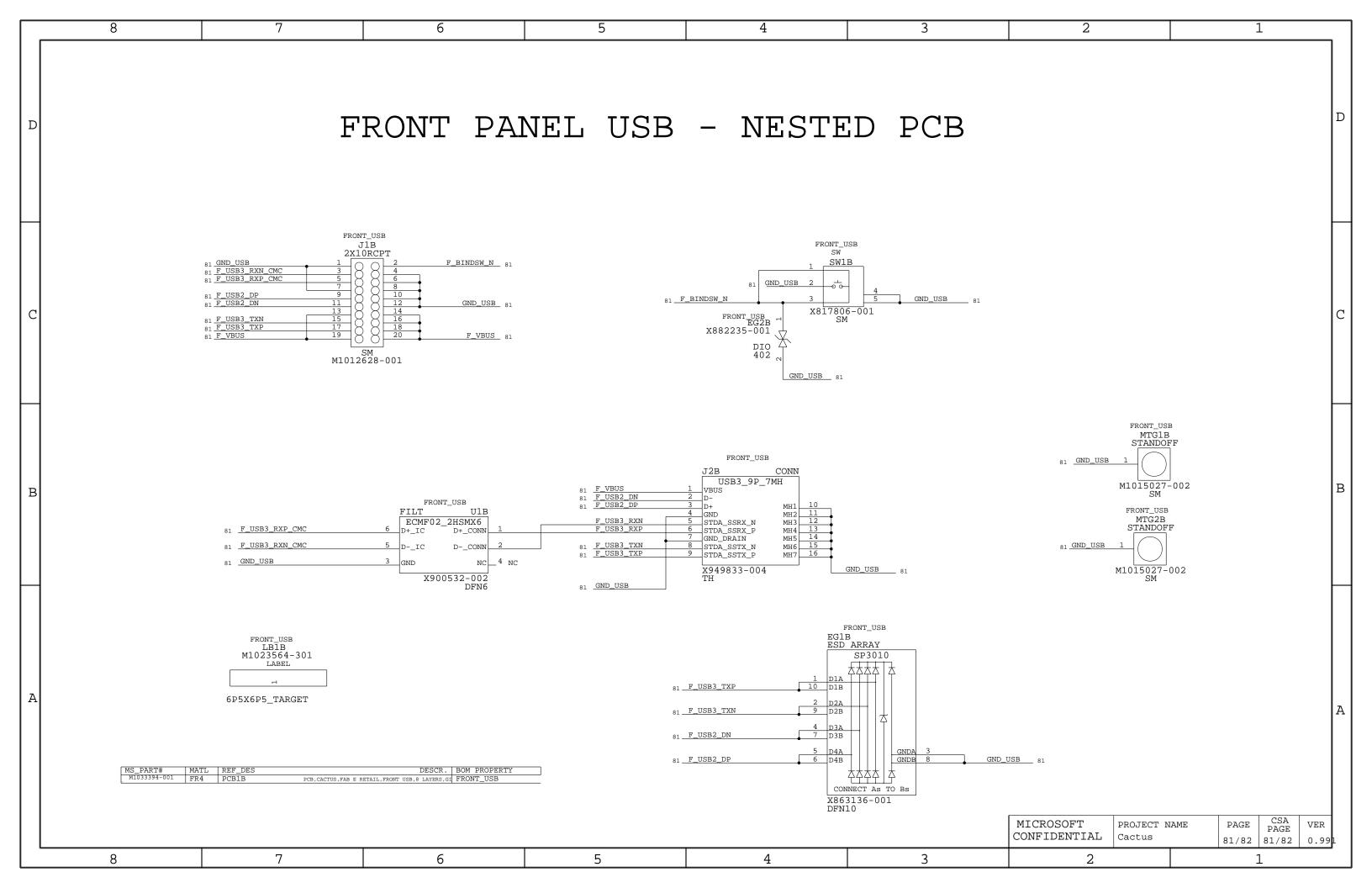












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		$D \cap M$ $D = T \times T \times T = T \cap M \cap C$							
			BOM DEFINITIONS						
D BOM DEFINTION									D
	AUDIO	INCLUDES COMPONENTS FOR THE STANDARD AUDIO SOLUTION							
	AUDIO_PREM	INCLUDES COMPONENTS FOR THE PREMIUM SE/LE SPEAKER SOLUTION							
	COMMON	ALL COMPONENTS WITH NO BOM PROPERTY							
DEBUG COMPONENTS REQUIRED FOR BRING UP & DEBUG									
DEBUG_HDT									
Н	DEBUG_SHUNT	COMPONENTS WHICH ARE ON DEBUG BOARDS, BUT ARE REMOVED/SHORTED ON RETAIL							
	EMMC_BASE	DUMMY PLACE HOLDER FOR EMMC DEVICE & RESISTORS. NEVER USE THIS IN THE RECIPE FILE. SELECT ONE OF THESE INSTEAD: EMMC_HYNIX_16NM, EMMC TOSHIBA_15NM, EMMC SAMSUNG_14NM							
	EMMC_HYNIX_16NM	HYNIX EMMC DEVICE							
	EMMC_SAMSUNG_14NM	SAMSUNG EMMC DEVICE							
	EMMC_TOSHIBA_15NM	TOSHIBA EMMC DEVICE							
	GDDR5_BASE	DUMMY PLACE HOLDER FOR GDDR5. NEVER USE THIS IN THE RECIPE FILE. SELECT ONE OF THESE INSTEAD: EMMC_HYNIX_16NM, EMMC TOSHIBA_15NM, EMMC SAMSUNG_14NM							
	GDDR5_HYNIX	HYNIX GDDR5 MEMORY C							
	GDDR5_SAMSUNG	SAMSUNG GDDR5 MEMORY							
	FRONT_USB	COMPONENTS ON THE FRONT PANEL USB							
	KIC_BASE	DUMMY PLACE HOLDER FOR KIC. NEVER USE THIS IN THE RECIPE FILE. USE ONE OF THESE INSTEAD: KIC_DEV OR KIC_RETAIL							
	KIC_DEV	DEBUG VERSION OF KRAKEN							
	KIC_RETAIL	RETAIL VERSION OF KRAKEN							
	M2_ONLY	POPULATE TO SUPPORT AN M.2 INTERFACE							
	NO_M2	POPULATE WHEN THERE IS NO M2. INTERFACE FAB TYPE: GOLD							
	PCB_GI PCB_OSP	FAB TYPE: GOLD FAB TYPE: ORGANIC SOLDERABILITY PRESERVATIVE GREEN SOLDERMASK							
	PCB_OSP_BLACK	FAB TYPE: ORGANIC SOLDERABILITY PRESERVATIVE BLACK SOLDERMASK FAB TYPE: ORGANIC SOLDERABILITY PRESERVATIVE BLACK SOLDERMASK							
B	RTC_RETAIL	RTC CIRCUIT IMPLEMENTATION FOR RETAIL BOARDS							
-	RTC_XDK	RTC CIRCUIT IMPLEMENTATION FOR XDK BOARDS							
	_SOC_BASE	DUMMY PLACE HOLDER FOR SOC. NEVER USE THIS IN THE RECIPE FILE. SELECT ONE OF THESE INSTEAD: EMMC_HYNIX_16NM, EMMC_TOSHIBA_15NM, EMMC_SAMSUNG_14NM							
	_SOC_EMPTY	DOES NOT STUFF ANUBIS							
	_SOC_INCLUDE	STUFFS ANUBIS							
	_VR_FIXED	SET ALL VRS TO FIXED VOLTAGES (NON-MARGINED). EXCLUDES V_MEMIO. MUST BE USED IN CONJUNCTION WITH NOT VR_MM							
	_VR_MM	ALLOWS MOST VRS TO BE MARGINED FOR M&M BOARDS. EXCLUDES V_MEMIO. MUST BE USED IN CONJUNCTION WITH NOT VR_FIXED							\vdash
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